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Optimization of Cooled Shields in Insulations

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ABSTRACT

A relatively simple method has been developed to optimize the location, temperature, and heat dissipation rate of each cooled shield inside an insulation layer. The method is based on the minimization of the entropy production rate which is proportional to the heat leak across the insulation. The results show that the maximum number of shields to be used in most practical applications is three. However, cooled shields are useful only at low values of the overall, cold wall to hot wall absolute temperature ratio. The performance of the insulation system is relatively insensitive to deviations from the optimum values of temperature and location of the cooling shields.

Design curves are presented for rapid estimates of the locations and temperatures of cooling shields in various types of insulations, and an equation is given for calculating the cooling loads for the shields.

NOMENCLATURE

A	Area of heat flow, m ²
C _p	Specific heat of the boiloff vapor, kJ/kg·K
D	Functional defined by Eq. (14)
F	Functional defined by Eq. (13)
h _{fg}	Latent heat of vaporization of the boiloff liquid, kJ/kg
k	Thermal conductivity, W/m-K; with subscripts, coefficients in Eq. (1)
L	Overall thickness of insulation, m*
m,n	Exponents in conductivity function, Eq. (1)
P	T _S /T _C , temperature ratio
q	Heat flow rate, W
R	T _C /T _H , overall temperature ratio
s	Dimensionless entropy production rate defined by Eq. (5)
S	Entropy production rate, W/K
t	Thickness between walls with single shield between, m*
T	Absolute temperature, K
x	Distance from cold wall, m*
x'	Distance from cold wall in a multi-shield configuration, m*
X	x/t, dimensionless distance*
X'	x'/L, dimensionless distance*
Y	Defined by Eq. (8)

Subscripts

C	Cold wall
H	Hot wall
i	i-th shield
min	Minimum
opt	Optimum
S	Shield

*For systems with single shield L = t, x = x', X = X'.

INTRODUCTION

The search for the ultimate, energy efficient insulation system has led in the past few years to a fascinating rediscovery and application of some fundamental concepts of thermodynamics: specifically, the second law and the use of entropy production rates and availability (or exergy) for design optimization purposes. The classical approach has been to minimize the heat flow between surfaces at different temperatures.

The concept of a single vapor-cooled shield in an insulation has been treated theoretically as far back as 1959 in Scott's classic textbook on cryogenics [1] and designs employing them were described not much later [2]. Paivanas, et al., obtained a patent [3] and later reported on the use of uniformly spaced multiple shields which were cooled by the boil-off from the insulated dewar [4]. Eyssa and Okasha [5] considered only radiative heat exchange between shields and minimized the total refrigeration power required. Hilal, et al., [6,7] used a similar minimization of refrigeration power as the design basis. Related works were reported by Bejan, et al., [8-11].

Recently, Bejan [12] proposed a new point of view, based on the second law of thermodynamics, which considers thermal insulations as dissipators of useful mechanical power (i.e. the availability or exergy) or, alternately, as generators of irreversibility or entropy. Thus, in this method, optimization of an insulation corresponds to minimization of either the entropy production rate or the irreversibility, or the decrease of availability. Various applications of this concept to insulation systems have been documented subsequently [13,14].

Our work grew out of an examination of Cunningham's paper [13] who utilized a numerical technique to find optimum temperatures at given locations for one and two shields for a thermal conductivity function of the form

$k_1 T^{0.6}$. Although several equations seemed to be incorrectly printed we have found two of the design curves to be essentially correct. Thus, our purpose was

1. To develop a simple optimization technique;
2. To generalize the results to a broader class of insulations; and
3. To develop simple design methods for cooled shields.

The essentials of this report were already published [15].

ANALYSIS

We accept the previously developed concept that to optimize an insulation system is equivalent to minimizing the entropy production rate. In addition, we assume one-dimensional heat flow and that the heat capacity of the boil-off gas is adequate to do the cooling for all shields and does not impose a restriction on the optimization. In contrast to Rejan [9,11] who has developed a constrained optimization based on the heat capacity of the boiloff we employ the argument that in all practical systems the boil-off is generated by cooling of some equipment in addition to the heat leakage across the insulation.

Parallel heat paths, e.g. supports, have not been considered. However, each path can be optimized separately using its own thermal conductivity function. Then a design decision has to be made whether the two structures should be independently cooled at their respective optimum conditions.

We examine the general situation of an insulation where equivalent thermal conductivity, k , can be expressed as a two-term function of the absolute temperature

$$k = k_1 T^m + k_2 T^n \quad (1)$$

where, typically, the first term represents actual conduction with $m \geq 1$ and the second term represents radiation with $n \geq 3$. In the following, m and n can be any value except -1.

The heat flow across a layer of insulation can be expressed in terms of Fourier's law

$$q dx = Ak dT \quad (2)$$

Substituting k from Eq. (1) and integrating across a layer from one end at 1, to the other at 2, yields

$$q = \frac{A}{x_2 - x_1} \left[\frac{k_1}{m+1} (T_2^{m+1} - T_1^{m+1}) + \frac{k_2}{n+1} (T_2^{n+1} - T_1^{n+1}) \right]. \quad (3)$$

Now consider the insulation with a cooled shield at T_S located at x between a hot surface at T_H and a cold one at T_C , separated by the insulation thickness, t , as shown in Fig. 1a. The entropy production rate for the insulation can be determined from the heat flows and temperatures as follows

$$\dot{S} = -\frac{q_H}{T_H} + \frac{q_C}{T_C} + \frac{q_S}{T_S} \quad (4)$$

where $q_S = q_H - q_C$.

The heat flow terms can be expressed in the form of Eq. (3) and the resulting expression can be non-dimensionalized using the following terms

$$s \equiv \frac{St}{Ak_H} \text{ where } k_H = k \text{ at } T_H, \quad (5)$$

$$P \equiv \frac{T_S}{T_C}, \quad (6)$$

$$R \equiv \frac{T_C}{T_H}, \quad (7)$$

$$\gamma \equiv \frac{k_2(m+1)}{k_1(n+1)} T_H^{n-m}, \quad (8)$$

and

$$X \equiv \frac{x}{t}. \quad (9)$$

The resulting equation is

$$\begin{aligned}
 & s(m+1)(1 + \gamma \frac{n+1}{m+1}) \\
 & = \frac{1}{1-X} \{[(PR)^m + 1 - (PR)^m - 1 + (PR)^{-1}] \\
 & + \gamma[(PR)^{n+1} - (PR)^n - 1 + (PR)^{-1}]\} \\
 & + \frac{1}{X} \{R^m[P^{m+1} - P^m - 1 + P^{-1}] \\
 & + \gamma R^n[P^{n+1} - P^n - 1 + P^{-1}]\} \tag{10}
 \end{aligned}$$

Since R , the overall temperature ratio, is generally known, s is a function of P and X , and its extreme value can be found by differentiating it with respect to each variable separately and setting the results equal to zero. This procedure yields two equations to be solved simultaneously: $\partial s / \partial P = 0$ and $\partial s / \partial X = 0$. Because of the regular form of the expressions, one of the final two equations contains only a single unknown as follows:

$$\begin{aligned}
 & \frac{R^m F(m,P) + \gamma R^n F(n,P)}{[R^{m-1} D(m,P) + \gamma R^{n-1} D(n,P)]^2} \\
 & = \frac{F(m,PR) + \gamma F(n,PR)}{[D(m,PR) + \gamma D(n,PR)]^2} \tag{11}
 \end{aligned}$$

$$\frac{X}{1-X} = - \frac{R^{m-1} D(m,P) + \gamma R^{n-1} D(n,P)}{D(m,PR) + \gamma D(n,PR)} \tag{12}$$

where the following functionals were used:

$$F(b, B) \equiv R^{b+1} - B^b - 1 + B^{-1} \quad (13)$$

$$D(b, B) \equiv (b + 1) B^b - bB^{b-1} - B^{-2}. \quad (14)$$

Thus, to find the optimum temperature and location for a shield, Eq. (11) can be solved for P , and then X can be calculated from Eq. (12). The heat to be removed by the shield, $q_S = q_H - q_C$, can be found, as before, from Eq. (3). In dimensionless form the equation becomes

$$\begin{aligned} & \frac{q_S t}{A k_H T_H} (m+1) \left(1 + \gamma \frac{n+1}{m+1}\right) \\ &= \frac{1 - (PR)^{m+1} + \gamma [1 - (PR)^{n+1}]}{1 - X} \\ & - \frac{(PR)^{m+1} - R^{m+1} + \gamma [(PR)^{n+1} - R^{n+1}]}{X}. \end{aligned} \quad (15)$$

For multiple shields t_i represents the distance between the two surfaces surrounding the i -th shield on either side, $T_{H,i}$ and $T_{C,i}$ are the temperatures of these two surfaces, $X_i = x_i/t_i$ is the location of the shield relative to t_i , and x'_i is the location of the shield relative to the cold wall as shown in Fig. 1b. To determine the optimum temperatures and locations for multiple shields, first we assumed a temperature for the first shield next to the cold wall, then we used Eqs. (11) and (12) to find the temperature and location of the second shield. This process was repeated for the rest of the shields and the hot wall. Thus, each shield was optimized consecutively with respect to the two surfaces on either side. With given values of the overall temperature ratio, R , and of the number of shields, the process requires iterative solution.

To put the results into proper perspective, the entropy production rates can be compared to the thermodynamically minimum rate obtainable through spatially continuous cooling. According to Bejan [12], this rate is

$$\dot{S}_{min} = \frac{A}{t} \left[\int_{T_C}^{T_H} (\kappa)^{1/2} T^{-1} dT \right]^2. \quad (16)$$

This expression was evaluated analytically for the single-term functions of κ , i.e. for $\gamma = 0$, and numerically otherwise.

RESULTS AND DISCUSSION

The first set of curves, Figs 2 through 9, show the relative entropy production rates for various thermal conductivity functions and for up to four optimally cooled shields as functions of the overall temperature ratio $R \equiv T_C/T_H$. The curves show that the entropy production rate increases with decreasing values of the temperature ratio, R, and with increasing values of the exponent, m and n. Adding shields, of course, reduces the entropy production rate; but for most of the practical temperature range, say $0.01 < R < 0.4$, only three shields contribute to significant decreases and adding a fourth shield can be considered unnecessary. No shields are useful at high values of R; but this "high" range is strongly dependent on the exponent of the temperature. The curves developed with $k = k_1 T^{0.6}$ for one and two shields were very close to those given by Cunningham [13], converted appropriately.

Study of the results of two-term conductivities reveals that the curves fall between those obtained for each of the two terms alone. If γ is small the first term, T^m , dominates; whereas if γ is large (>10), the second term, T^n , controls. Thus, general conclusions can be drawn from examining the results of the single-term conductivities.

The second set of curves, Figs. 10 through 31, show the optimum temperature ratios, T_S/T_H , and optimum locations, x'/L , of cooled shields as functions of the overall temperature ratio, T_C/T_H , for various thermal conductivity functions and with different number of cooled shields.

Figures 10 and 11 show the optimum single shield temperature ratios, $PR = T_S/T_H$, and locations, $X = x/L$, for five conductivity functions. Both of these functions generally decrease with decreasing R. The other figures in this set show shield temperatures and locations for systems with up to three

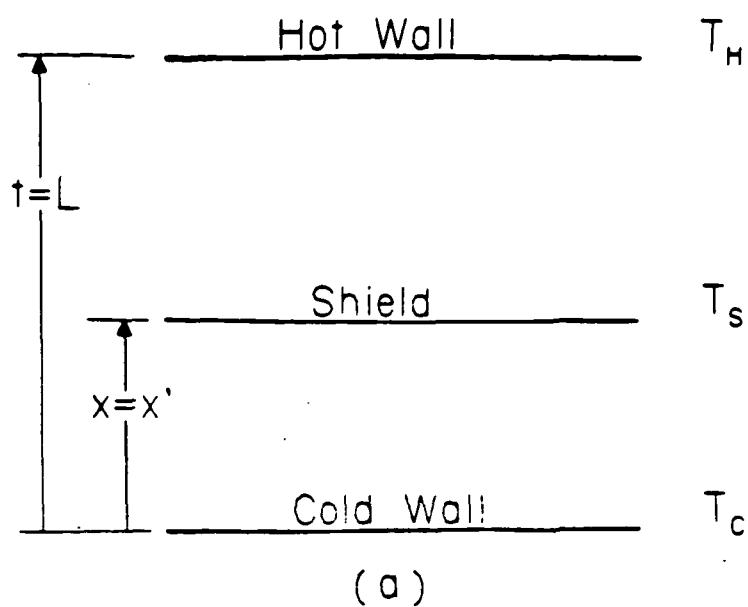
shields and for both single-term and two-term conductivities. The results are strongly non-linear. For example, for $k_1 T^3$ and $R = 0.01$, the optimum temperature ratios for three shields are about 0.09, 0.3, and 0.6 and the optimum locations are about 0.05, 0.2, and 0.5. As is to be expected, our unconstrained optimization yields a somewhat better performance per shield than Bejan's [9,11] constrained method.

The sensitivities of the entropy production rates to deviations from the optimum values of PR and X are demonstrated in the last set of curves, Figs. 32 through 35, for single shields. The sensitivity increases with the value of the exponents, m and n, but the curves are relatively flat near the minima. A ± 20 percent change from optimum, for example, has negligible effect. Thus, the system is relatively tolerant of deviations from the optimum design conditions.

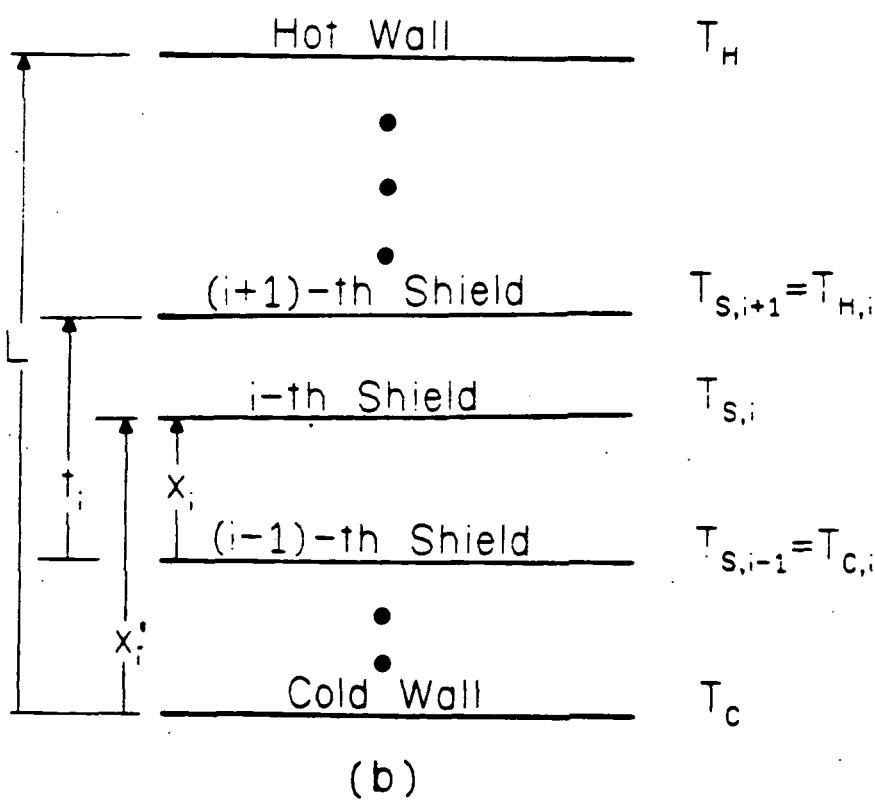
Calculations with two different conductivities on the two sides of a cooled shield show that using the better insulator on both sides always yields the optimum condition. However, if for some reason two types of insulations have to be used, then the better insulator should be placed on the warm side of the shield.

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(a)



(b)

Figure 1 Schematic of the Nomenclature for (a) Single and (b) Multiple Shields

Curve Set 1: Figures 2 through 9

The effect of optimally cooled shields on
the entropy production rate for various thermal conductivities.

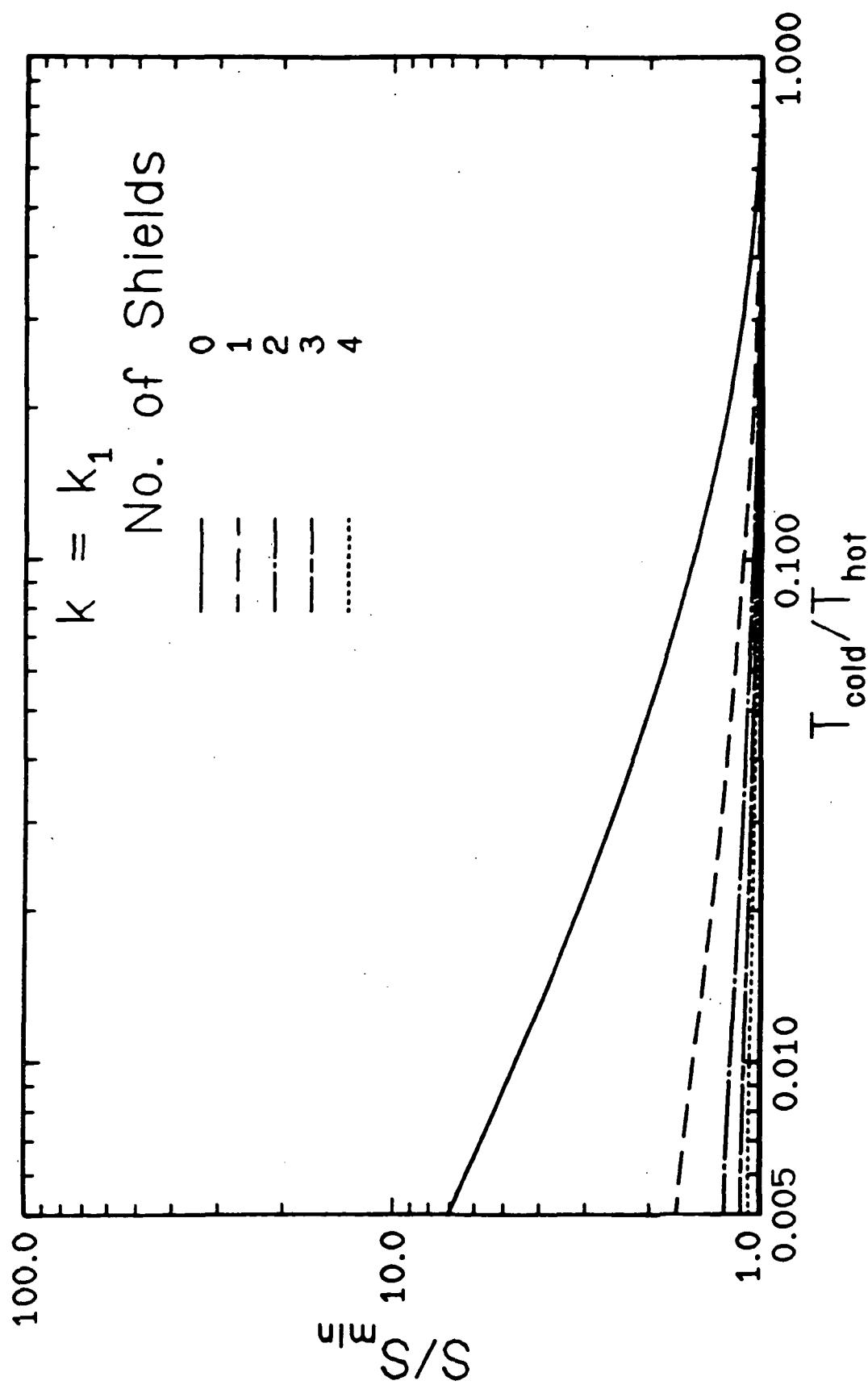


Figure 2

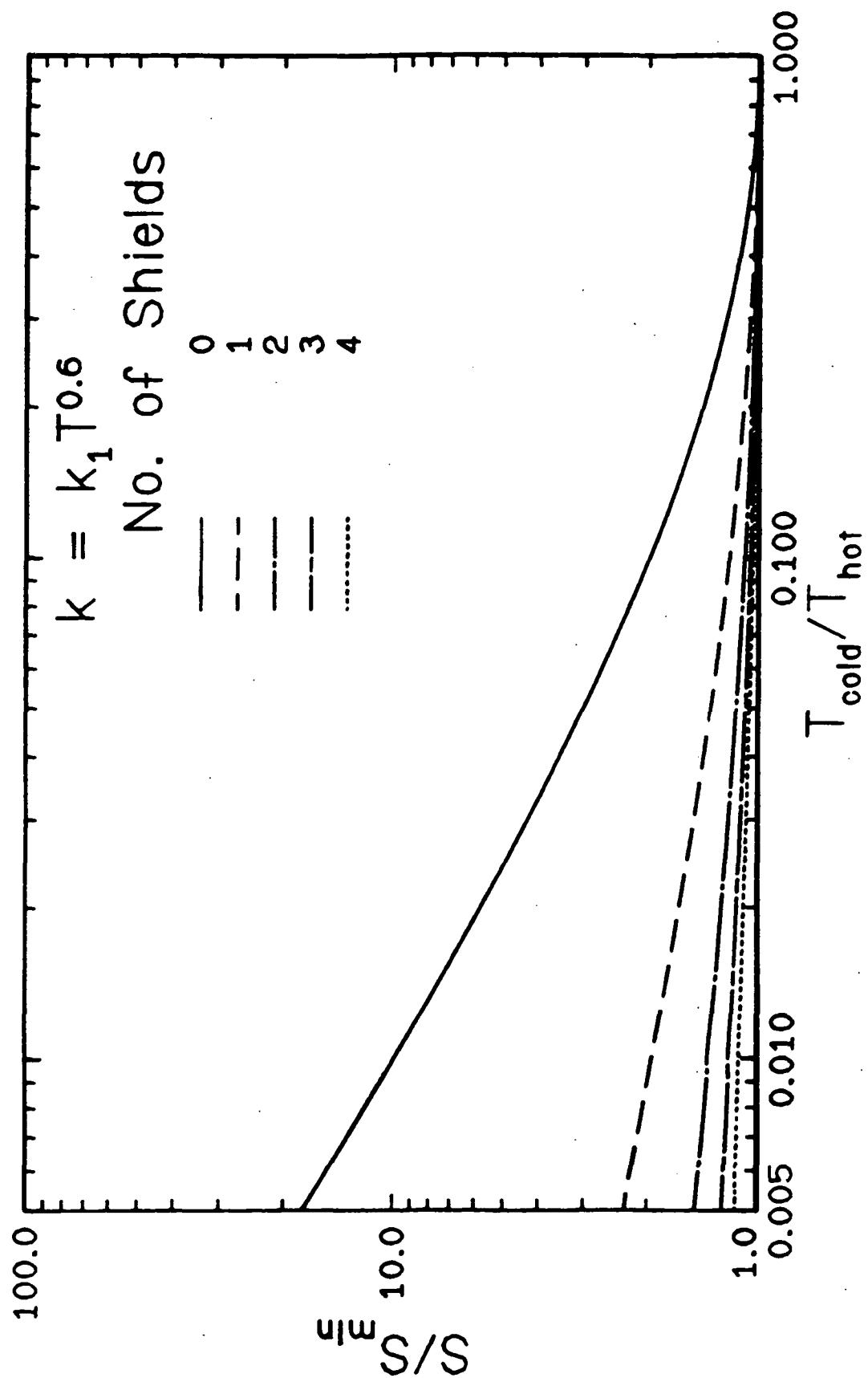


Figure 3

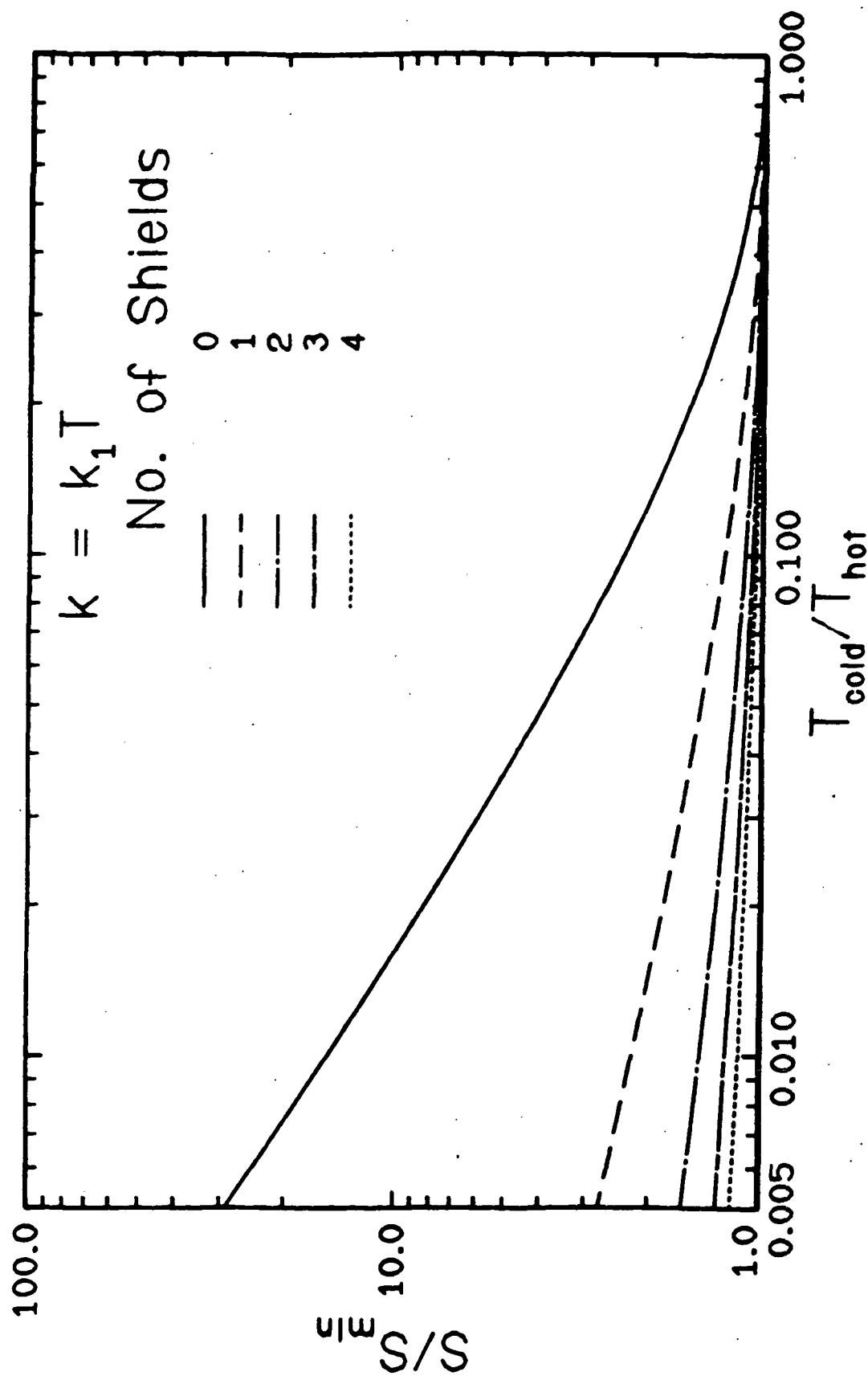


Figure 4

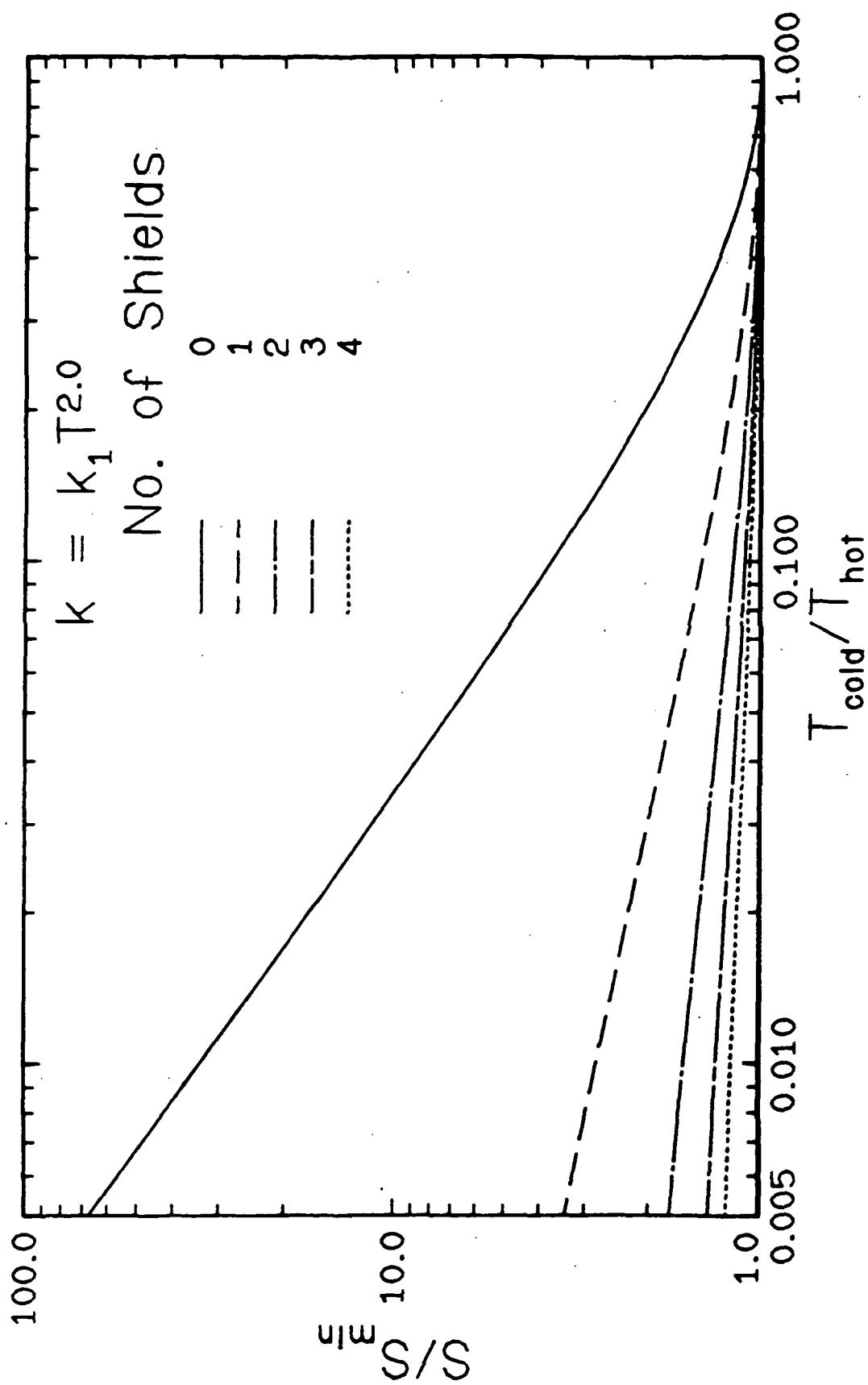


Figure 5

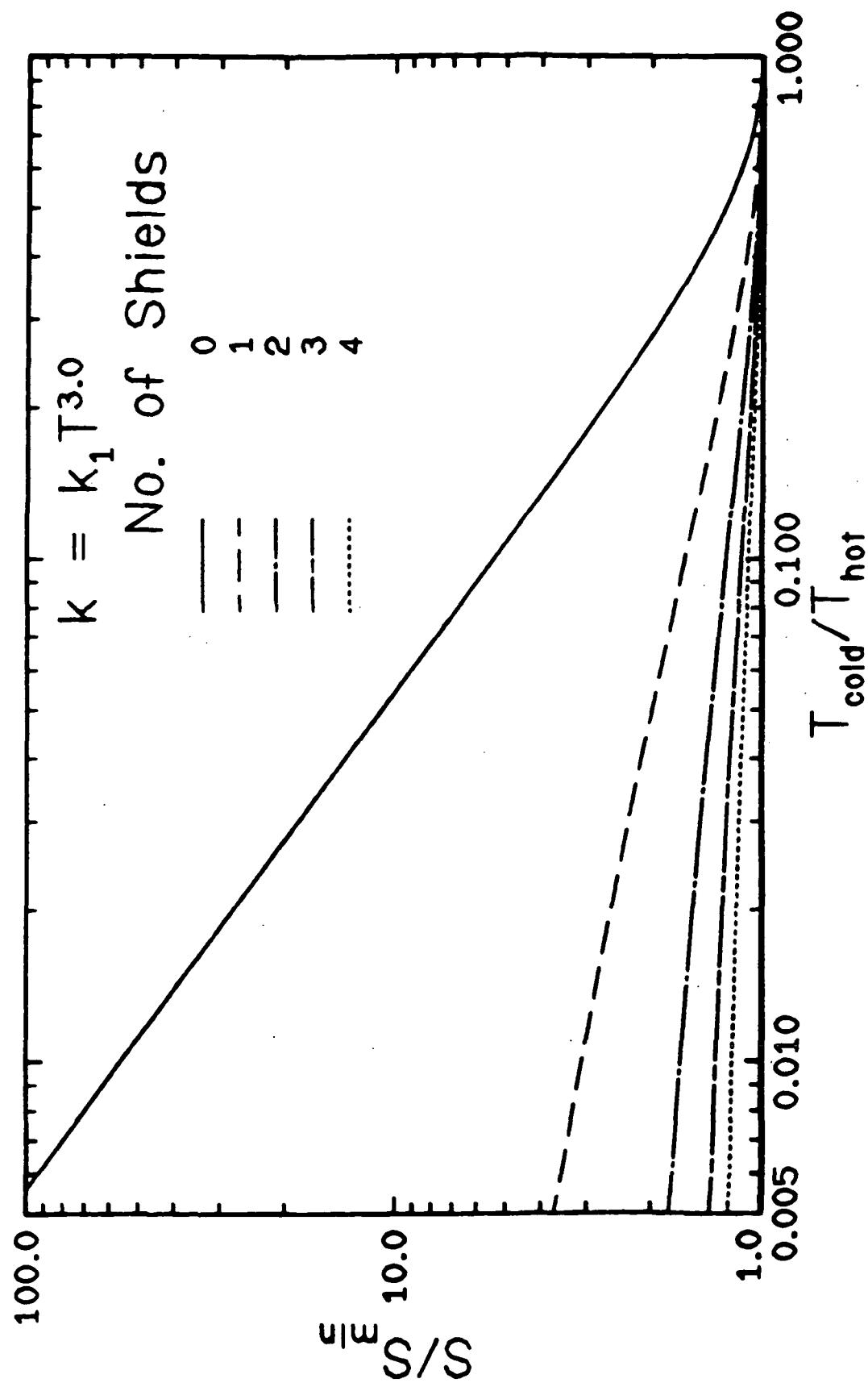


Figure 6

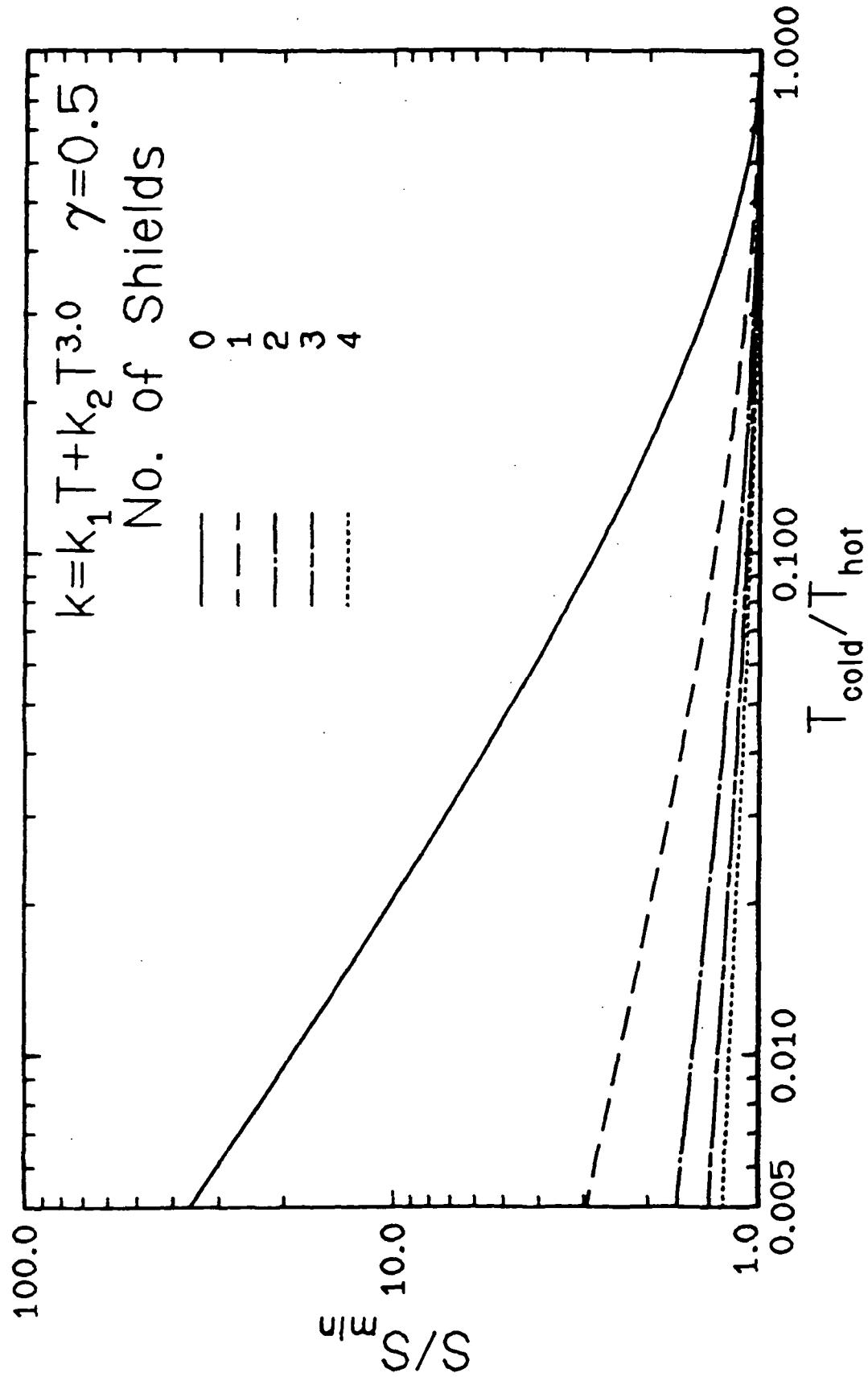


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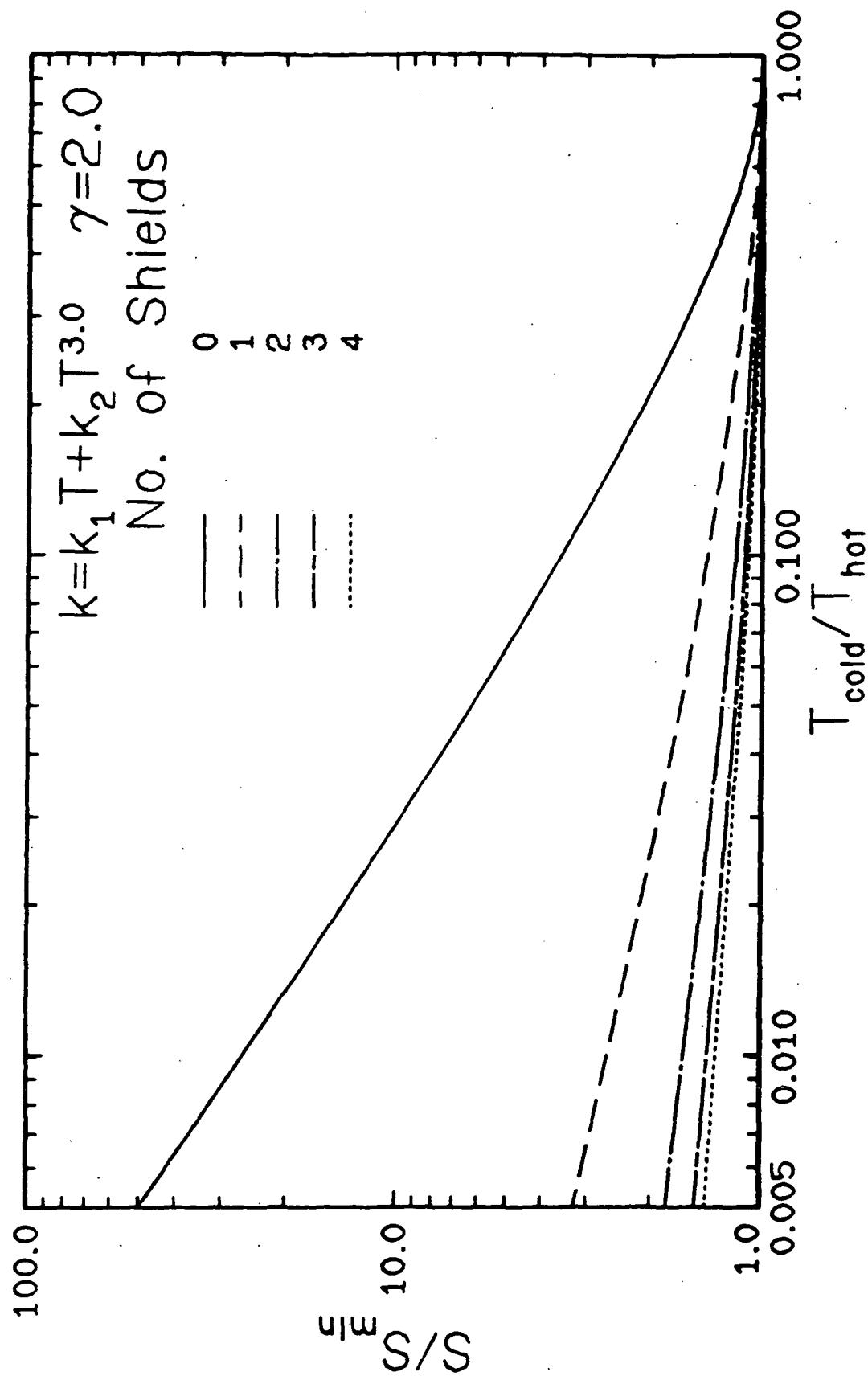


Figure 8

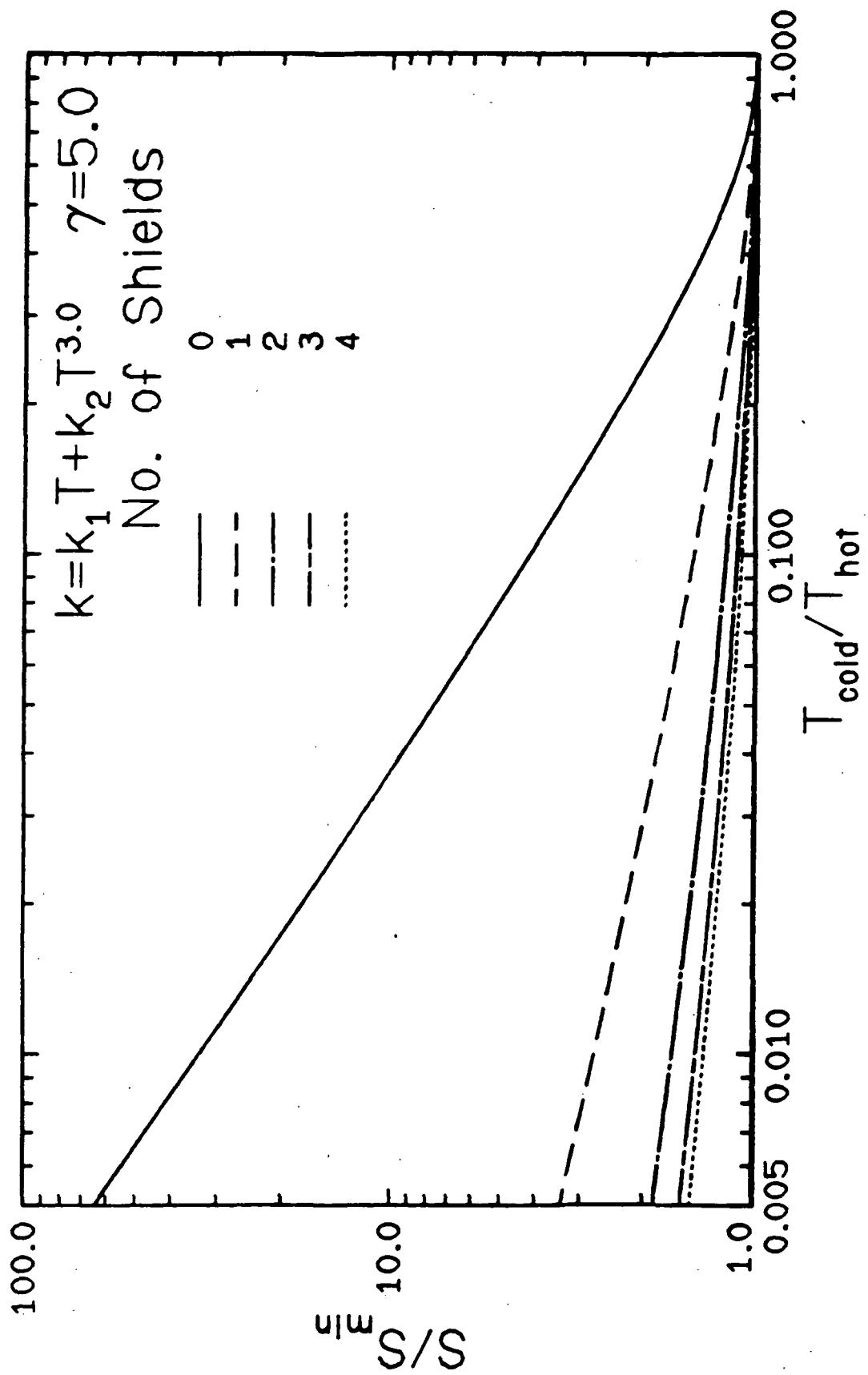


Figure 9

Curve Set 2: Figures 10 through 31

Optimal shield temperatures and locations for various thermal conductivity functions with different number of shields.

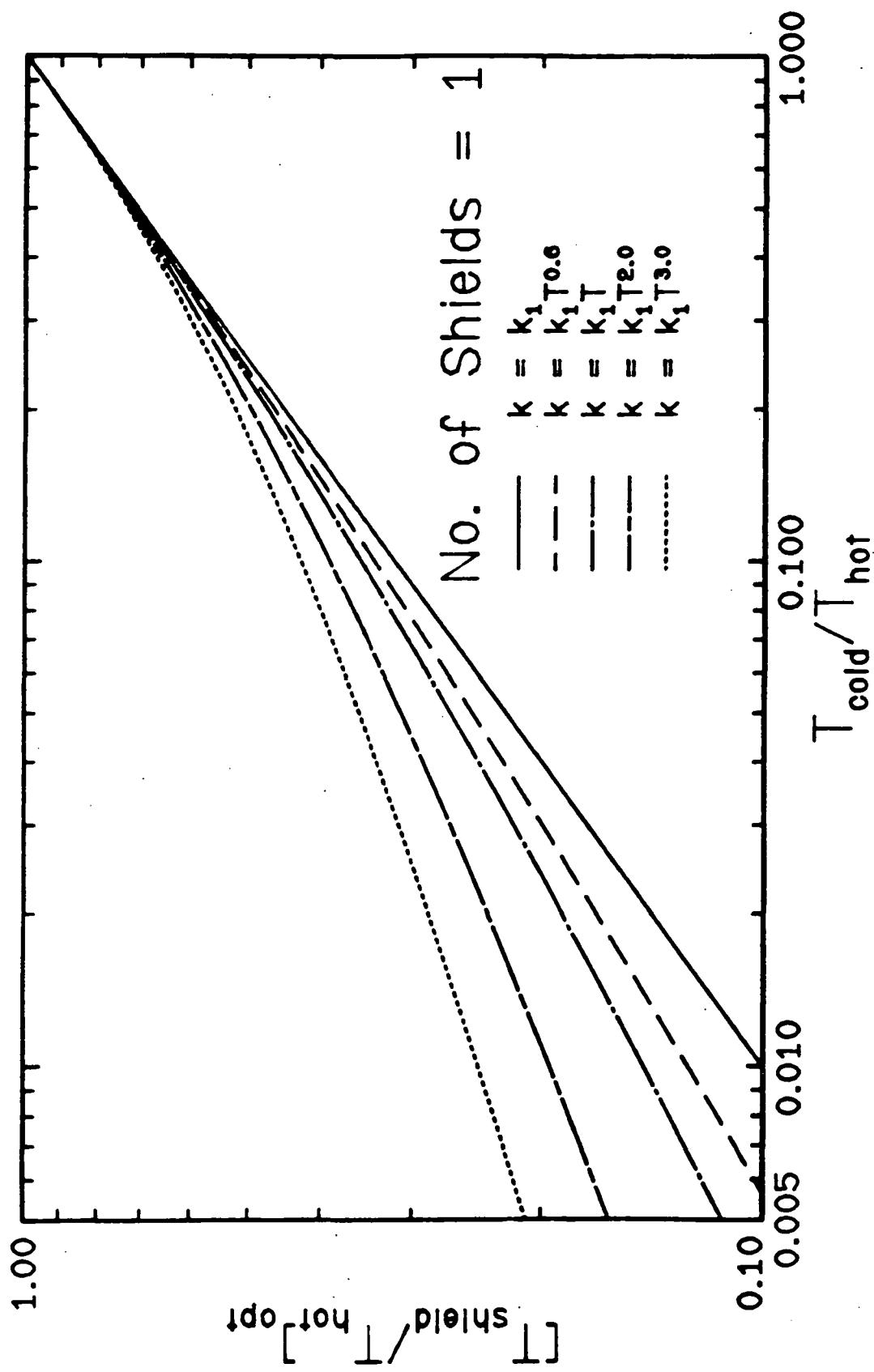


Figure 10

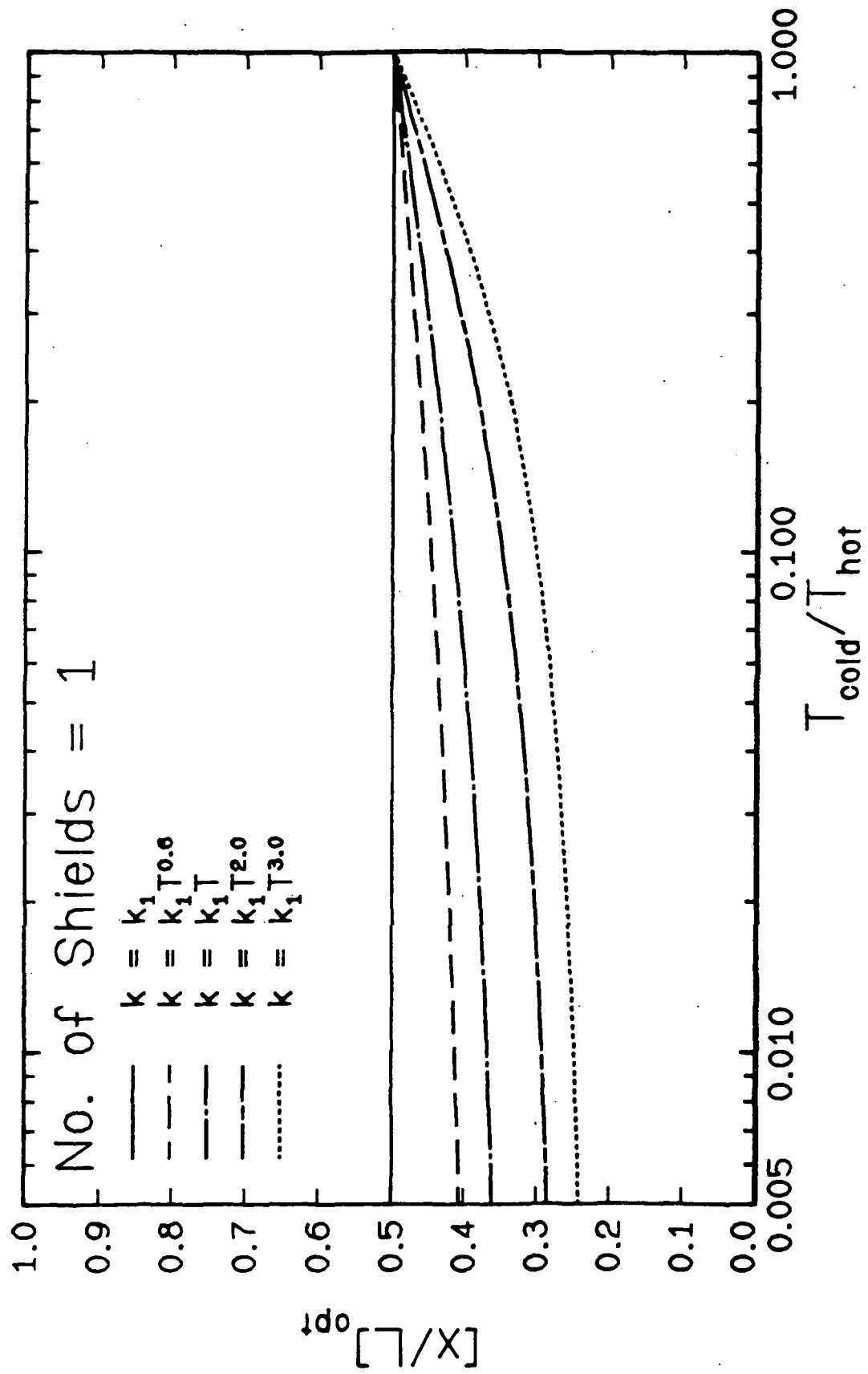


Figure 11

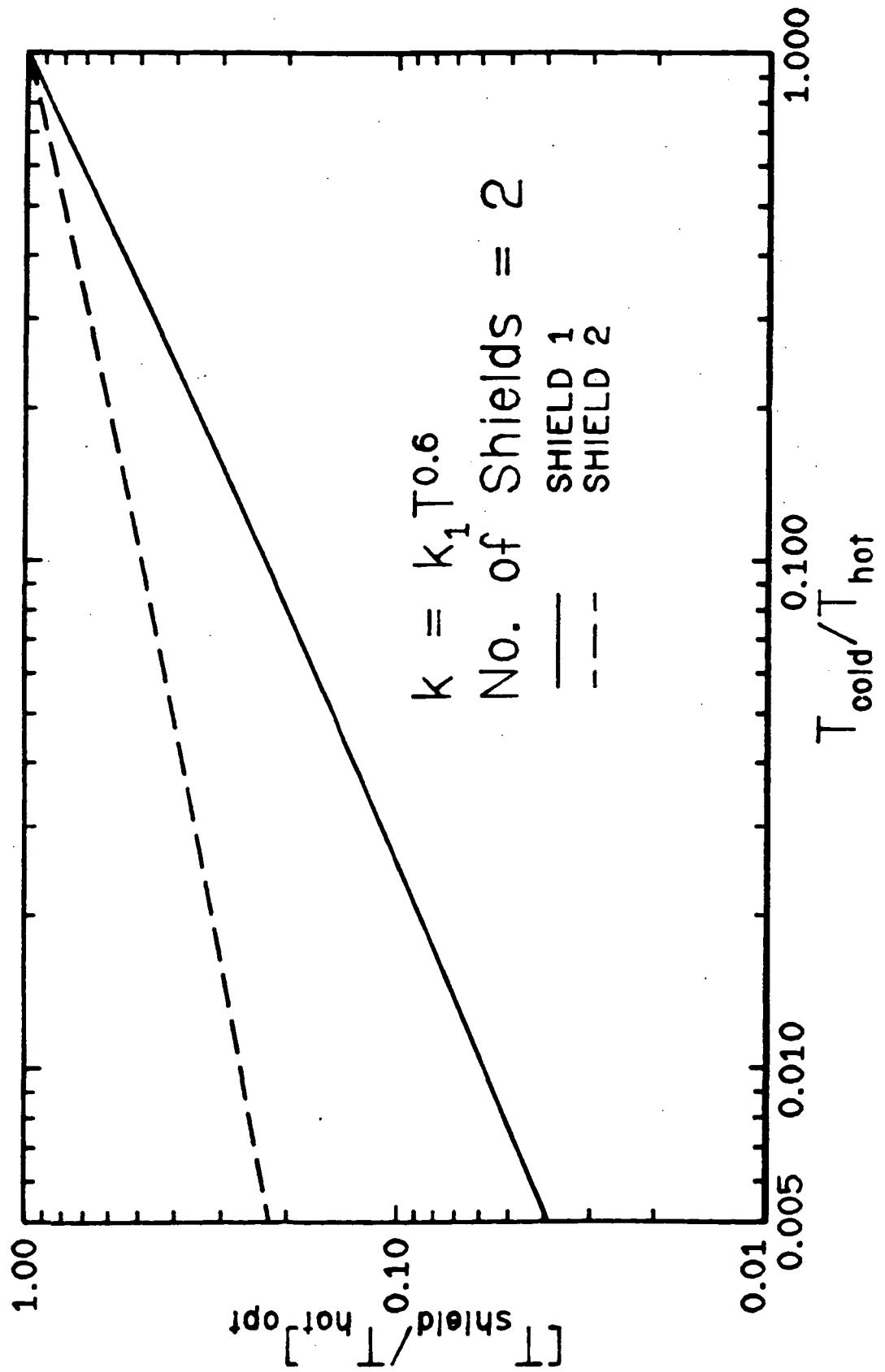


Figure 12

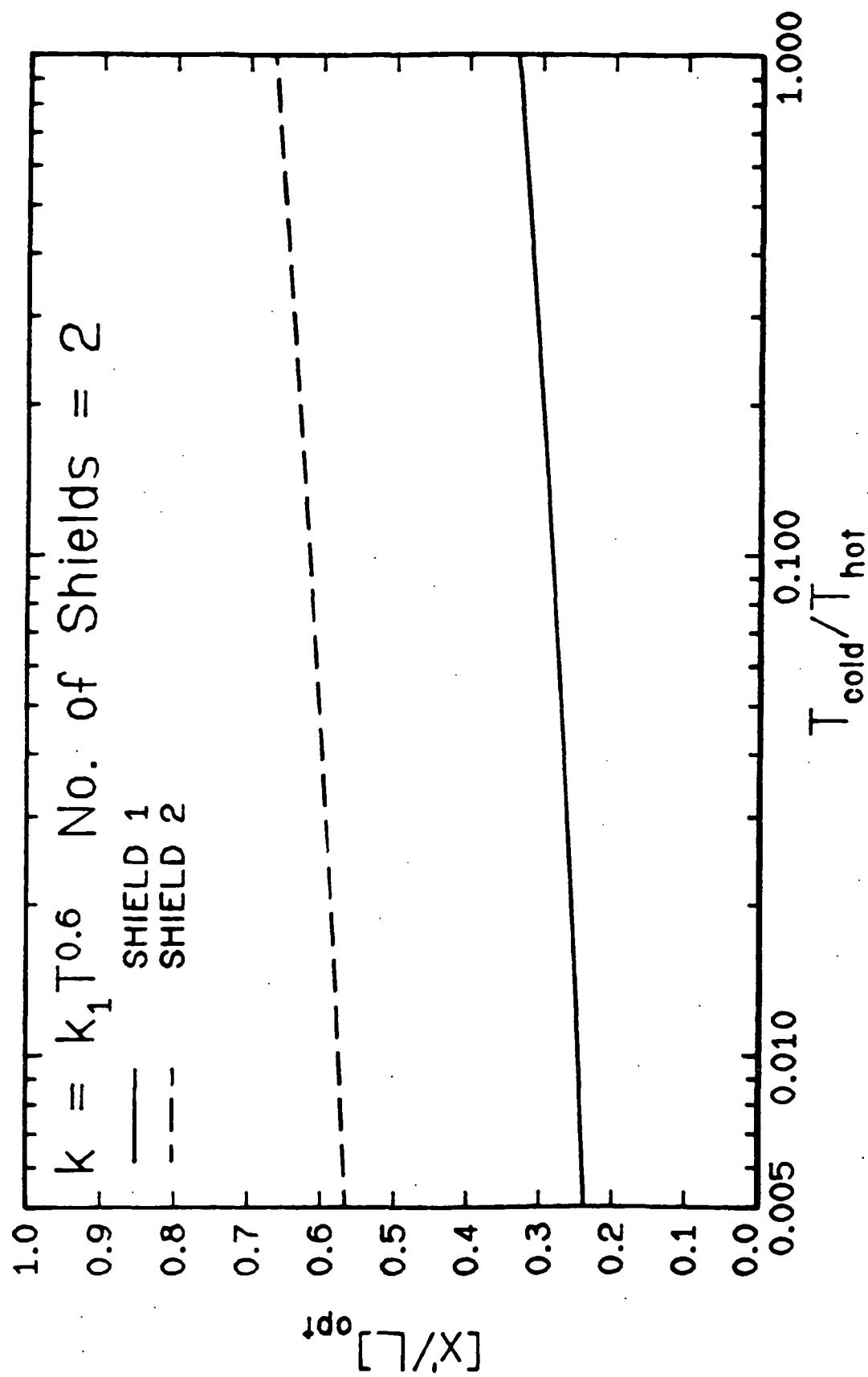


Figure 13

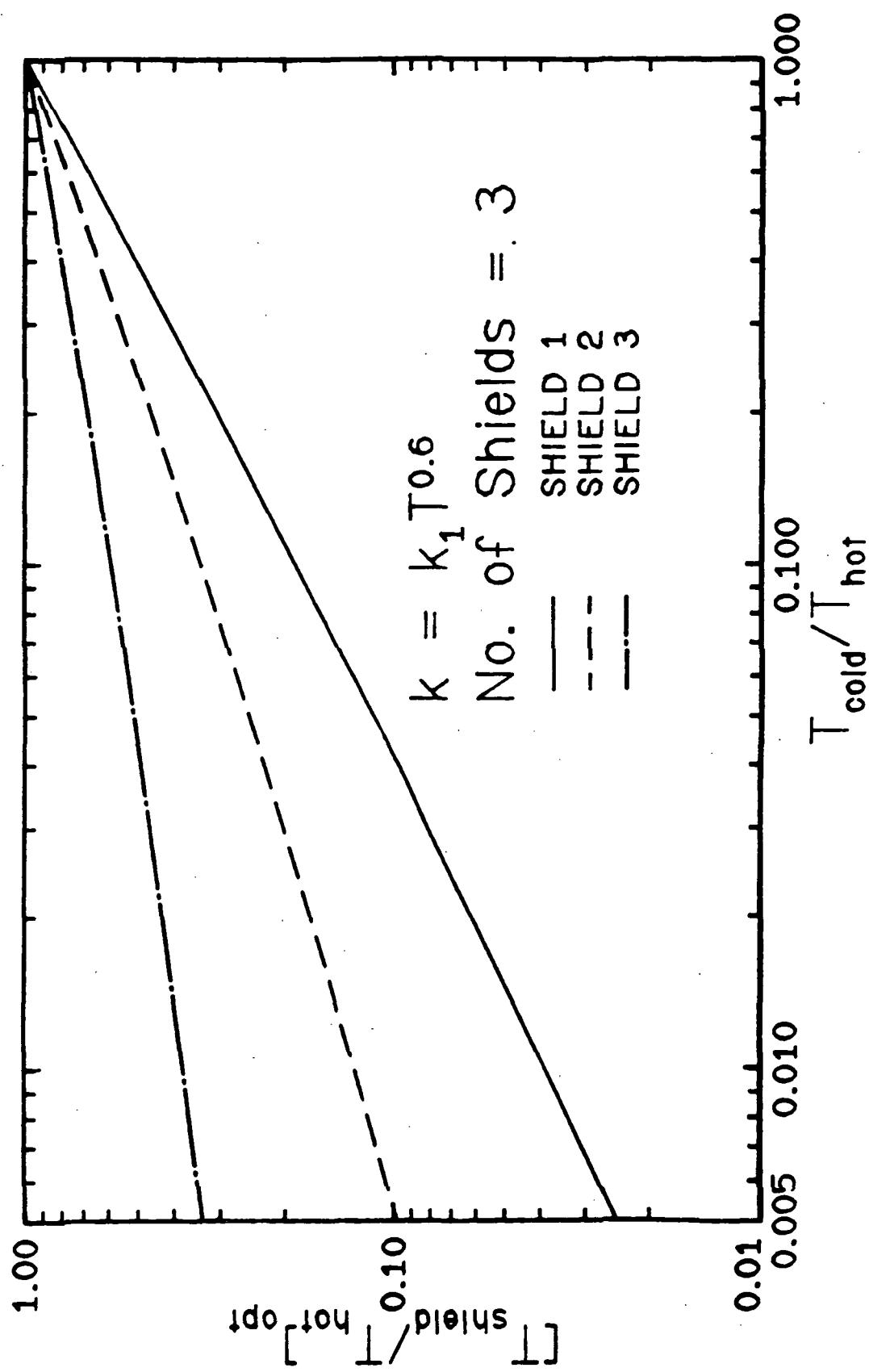


Figure 14

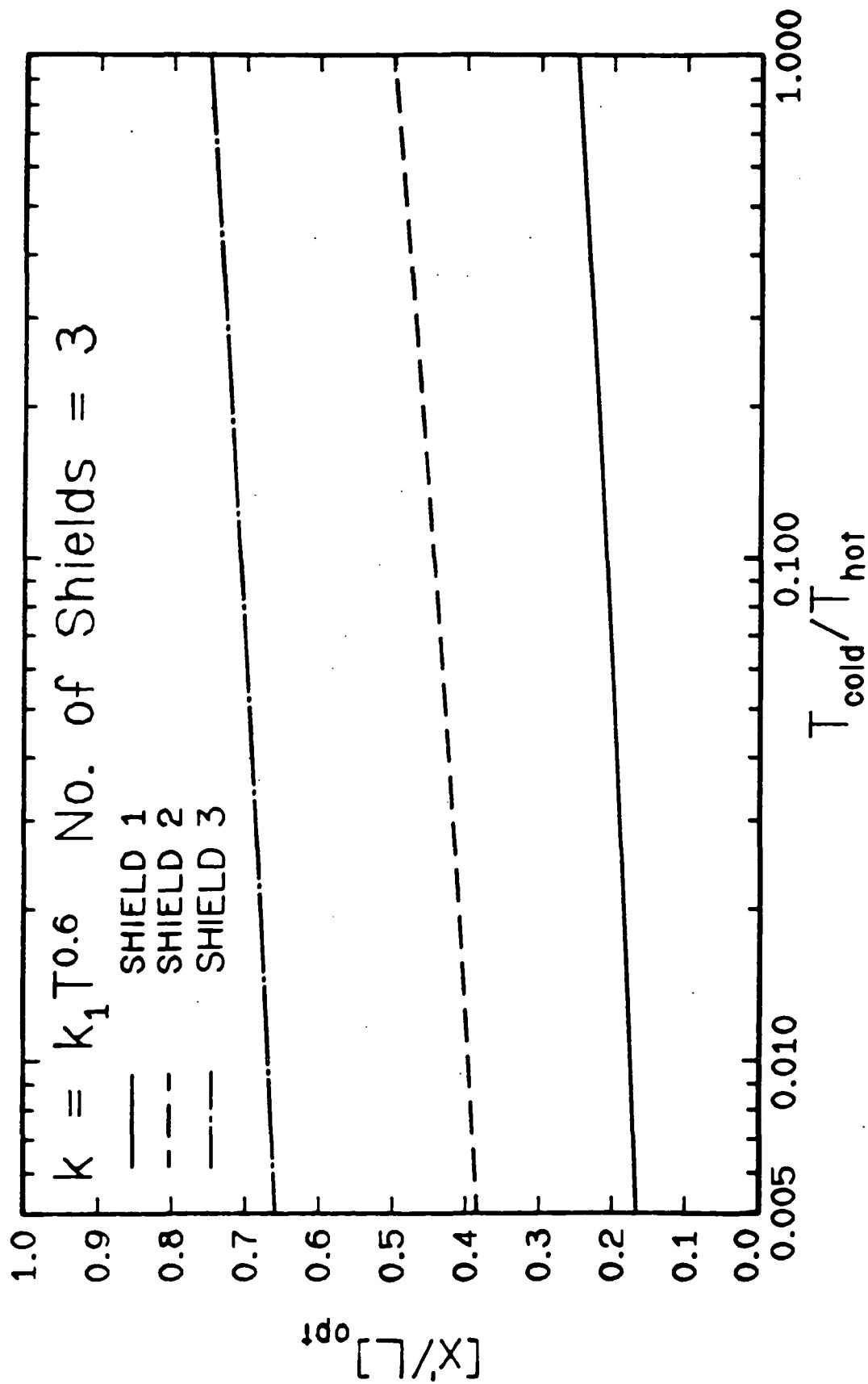


Figure 15

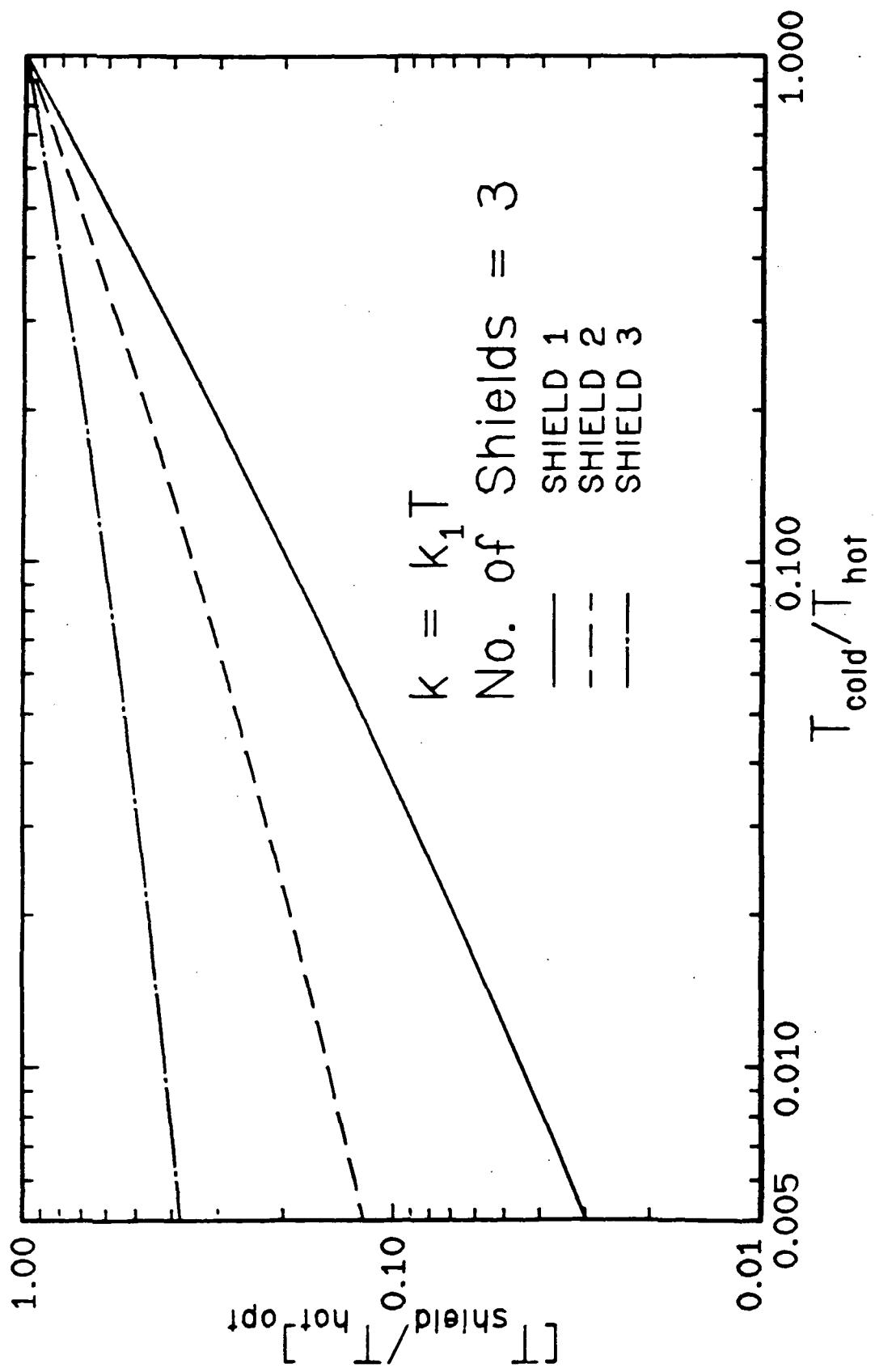


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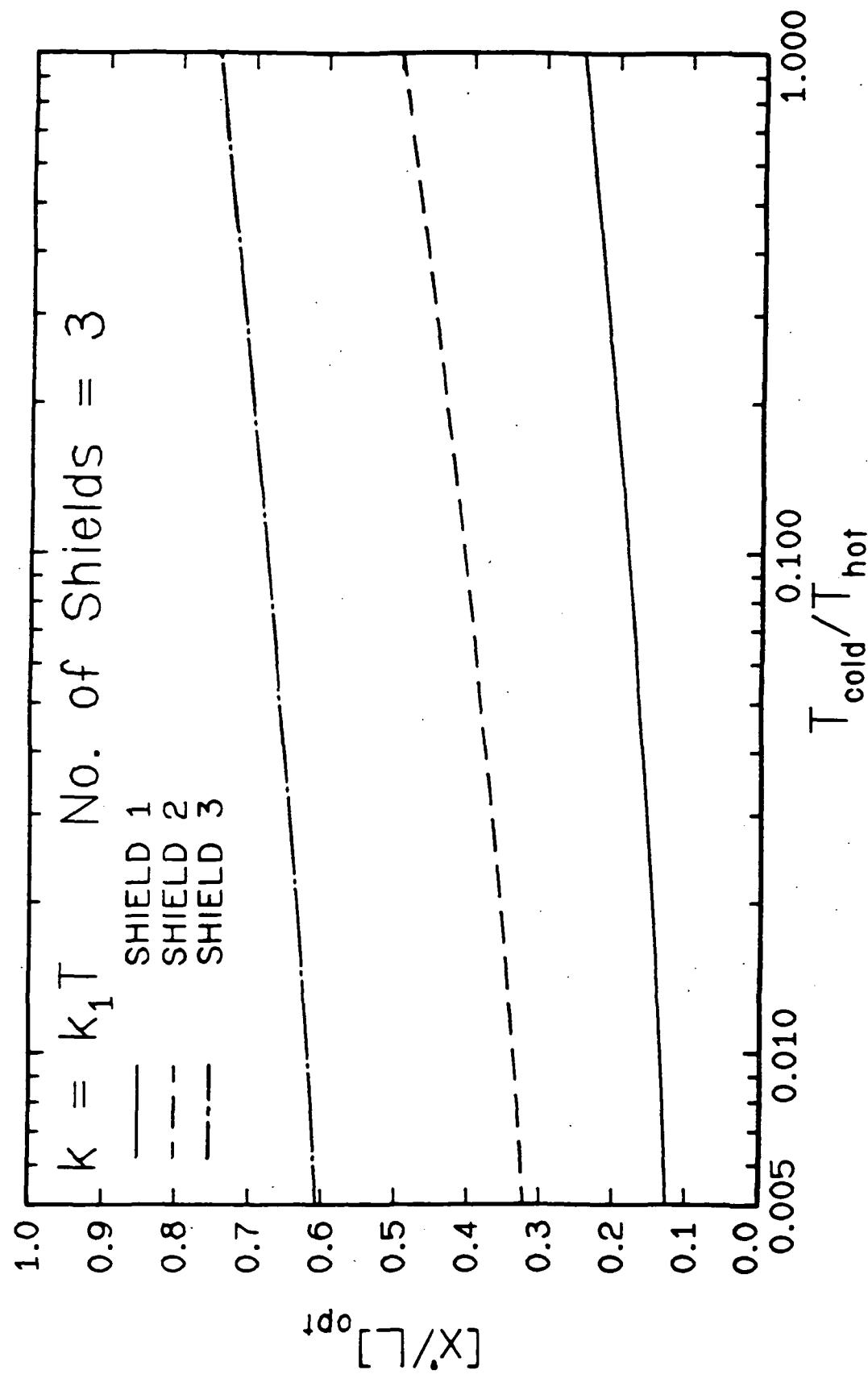


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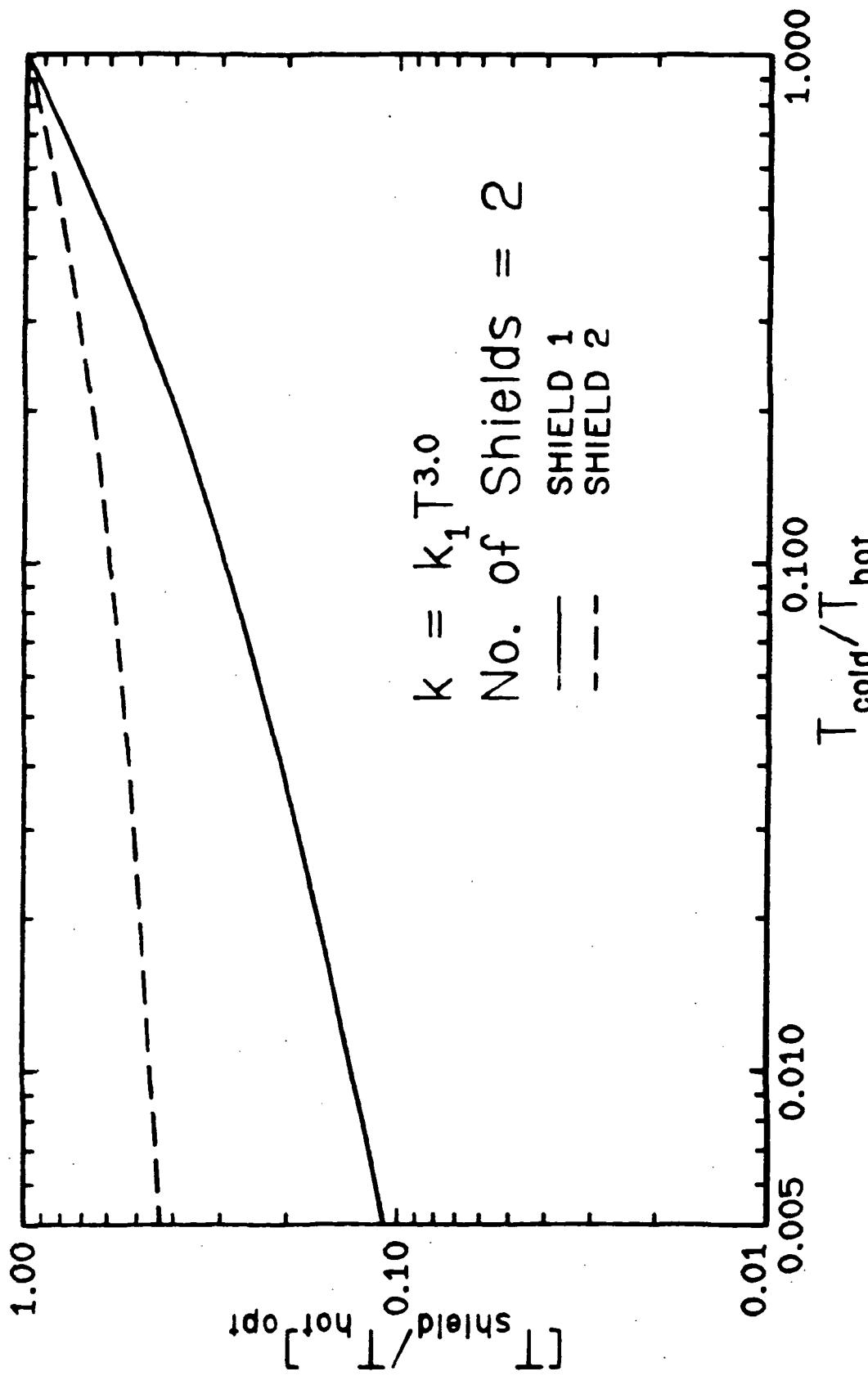


figure 18

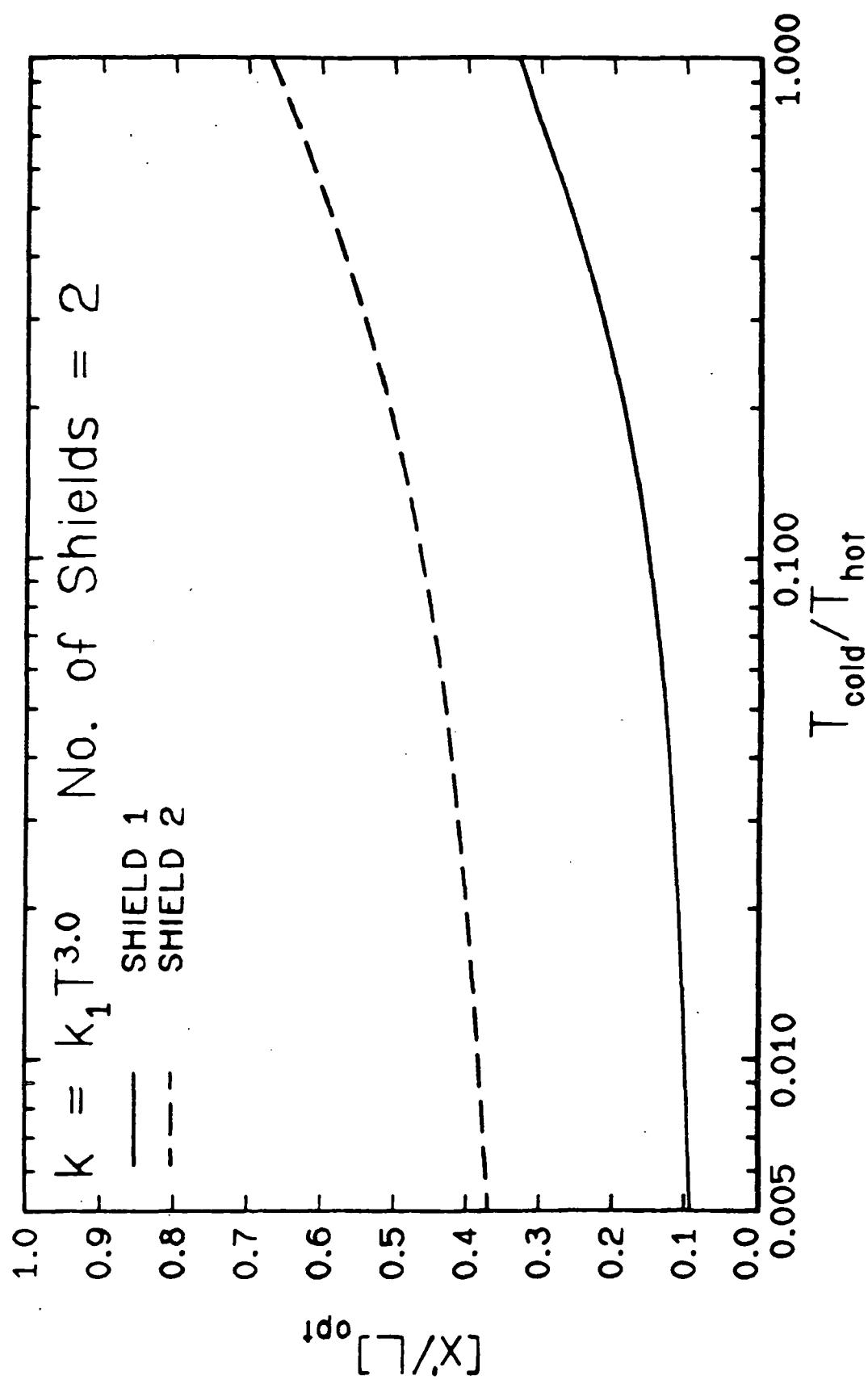


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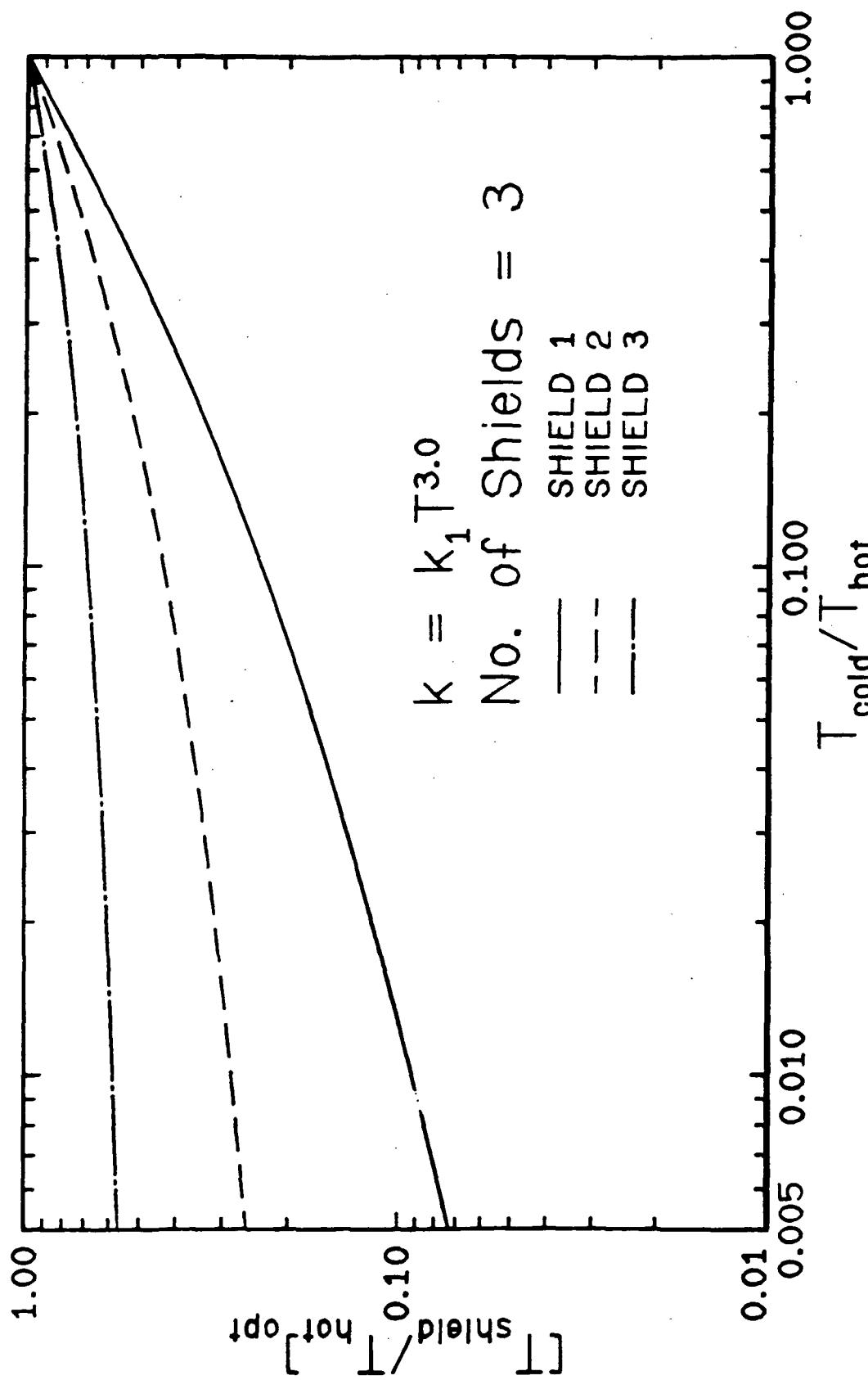


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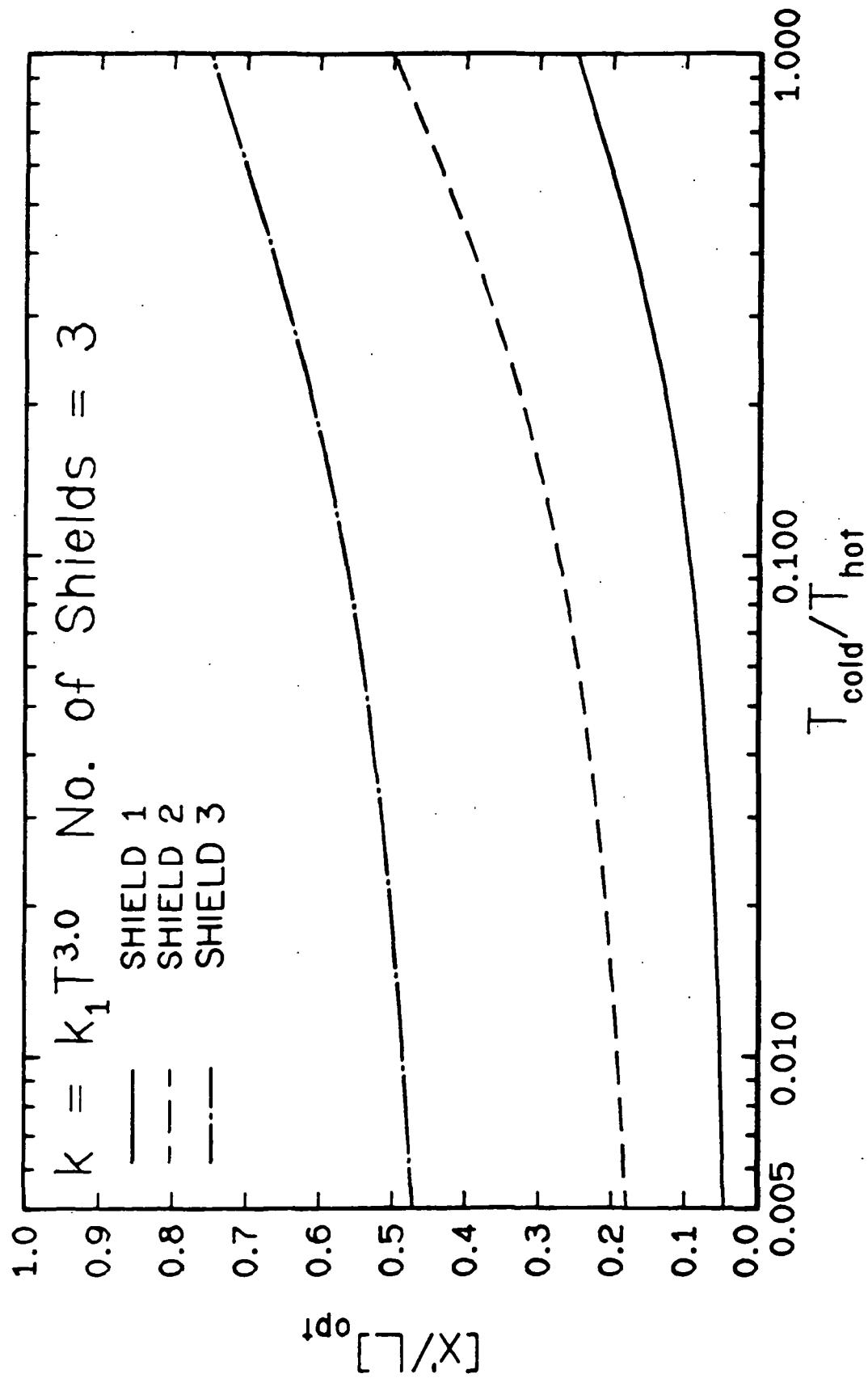


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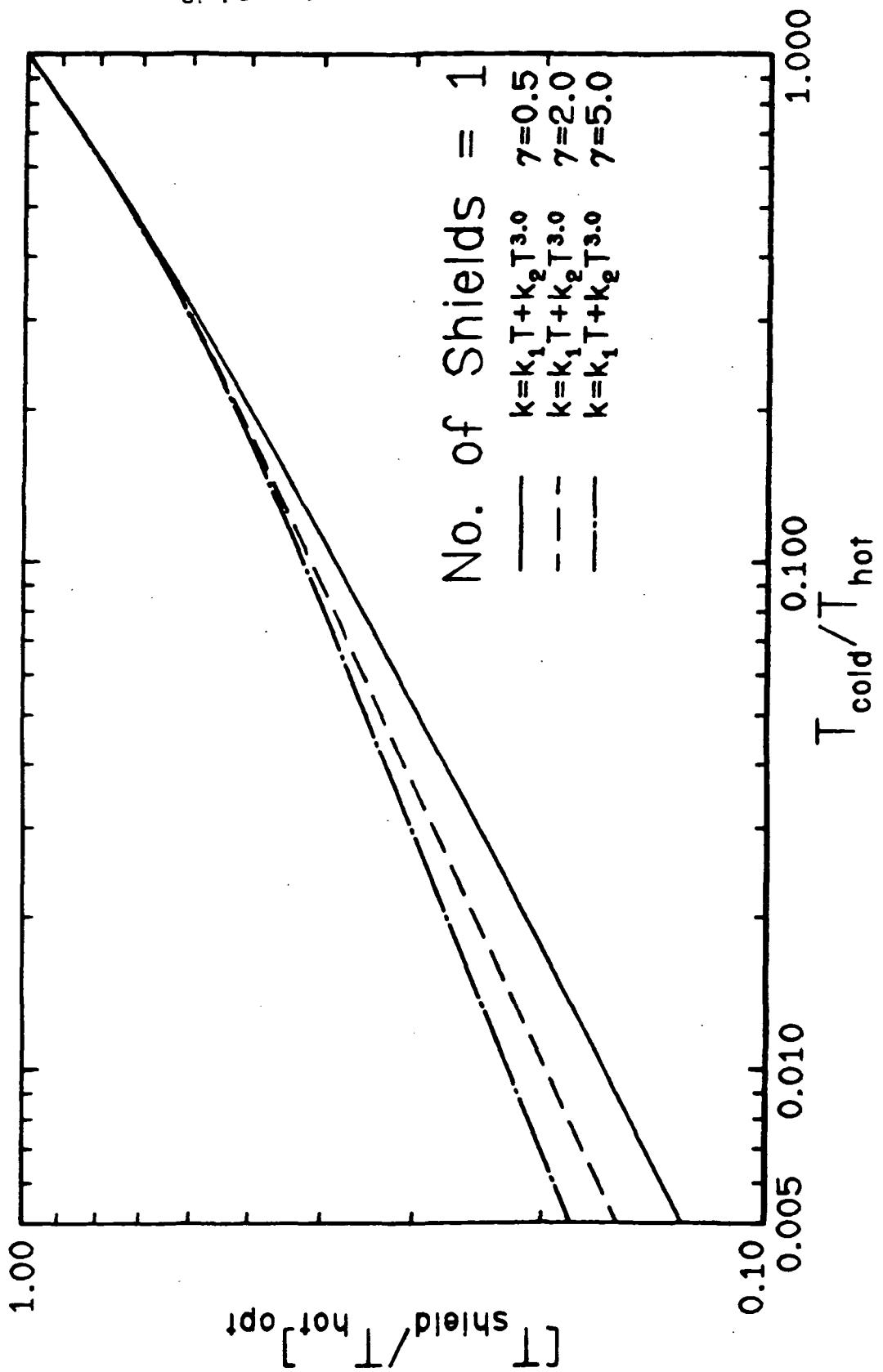


Figure 22

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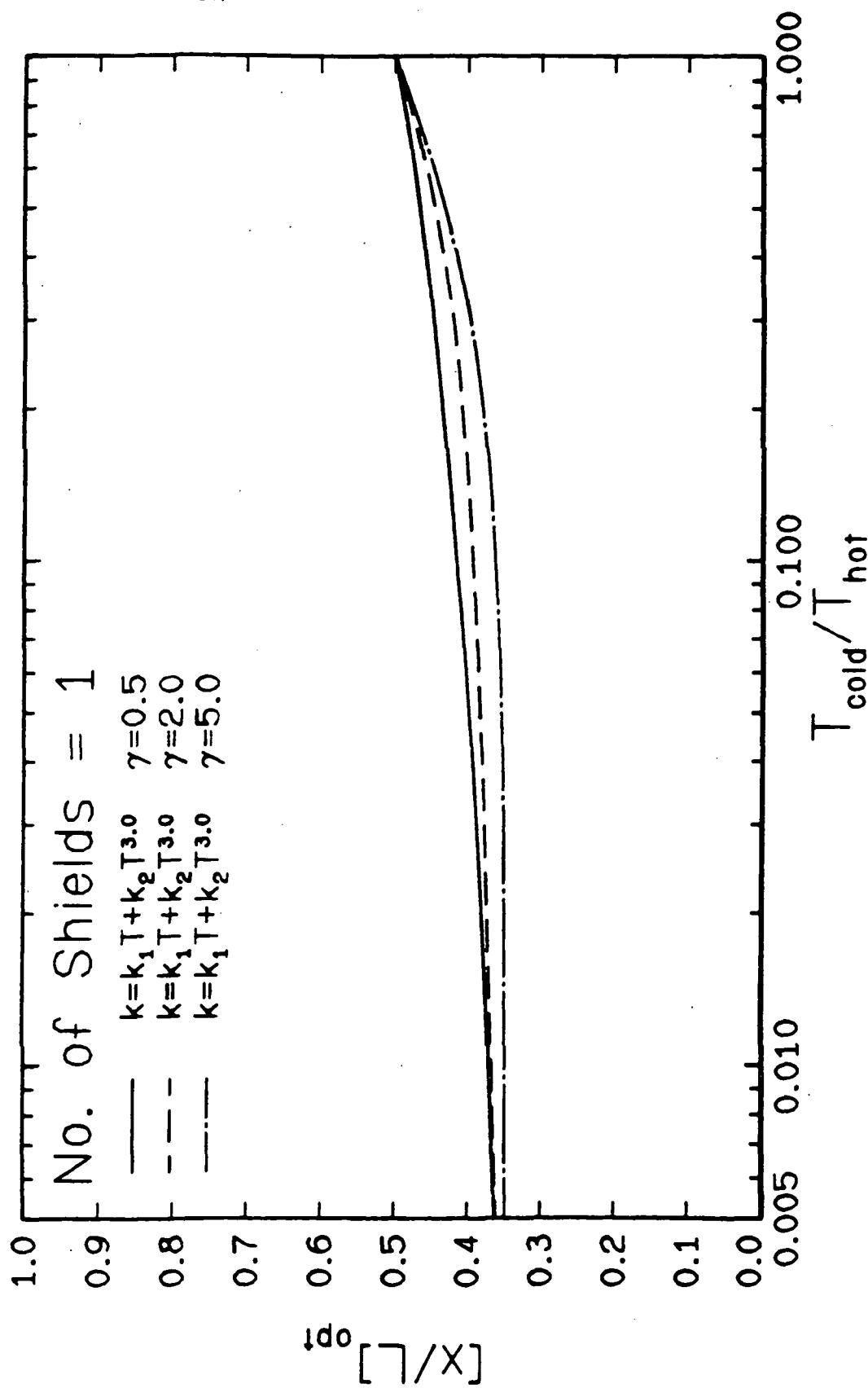


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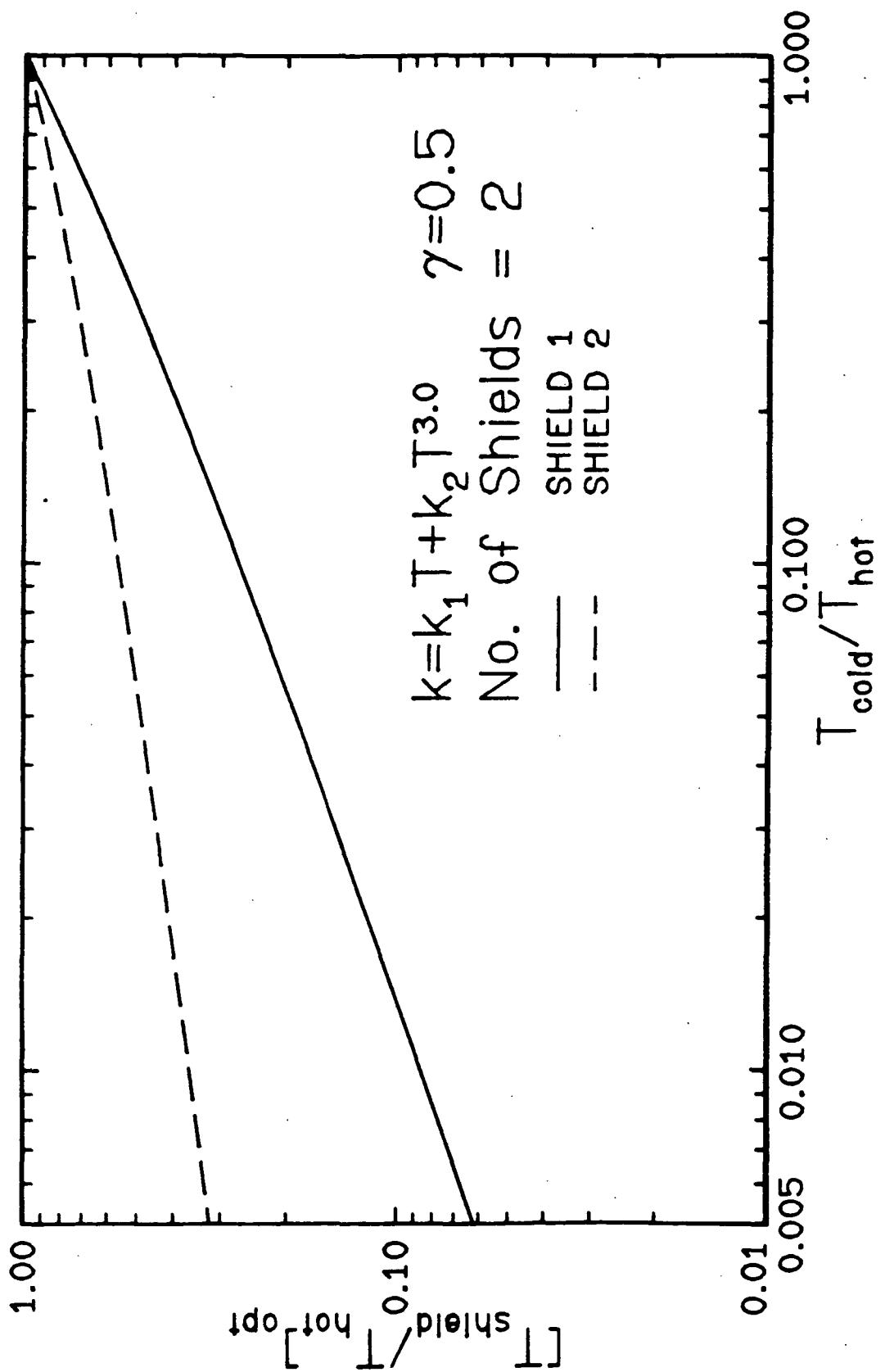


Figure 24

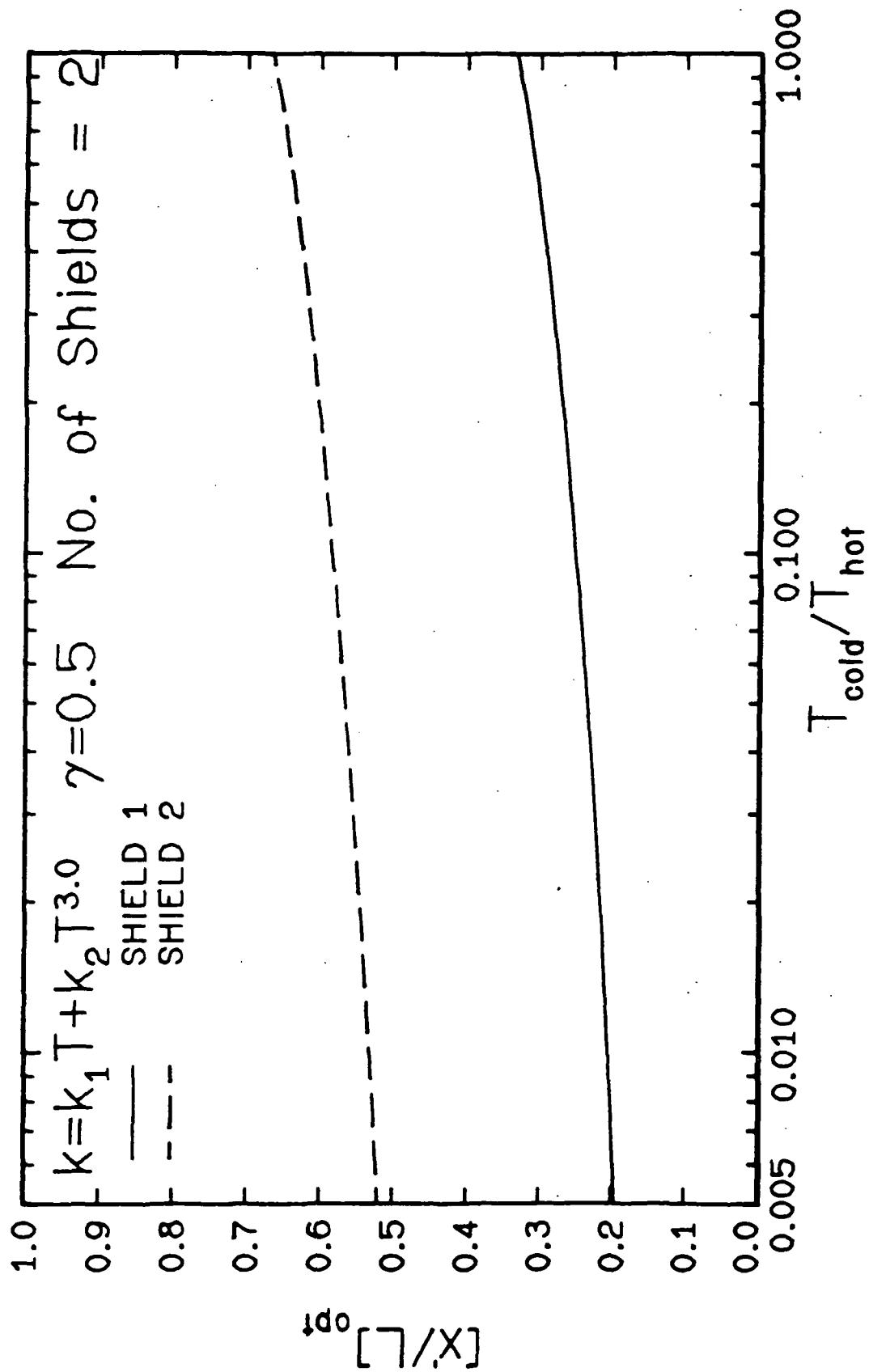


Figure 25

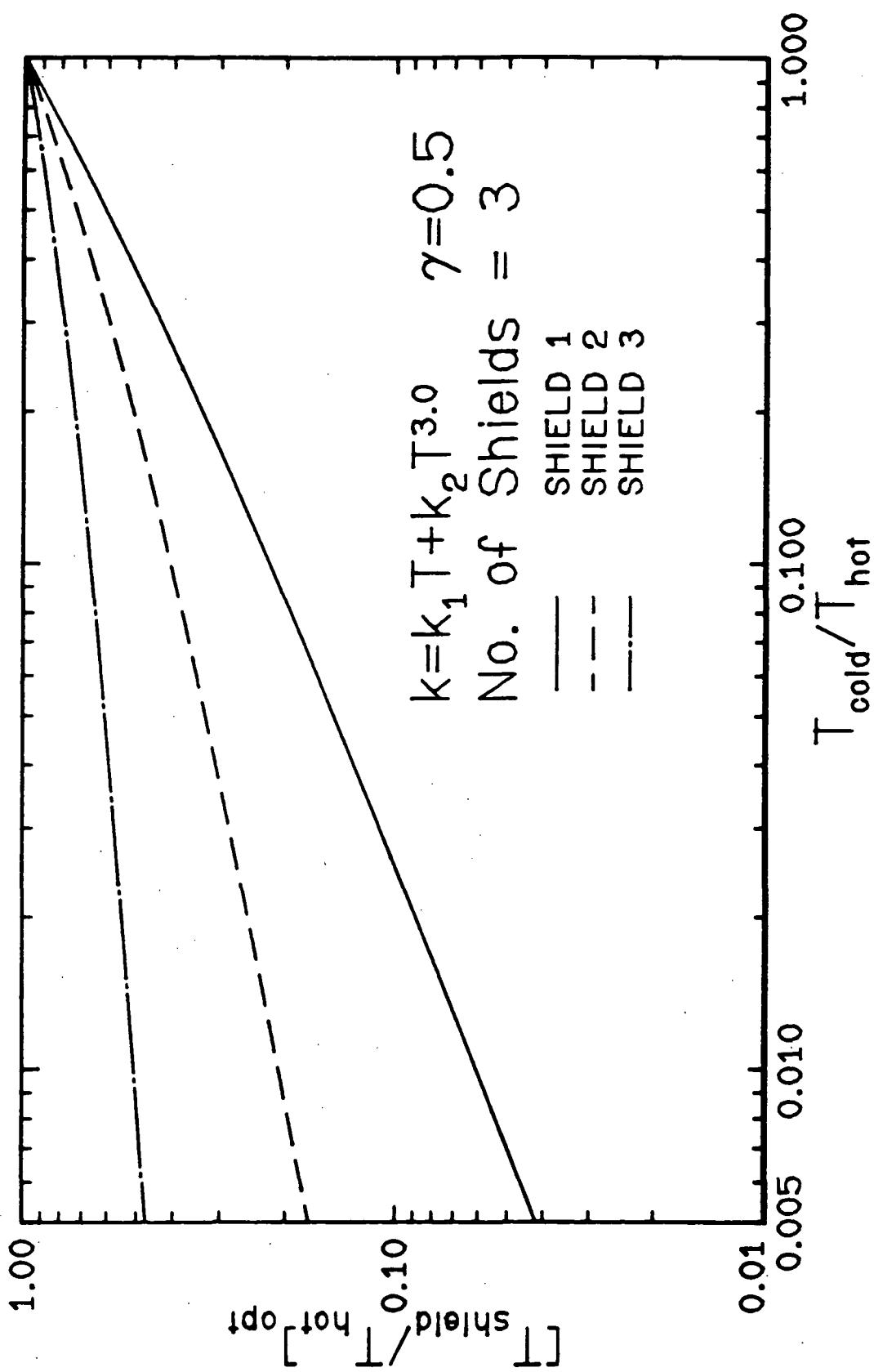


Figure 26

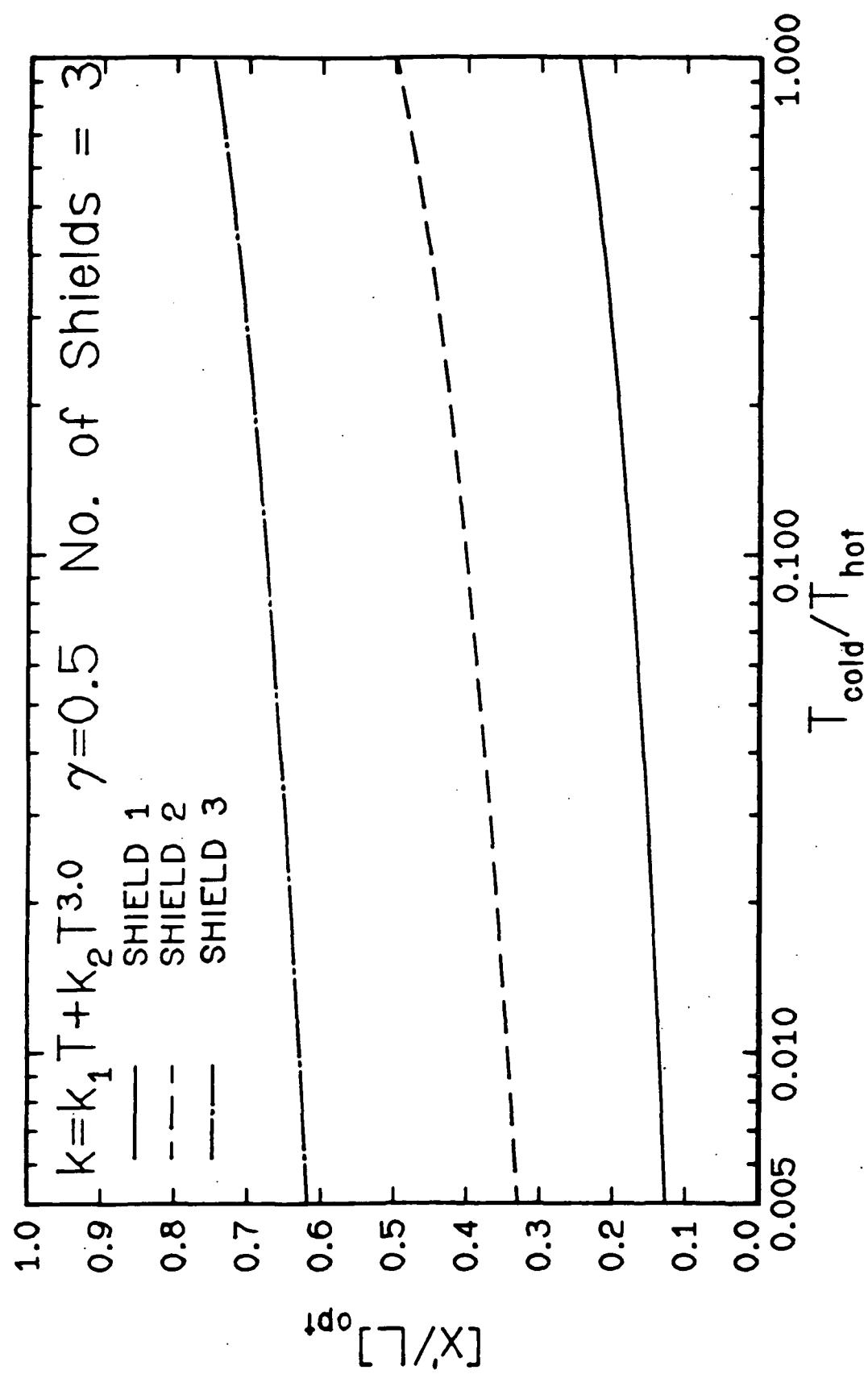


Figure 27

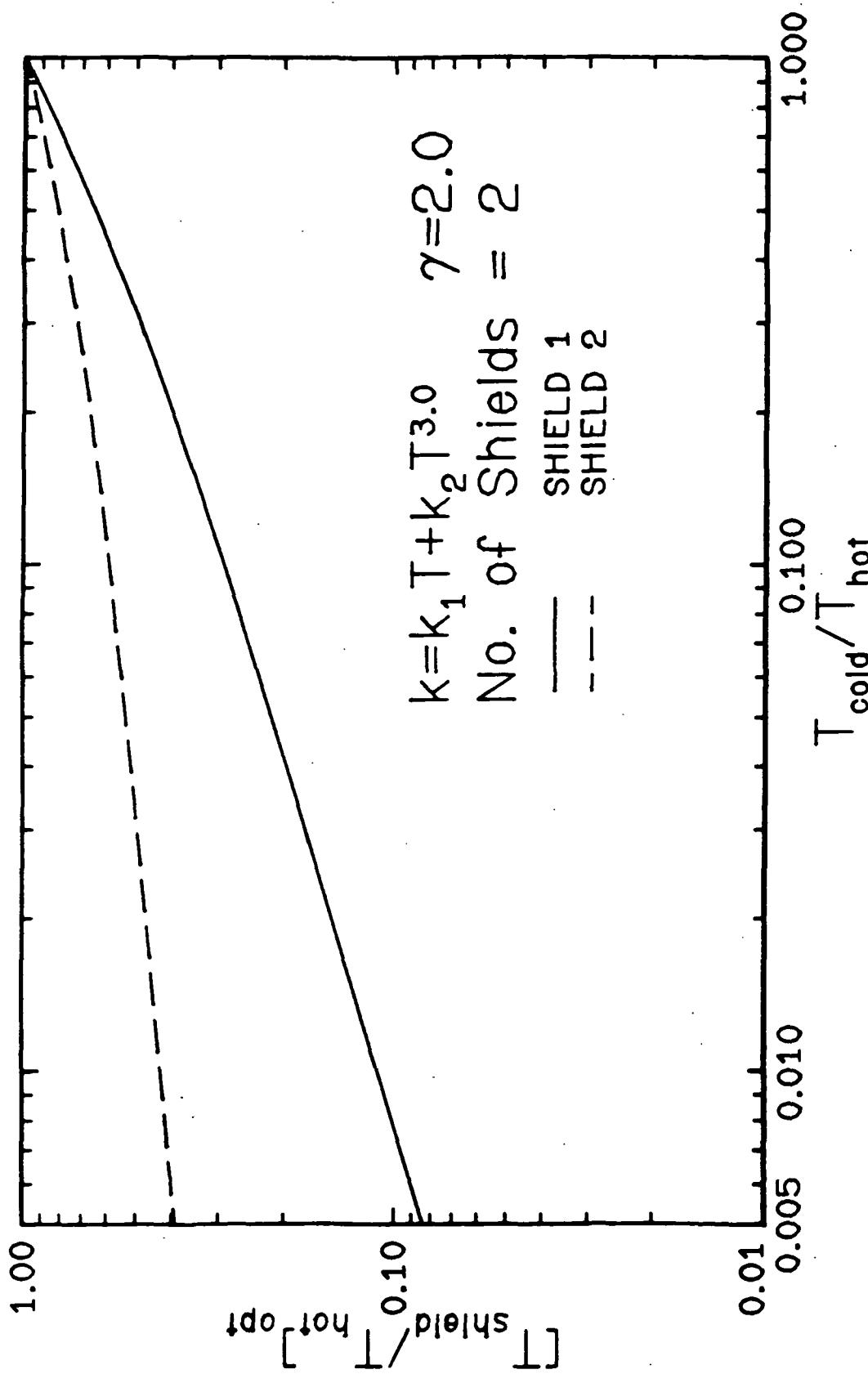


Figure 28

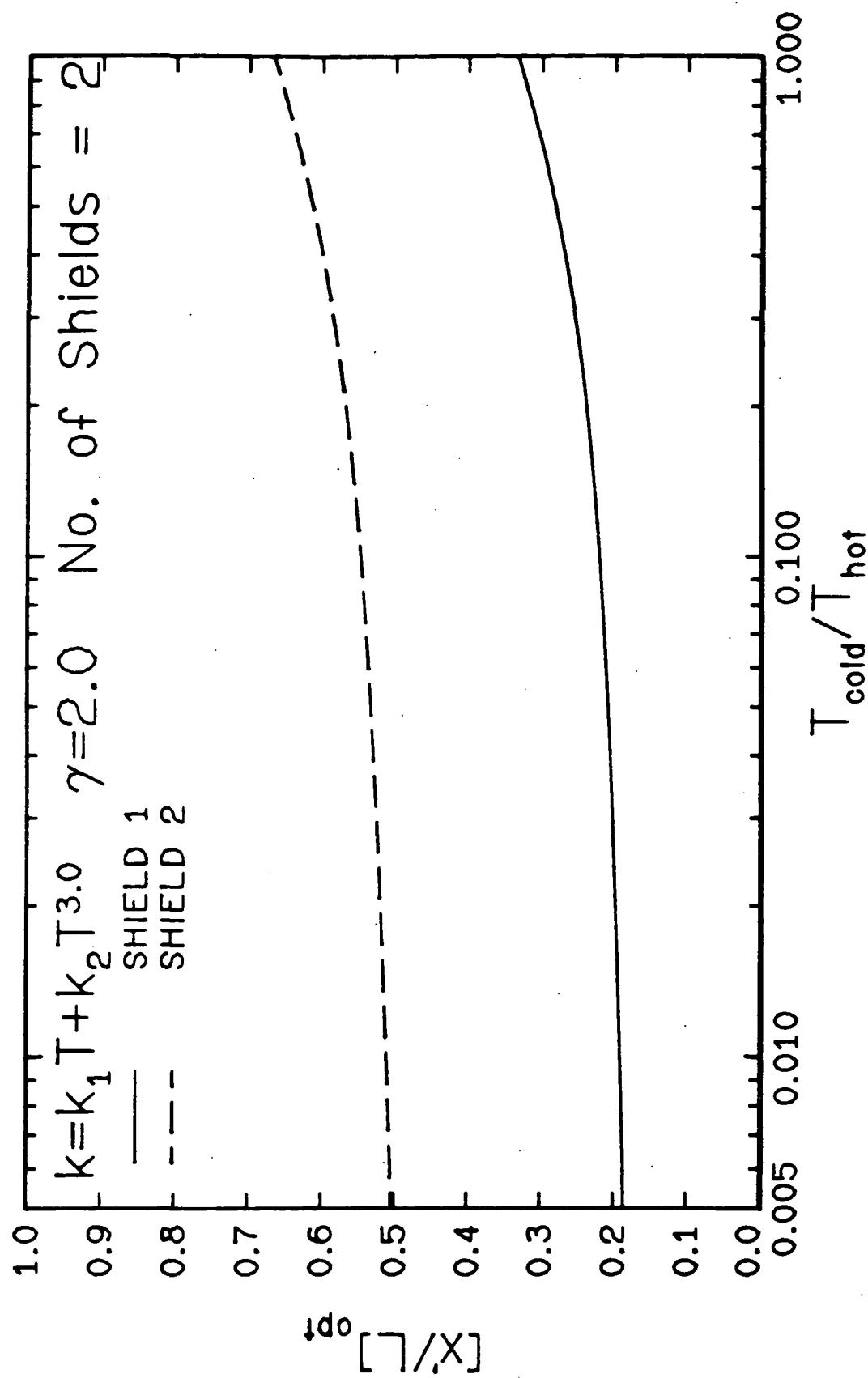


Figure 29.

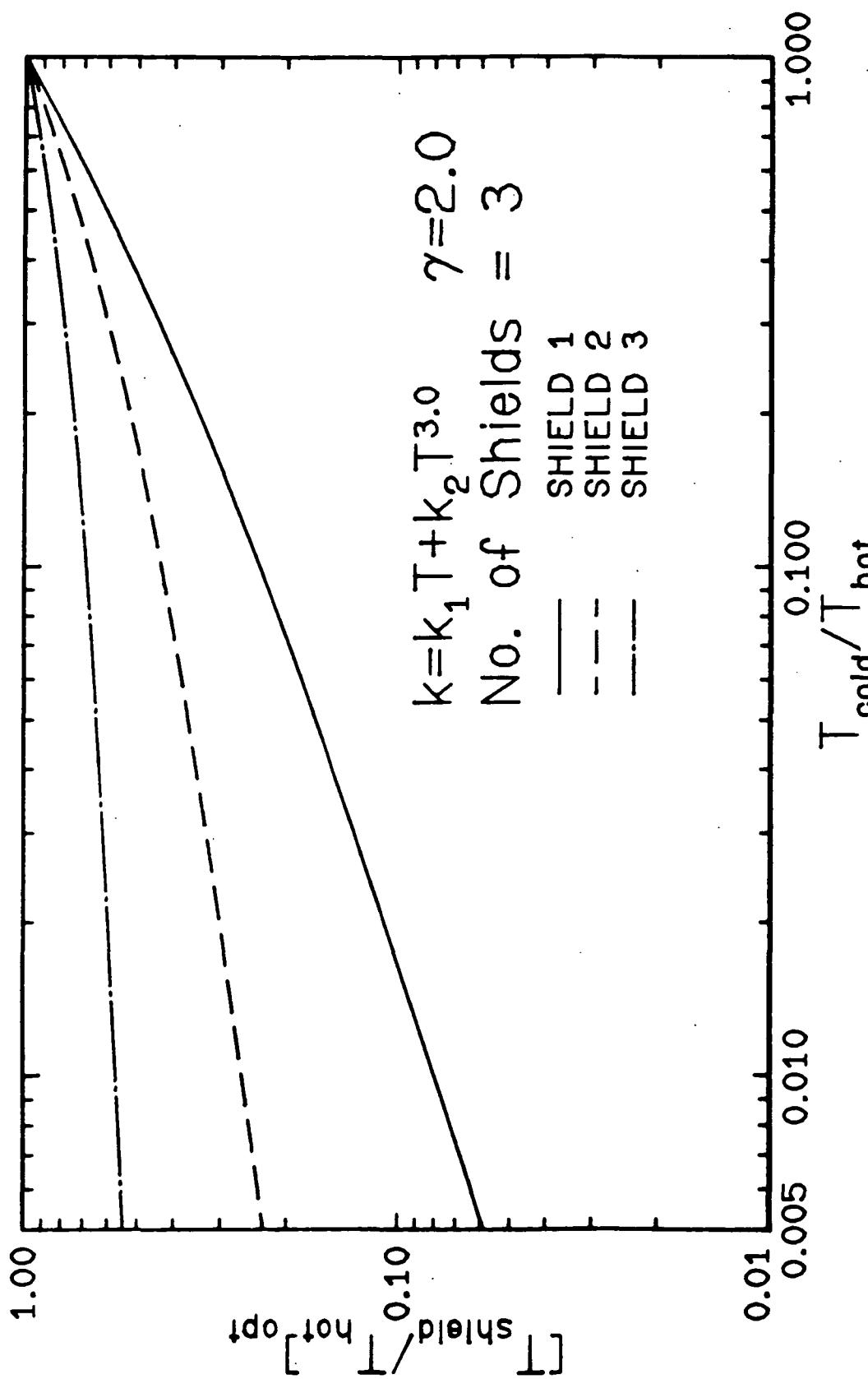


Figure 30

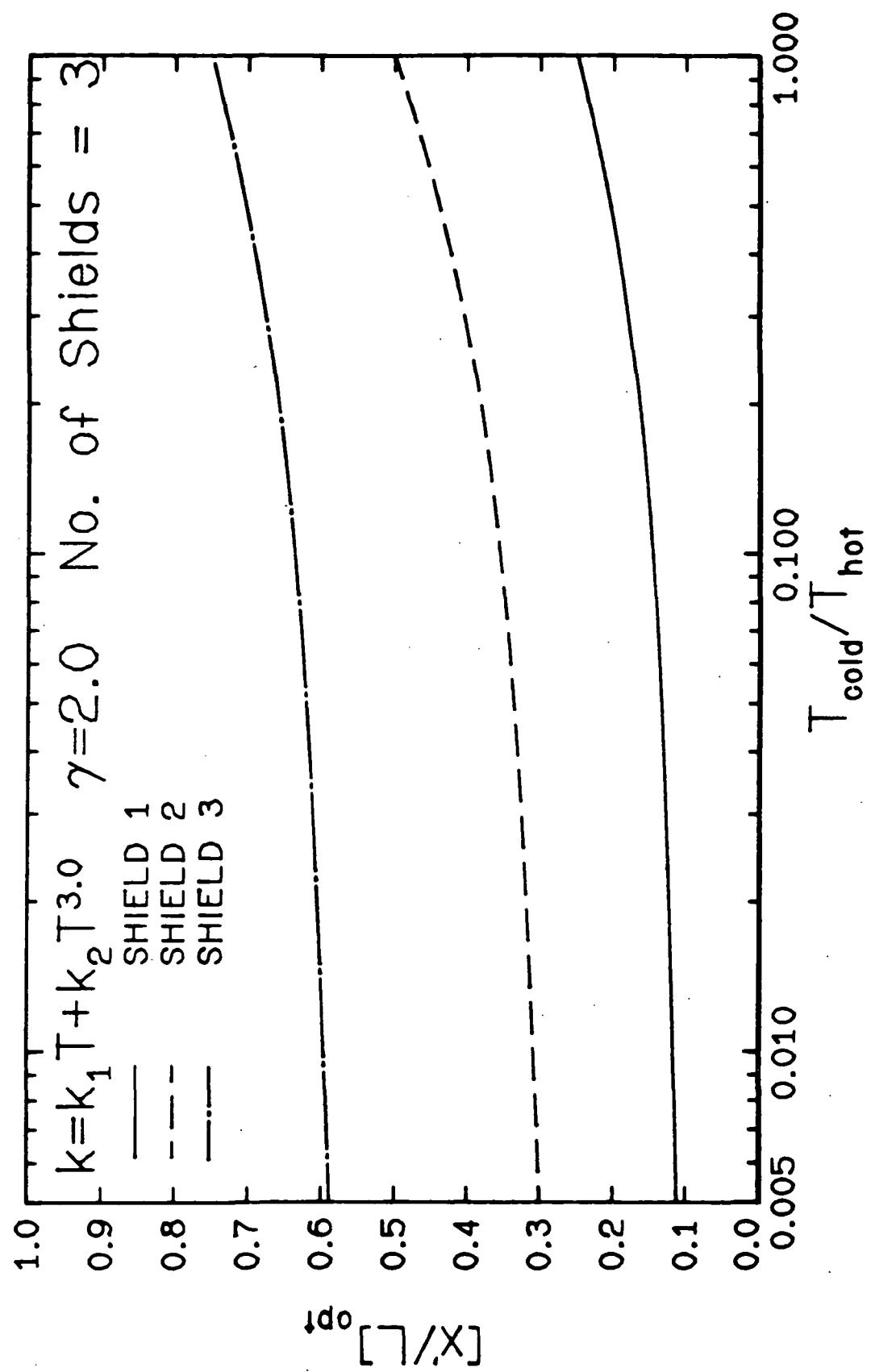


Figure 31

Curve Set 3: Figures 32 through 35

System sensitivity to deviations from the optimum shield
temperatures and locations for two overall temperature ratios
with one cooled shield

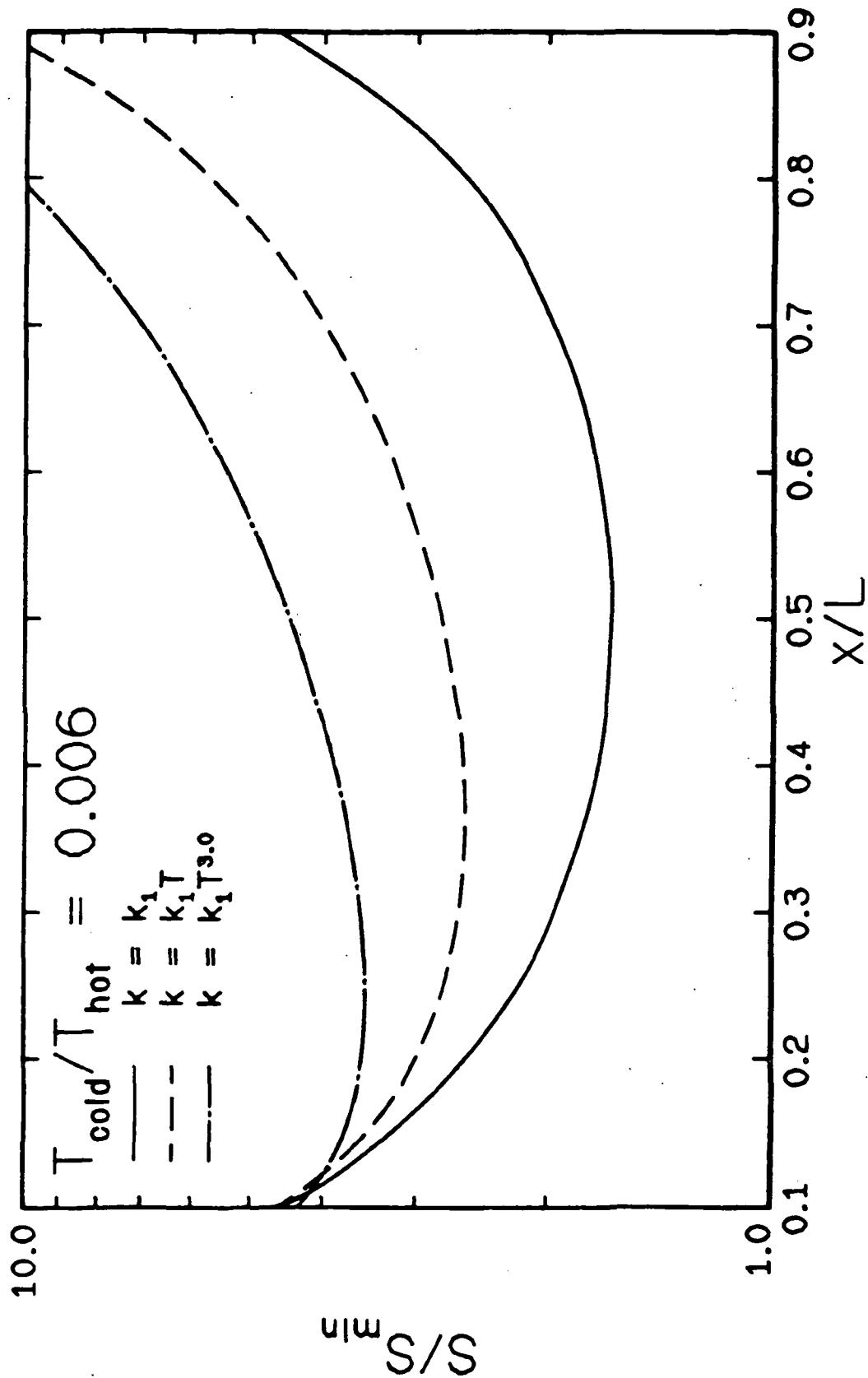


Figure 32

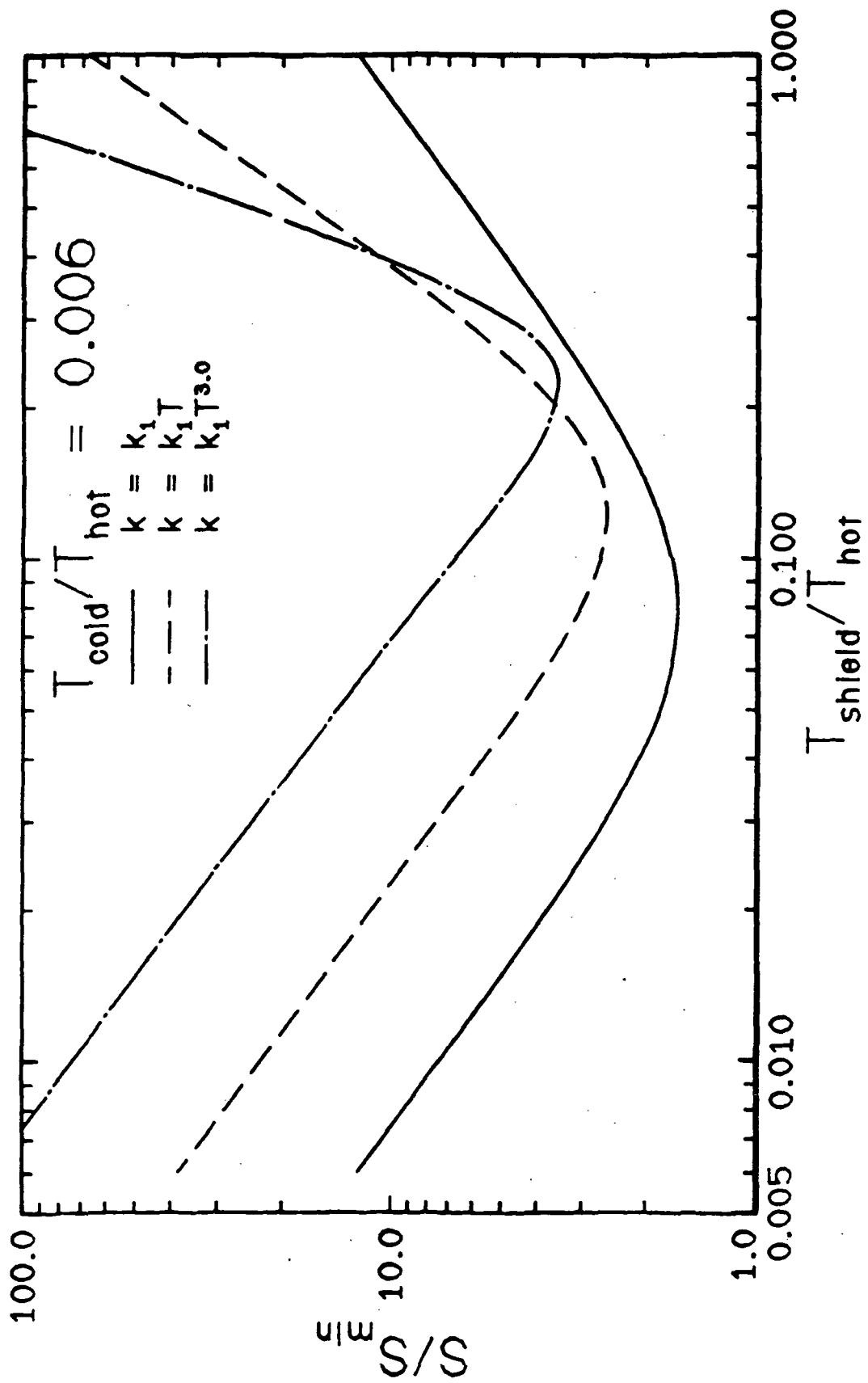


Figure 33

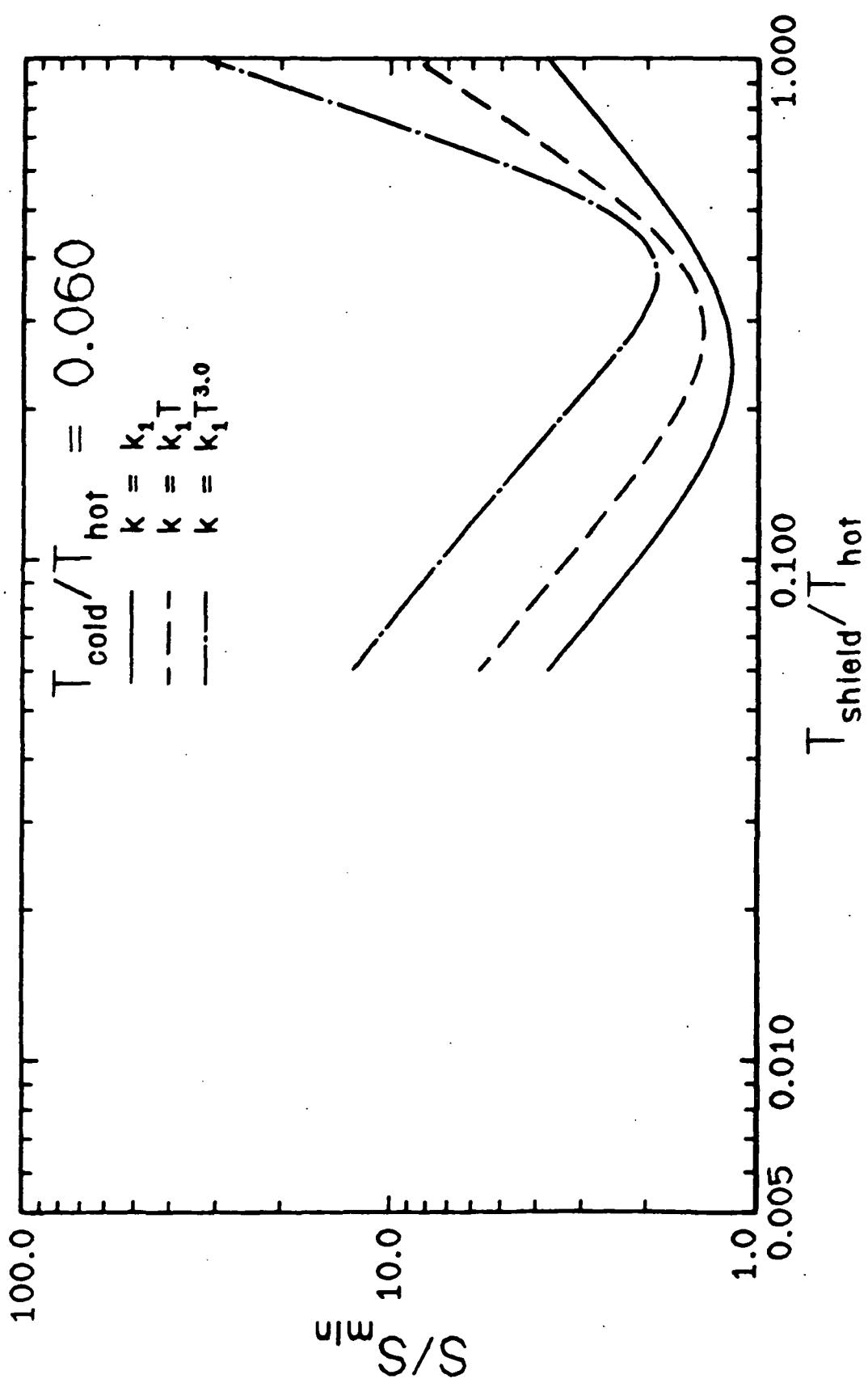


Figure 34

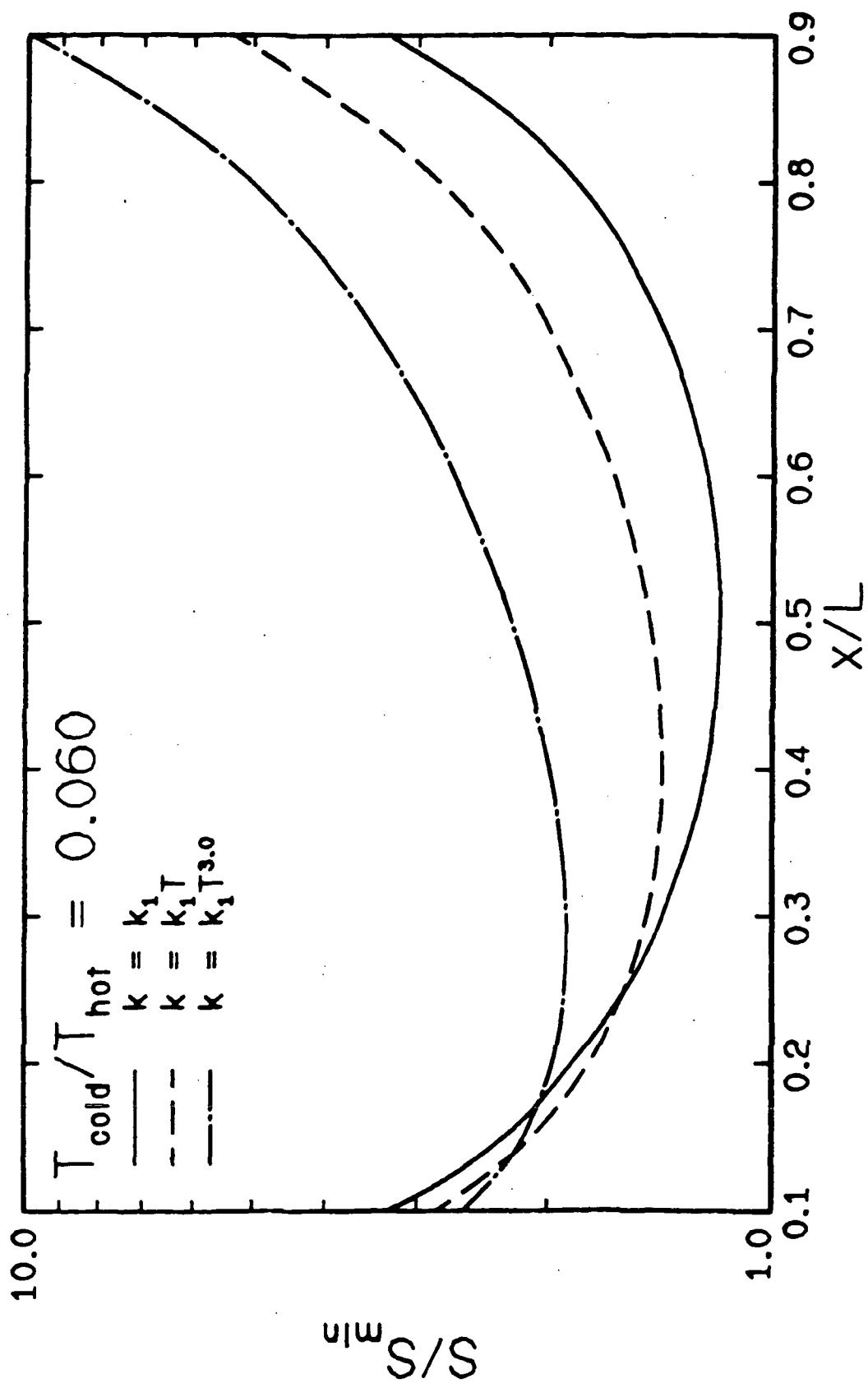


Figure 35

APPENDIX
COMPUTER PROGRAMS

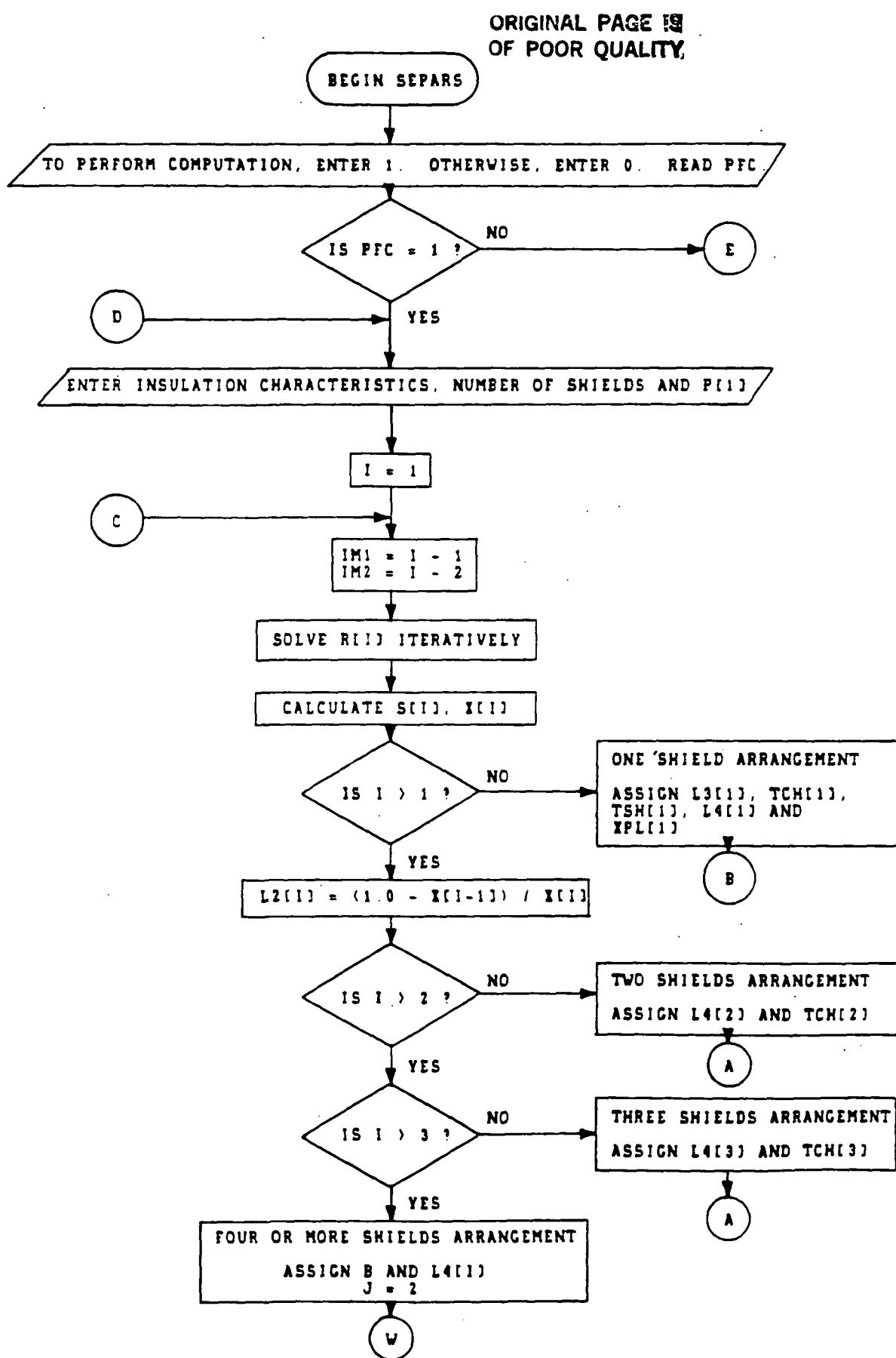
SEPARS and SHIELD

These two programs are essentially identical, but SEPARS is written in PASCAL whereas SHIELD is in BASIC.

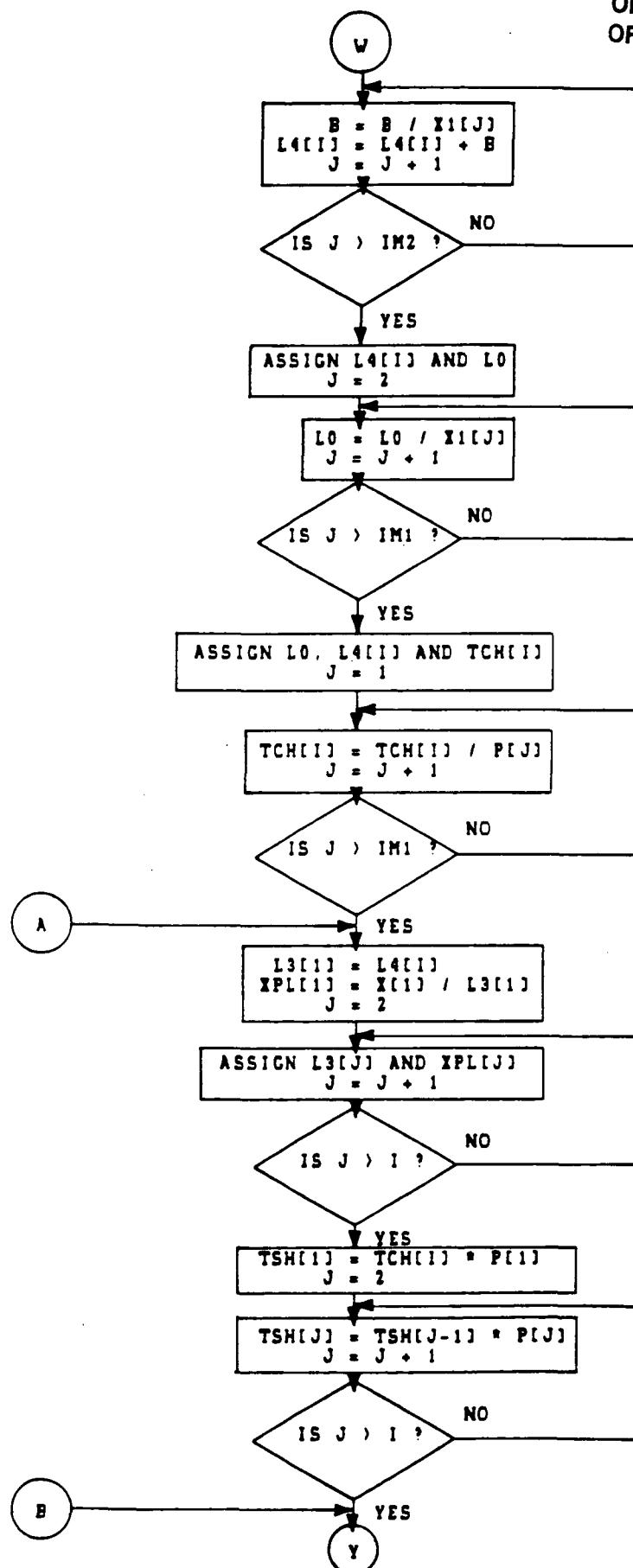
To allow for consecutive calculations of different systems, the program always recycles to the starting point. Consequently, the first input requested is either a 1, if a calculation is to be performed, or a 0, if no more work is to be done.

Next the program requests input of the insulation's characteristics, specifically, the two exponents of the temperatures in the two-term conductivity function, the maximum number of cooled shields (<10) to evaluate, the value of γ , and the temperature ratio of the first shield to the cold wall, $P(1) = T_{S1}/T_C$. The program calculates and presents the characteristics of all optimal systems of cooled shields from one shield to the maximum number specified in the input.

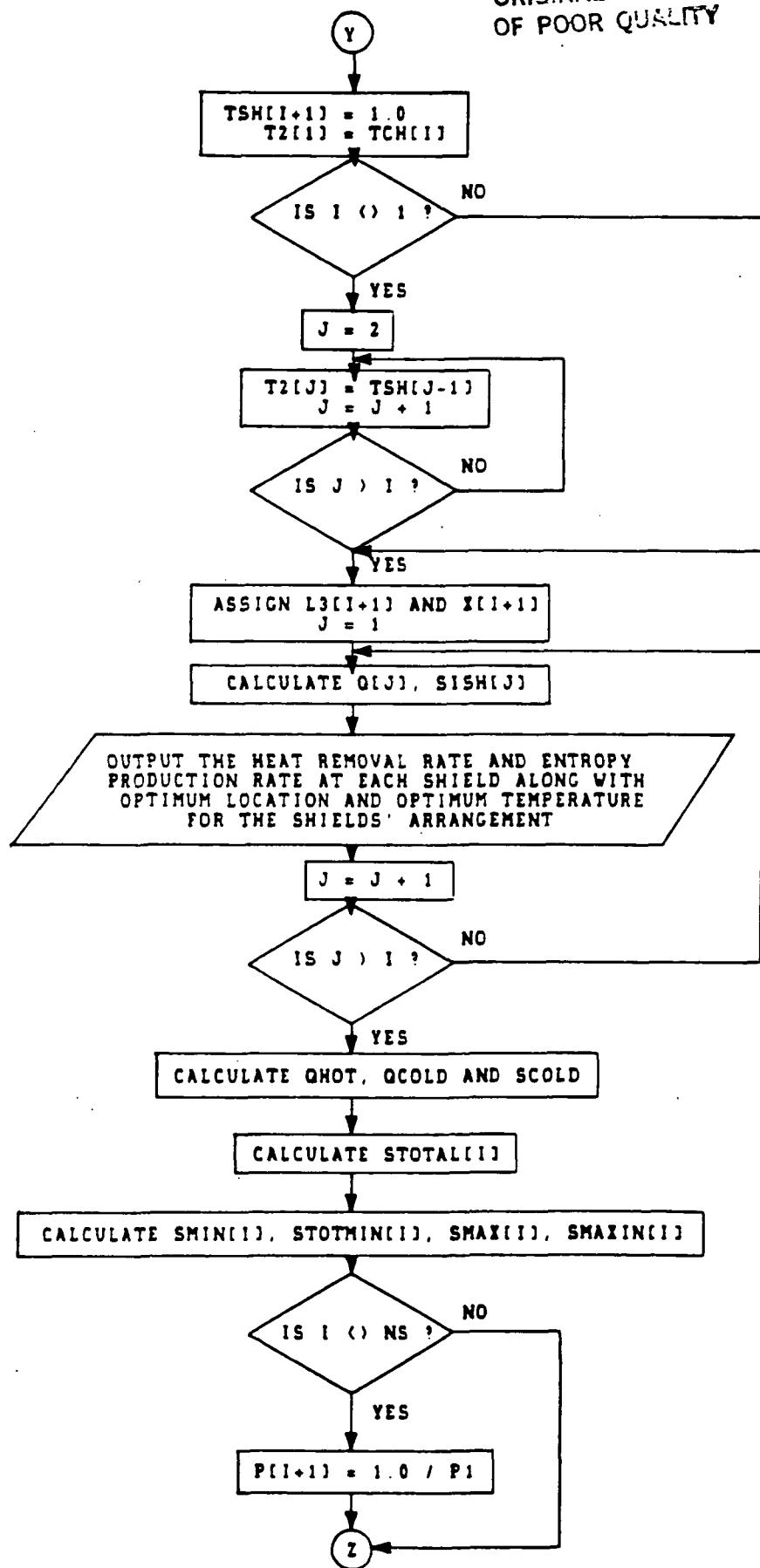
The flow chart and a program sample follows.



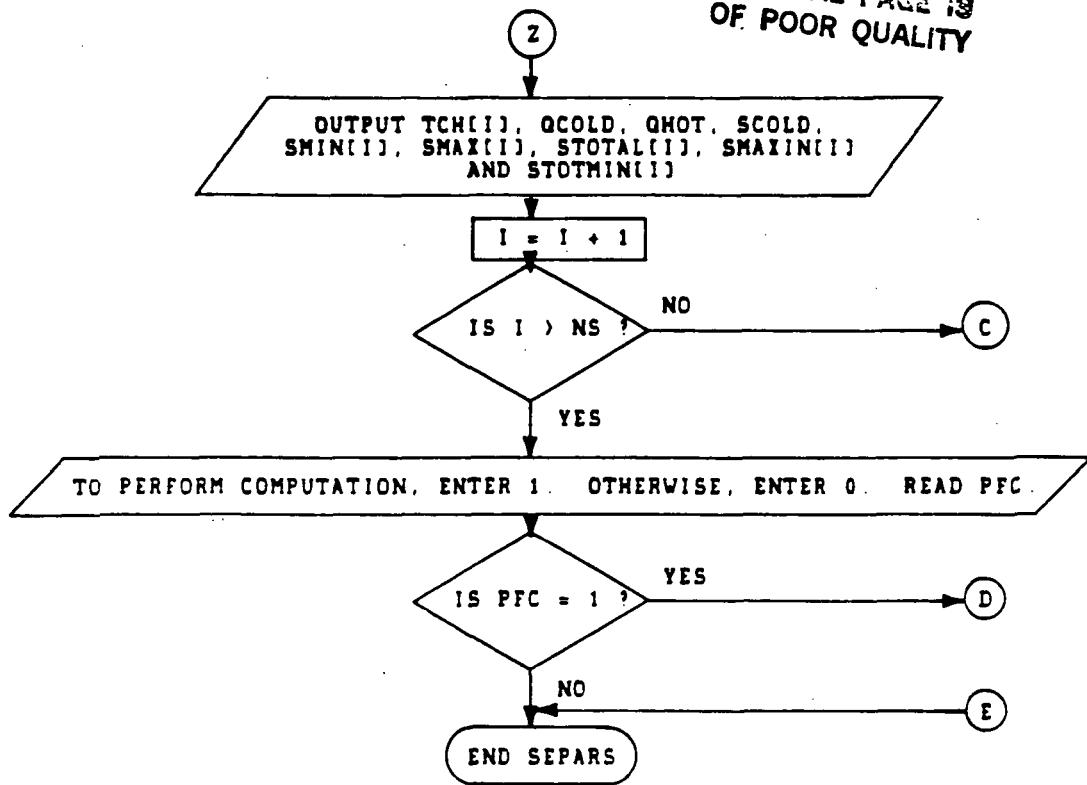
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PROGRAM SHIELDS (INPUT/, OUTPUT/, JMK).

```

75      B          REAL.           (* DUMMY VARIABLE *)
76      CC         REAL.           (* DUMMY VARIABLE *)
77      COUNT     INTEGER.        (* NUMBER OF ITERATIONS NEEDED TO DETERMINE R[1] *)
78      DD         REAL.           (* DUMMY VARIABLE *)
79      E,G1      REAL.           (* DUMMY VARIABLES *)
80      GAMA     REAL.           (* [K1*(N+1)]/[K1*(N+1)] * THOT**(N-N) , ALWAYS = 0 *)
81                  (* WHERE THOT IS THE HOT WALL TEMPERATURE (K) *)
82      I,IM1,IM2,J INTEGER.        (* INDICES FOR LOOPS *)
83      JNK       TEXT.           (* OUTPUT FILE TO BE USED IF DESIRED *)
84      L0         REAL.           (* DUMMY VARIABLE *)
85      M          REAL.           (* 1ST POWER IN THE THERMAL CONDUCTIVITY EQUATION *)
86      MP1       REAL.           (* EQUALS N+1 *)
87      N          REAL.           (* 2ND POWER IN THE THERMAL CONDUCTIVITY EQUATION *)
88      NP1       REAL.           (* EQUALS N+1 *)
89      NS         INTEGER.        (* NUMBER OF SHIELDS *)
90      PFC      INTEGER.        (* PROGRAM FLOW CONTROLLER *)
91      PI         REAL.           (* I-TH SHIELD / LOCAL HOT TEMPERATURE RATIO, ALWAYS < 1 *)
92      QCOLD    REAL.           (* HEAT OUT AT COLD WALL *)
93      QHOT     REAL.           (* HEAT IN AT HOT WALL *)
94      SCOLD    REAL.           (* ENTROPY PRODUCTION RATE AT COLD WALL *)
95      U,V       REAL.           (* DUMMY VARIABLES *)
96      W1,W2,W3  REAL.           (* DUMMY VARIABLES *)
97      Z1,Z2    REAL.           (* DUMMY VARIABLES *)
98
99
100
101 PROCEDURE INPUTH.
102 BEGIN   (* INPUT OF DATA HEADING *)
103     WRITELN;
104     WRITELN(* ENTER ----) M N NS GAMA P[1] ----*),
105     WRITELN(*),
106     WRITELN(* WHERE M ----- 1ST POWER IN THE THERMAL CONDUCTIVITY EQUATION),
107     WRITELN(* N ----- 2ND POWER IN THE THERMAL CONDUCTIVITY EQUATION),
108     WRITELN(* NS ----- NUMBER OF SHIELDS),
109     WRITELN(* GAMA -- =0 IF USING ONE TERM THERMAL CONDUCTIVITY EQUATION),
110     WRITELN(* >0 IF USING TWO TERM THERMAL CONDUCTIVITY EQUATION),
111     WRITELN(* P[1] -- 1ST SHIELD / COLD WALL TEMPERATURE RATIO, ALWAYS > 1),
112     WRITELN(*),
113     END.    (* INPUT OF DATA HEADING *)
114
115
116
117 PROCEDURE PFCH.
118 BEGIN   (* PFCH *)
119     WRITELN;
120     WRITELN(* TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.),
121     WRITELN(*),
122     END.    (* PFCH *)
123
124
125
126 PROCEDURE SINGLESPACE.
127 BEGIN   (* SINGLE SPACE IN OUTPUT *)
128     WRITELN(*),
129     END.    (* SINGLE SPACE IN OUTPUT *)
130
131
132
133 FUNCTION PWR(X,E) REAL;
134 VAR
135     A          REAL.
136     BEGIN   (* COMPUTE XX**E *)
137     A=E*LN(X),
138     PWR=EXP(A)
139     END.    (* COMPUTE XX**E *)
140
141
142
143
144 FUNCTION D(E,XX) REAL;
145 BEGIN   (* FUNCTIONAL D *)
146     D=(E+1.0)*PWR(XX,E)-E/(PWR(XX,(1.0-E)))-(1.0/SQR(XX))
147     END.    (* FUNCTIONAL D *)
148
149
150

```

```

151 FUNCTION F(E,XI:REAL):REAL;
152 BEGIN          (* FUNCTIONAL F *)
153   F:=(PWR(XI,(E+1.0))-PWR(XI,E)-1.0)*(1.0/XI)
154 END.           (* FUNCTIONAL F *)
155
156
157
158 FUNCTION SIMPSON(TCHB:REAL):REAL;
159 TYPE
160   ARR:ARRAY[1..101] OF REAL;
161
162 VAR
163   C,Y           ARR;
164   DELTAT        REAL;
165   H             REAL;
166   K,L           INTEGER;
167
168 BEGIN          (* COMPUTE MINIMUM ENTROPY PRODUCTION RATE USING SIMPSON'S NUMERICAL INTEGRATION SCHEME *)
169   DELTAT:=(1.0-TCHB)/100.0;
170   FOR L:=1 TO 101 DO
171     BEGIN
172       C[L]:=TCHB+DELTAT*(L-1);
173       Y[L]:=PWR((PWR(C[L],H)+GAMA*NPI/MPI)*PWR(C[L],N)),0.5)/C[L];
174     END;
175   H:=Y[1]+Y[101];
176   FOR K:=2 TO 100 DO
177     BEGIN
178       IF K=([K DIV 2]*2) THEN
179         H:=H+4.0*Y[K];
180       ELSE
181         H:=H+2.0*Y[K];
182     END;
183   SIMPSON:=(SQR(DELTAT/3.0)*H)/(1.0+GAMA*NPI/MPI);
184 END.           (* COMPUTE MINIMUM ENTROPY PRODUCTION RATE USING SIMPSON'S NUMERICAL INTEGRATION SCHEME *)
185
186
187
188
189
190
191
192 (* MAIN PROGRAM BODY *)
193
194 BEGIN
195   TCHB;
196   READLN;
197   READ(PFC);
198   WHILE PFC=1 DO
199     BEGIN
200
201       (* THIS BLOCK IS USED TO INPUT THE INSULATION THERMAL CONDUCTIVITY, NUMBER *)
202       (* OF SHIELDS AND 1ST. SHIELD / COLD WALL TEMPERATURE RATIO *)
203
204       INPUTH;
205       READLN;
206       READ(M,N,NS,GAMA,P1));
207       SINGLESPACE;
208       IF GAMA=0.0 THEN
209         Writeln('          THERMAL CONDUCTIVITY OF THE INSULATION IS K = K1*T**0.5*(H-1.0)');
210       ELSE
211         BEGIN
212           Writeln('          THERMAL CONDUCTIVITY OF THE INSULATION IS K = K1*T**0.5*(H-1.0) + K2*T**0.5*(H-1.0)');
213           Writeln('          [K1**2*(N+1)]/[K1**2*(N+1)]*THOT**0.5*(H-M) = ',GAMA:9,2);
214         END;
215       SINGLESPACE;
216       SINGLESPACE;
217
218
219       MPI:=M+1.0;
220       NPI:=N+1.0;
221       FOR I:=1 TO NS DO
222         BEGIN
223           IM1:=I-1;
224           IM2:=I-2;
225           BUSS:=0.000001;
226           CC:=0.1;
227           DD:=1.0;
228           COUNT:=0;
229

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230      (* THIS BLOCK CALCULATES R[] ITERATIVELY *)
231
232      REPEAT
233          P1 = P[1]*R[1];
234          W1 = PWR(R[1], M)*F(M, P[1]) + GAMA*PWR(R[1], N)*F(N, P[1]);
235          V2 = SQR(PWR(R[1], (M-1, 0))*D(M, P[1]) + GAMA*PWR(R[1], (N-1, 0))*D(N, P[1]));
236          V3 = SQR(D(M, P1) + GAMA*D(N, P1))/(F(M, P1) + GAMA*F(N, P1));
237          C = (V2/V1)*V3;
238          G1 = C*DD;
239          IF G1<0.0 THEN GOTO 100;
240          IF G1>0.0 THEN GOTO 200;
241          CC = (-0.1)*CC;
242          IF ABS(CC)<0.000001 THEN GOTO 300;
243          DD = -DD;
244          100 R[1] = R[1]+CC;
245          IF (R[1]>0.999999) OR (R[1]<-0.000001) THEN
246              BEGIN
247                  R[1] = R[1]-0.9*CC;
248                  CC = 0.1*CC;
249              END;
250          200 COUNT = COUNT+1;
251      UNTIL (G1=0.0) OR (ABS(CC)<0.000001);
252
253
254      U = -(PWR(R[1], (M-1, 0))*D(M, P[1]) + GAMA*PWR(R[1], (N-1, 0))*D(N, P[1]));
255      I[1] = U/(D(M, P1) + GAMA*D(N, P1));
256      X[1] = I[1]/(1.0-X[1]);
257      V = (F(M, P1) + GAMA*F(N, P1))/(1.0-X[1]);
258      S[1] = V*(PWR(R[1], M)*F(M, P[1]) + GAMA*PWR(R[1], N)*F(N, P[1]))/X[1];
259      S[1] = S[1]/(1.0+GAMA*MP1/MP1);
260
261      (* IN THIS BLOCK VARIABLES ARE ASSIGNED FOR DIFFERENT SHIELD CONFIGURATIONS *)
262
263      IF I[1] THEN
264          BEGIN
265              L2[1] = (1.0-I[1-1])/X[1];
266              IF I[1/2] THEN
267                  IF I[1/3] THEN
268                      BEGIN
269                          B = 1.0;
270                          L4[1] = 0.0;
271                          FOR J = 2 TO IM2 DO
272                              BEGIN
273                                  B = B/X[1];
274                                  L4[1] = L4[1]+B;
275                              END;
276                          L4[1] = L4[1]*(1.0-X[1])+1.0;
277                          L0 = 1.0-X[1];
278                          FOR J = 2 TO IM1 DO L0 = L0/X[1];
279                          L0 = L0/X[1];
280                          L4[1] = L4[1]+L0;
281                          TCH[1] = R[1];
282                          FOR J = 1 TO IM1 DO TCH[1] = TCH[1]/P[J];
283                      END;
284                  ELSE
285                      BEGIN
286                          L4[3] = 1.0*(1.0-I[1])*(1.0-X[2])/(X[2]*X[3]);
287                          TCH[3] = R[3]/(P[1]*P[2]);
288                      END;
289                  ELSE
290                      BEGIN
291                          L4[2] = X[1]+(1.0-I[1])/X[2];
292                          TCH[2] = R[2]/P[1];
293                      END;
294                  L3[1] = L4[1];
295                  XPL[1] = X[1]/L3[1];
296                  FOR J = 2 TO 1 DO
297                      BEGIN
298                          L3[2] = L3[2-1]/L2[2];
299                          XPL[2] = XPL[2-1]*X[2]/L3[2];
300                      END;
301                  TSH[1] = TCH[1]*P[1];
302                  FOR J = 2 TO 1 DO TSH[1] = TSH[1]*P[J];
303              END;
304          ELSE

```

```

305      BEGIN
306          L3[1] = 1.0.
307          TCH[1] = R[1].
308          TSH[1] = TCH[1]*P[1].
309          L4[1] = 1.0;
310          XPL[1] = X[1]
311      END.
312      TSH[1+1] = 1.0,
313      T2[1] = TCH[1],
314
315
316      SINGLESPACE.
317      WRITELN('      NUMBER OF SHIELDS      = ',I-1);
318      WRITELN('      NUMBER OF ITERATIONS = ',COUNT),
319      SINGLESPACE,
320      WRITELN('      HEAT REMOVAL      ENTROPY PRODUCTION      OPTIMUM      OPTIMUM'),
321      WRITELN('      RATE            RATE            LOCATION      TEMPERATURE'),
322      WRITELN('-----  -----  -----  -----');
323      SINGLESPACE,
324      IF (<)0 THEN
325          FOR J = 2 TO I DO T2[J] = TSH[J-1];
326          L3[1+1] = L3[1];
327          X[1+1] = 1.0-X[1];
328
329
330      (* IN THIS BLOCK DIMENSIONLESS HEAT REMOVAL AND ENTROPY PRODUCTION RATES *)
331      (* ARE CALCULATED FOR EACH SHIELD *)
332
333      FOR J = 1 TO I DO
334          BEGIN
335              Z1 = ((PWR(TSH[J-1],NP1)-PWR(TSH[J],NP1))*L3[J+1]/X[J+1]-(PWR(TSH[J],NP1)-PWR(T2[J],NP1))*L3[J]/X[J])/NP1;
336              Z2 = ((PWR(TSH[J+1],NP1)-PWR(TSH[J],NP1))*L3[J+1]/X[J+1]-(PWR(TSH[J],NP1)-PWR(T2[J],NP1))*L3[J]/X[J])/NP1;
337              Q(J) = Z1*GAMA*Z2/(1.0+GAMA*NP1/NP1);
338              SISH(J) = Q(J)/TSH[J];
339              WRITELN('      SHIELD ',J,2,'  ',5,0,Q(J),9.5,'  ',11,SISH(J),9.5,'  ',9,XPL(J),9.5,'  ',5,TSH[J],9.5),
340          END.
341
342      (* FINALLY, OTHER QUANTITIES OF INTEREST ARE CALCULATED IN THIS BLOCK *)
343
344      SINGLESPACE.
345      QHOT = ((1.0-PWR(TSH[1],NP1)+GAMA-GAMA*PWR(TSH[1],NP1))*L3[1]/(X[1]+1)*NP1)/(1.0+GAMA*NP1/NP1),
346      QCOLD = (PWR(TSH[1],NP1)-PWR(TCH[1],NP1)+GAMA*PWR(TSH[1],NP1)-GAMA*PWR(TCH[1],NP1))*L3[1]/(X[1]*NP1),
347      QCOLD = QCOLD/(1.0+GAMA*NP1/NP1),
348      SCOLD = QCOLD/TCH[1];
349      STOTAL[1] = SCOLD-QHOT;
350      FOR J = 1 TO I DO STOTAL[1] = STOTAL[1]+SISH(J),
351      SMIN[1] = SIMPSON(TCH[1]),
352      STOTMIN[1] = STOTAL[1]/SMIN[1],
353      SMA[1] = ((1.0-PWR(TCH[1],NP1)+GAMA-GAMA*PWR(TCH[1],NP1))*(1.0/TCH[1]-1.0)/NP1)/(1.0+GAMA*NP1/NP1),
354      SMA[1] = SMA[1]/SMIN[1],
355
356
357      IF (<)0.5 THEN P[1+1] = 1.0/P[1];
358      SINGLESPACE,
359      WRITELN('      COLD WALL / HOT WALL TEMPERATURE RATIO      = ',TCH[1],14.6),
360      WRITELN('      HEAT OUT AT COLD WALL      = ',QCOLD,14.6),
361      WRITELN('      HEAT IN AT HOT WALL      = ',QHOT,14.6),
362      WRITELN('      ENTROPY PRODUCTION RATE AT COLD WALL      = ',SCOLD,14.6),
363      WRITELN('      ENTROPY PRODUCTION RATE AT HOT WALL      = ',-QHOT,14.6),
364      WRITELN('      MINIMUM ENTROPY PRODUCTION RATE      = ',SMIN[1],14.6),
365      WRITELN('      MAXIMUM ENTROPY PRODUCTION RATE      = ',SMA[1],14.6),
366      WRITELN('      TOTAL ENTROPY PROD. RATE WITH ',I,2,' SHIELDS      = ',STOTAL[1],14.6),
367      WRITELN('      MAXIMUM / MINIMUM ENTROPY PRODUCTION RATIO      = ',SMA[1],14.6),
368      WRITELN('      TOTAL / MINIMUM ENTROPY PRODUCTION RATIO      = ',STOTMIN[1],14.6),
369      SINGLESPACE,
370      SINGLESPACE,
371      SINGLESPACE
372
373      END.
374      PFCN,
375      READLN,
376      READ(PFC),
377      END
378      END
379  /EOP
???

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TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.

? 1

ENTER ----> M N NS GAMA P[1] <----

WHERE: M ----- 1ST. POWER IN THE THERMAL CONDUCTIVITY EQUATION
 N ----- 2ND. POWER IN THE THERMAL CONDUCTIVITY EQUATION
 NS ---- NUMBER OF SHIELDS
 GAMA -- =0 IF USING ONE TERM THERMAL CONDUCTIVITY EQUATION
 >0 IF USING TWO TERM THERMAL CONDUCTIVITY EQUATION
 P[1] -- 1ST. SHIELD / COLD WALL TEMPERATURE RATIO, ALWAYS > 1

? 1.0 3.0 1 2.5 15.0

THERMAL CONDUCTIVITY OF THE INSULATION IS $K = K1*T**1.0 + K2*T**3.0$
 $[K2*(M+1)]/[K1*(N+1)]*THOT**(N-M) = 2.50$

NUMBER OF SHIELDS = 1
 NUMBER OF ITERATIONS = 35

HEAT REMOVAL RATE	ENTROPY PRODUCTION RATE	OPTIMUM LOCATION	OPTIMUM TEMPERATURE
SHIELD 1 0.43837	1.85659	0.36744	0.23611
COLD WALL / HOT WALL TEMPERATURE RATIO	=	0.015741	
HEAT OUT AT COLD WALL	=	0.014350	
HEAT IN AT HOT WALL	=	0.452719	
ENTROPY PRODUCTION RATE AT COLD WALL	=	0.911631	
ENTROPY PRODUCTION RATE AT HOT WALL	=	-0.452719	
MINIMUM ENTROPY PRODUCTION RATE	=	1.000503	
MAXIMUM ENTROPY PRODUCTION RATE	=	18.236148	
TOTAL ENTROPY PROD. RATE WITH 1 SHIELDS	=	2.315503	
MAXIMUM / MINIMUM ENTROPY PRODUCTION RATIO =		18.226982	
TOTAL / MINIMUM ENTROPY PRODUCTION RATIO =		2.314340	

TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.

? 1

ENTER ----> M N NS GAMA P[1] <----

WHERE: M ----- 1ST. POWER IN THE THERMAL CONDUCTIVITY EQUATION
 N ----- 2ND. POWER IN THE THERMAL CONDUCTIVITY EQUATION
 NS ---- NUMBER OF SHIELDS
 GAMA -- =0 IF USING ONE TERM THERMAL CONDUCTIVITY EQUATION
 >0 IF USING TWO TERM THERMAL CONDUCTIVITY EQUATION
 P[1] -- 1ST. SHIELD / COLD WALL TEMPERATURE RATIO, ALWAYS > 1

? 1.0 .090 2 0.0 25.0

THERMAL CONDUCTIVITY OF THE INSULATION IS $K = K1*T**1.0$

NUMBER OF SHIELDS = 1
 NUMBER OF ITERATIONS = 23

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HEAT REMOVAL RATE	ENTROPY PRODUCTION RATE	OPTIMUM LOCATION	OPTIMUM TEMPERATURE
SHIELD 1 0.75466	7.03151	0.35870	0.10732

COLD WALL / HOT WALL TEMPERATURE RATIO	=	0.004293
HEAT OUT AT COLD WALL	=	0.016030
HEAT IN AT HOT WALL	=	0.770687
ENTROPY PRODUCTION RATE AT COLD WALL	=	3.734070
ENTROPY PRODUCTION RATE AT HOT WALL	=	-0.770687
MINIMUM ENTROPY PRODUCTION RATE	=	3.504633
MAXIMUM ENTROPY PRODUCTION RATE	=	115.966533
TOTAL ENTROPY PROD. RATE WITH 1 SHIELDS	=	9.994893
MAXIMUM / MINIMUM ENTROPY PRODUCTION RATIO	=	33.089491
TOTAL / MINIMUM ENTROPY PRODUCTION RATIO	=	2.851908

NUMBER OF SHIELDS = 2
NUMBER OF ITERATIONS = 36

HEAT REMOVAL RATE	ENTROPY PRODUCTION RATE	OPTIMUM LOCATION	OPTIMUM TEMPERATURE
SHIELD 1 0.05470	2.71297	0.17465	0.02016
SHIELD 2 0.88421	4.70678	0.48690	0.18786

COLD WALL / HOT WALL TEMPERATURE RATIO	=	0.000806
HEAT OUT AT COLD WALL	=	0.001162
HEAT IN AT HOT WALL	=	0.940073
ENTROPY PRODUCTION RATE AT COLD WALL	=	1.440716
ENTROPY PRODUCTION RATE AT HOT WALL	=	-0.940073
MINIMUM ENTROPY PRODUCTION RATE	=	3.921467
MAXIMUM ENTROPY PRODUCTION RATE	=	619.477774
TOTAL ENTROPY PROD. RATE WITH 2 SHIELDS	=	7.920388
MAXIMUM / MINIMUM ENTROPY PRODUCTION RATIO	=	157.970919
TOTAL / MINIMUM ENTROPY PRODUCTION RATIO	=	2.019751

TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.

? 0

0.175 CP SECs. 124158 CM USED.

PROGRAM SHIELD

```
1 00010 REM THIS IS A "BASIC" PROGRAM TO CALCULATE OPTIMUM TEMPERATURES.
2 00020 REM LOCATIONS, AND COOLING LOADS FOR COOLED SHIELDS IN A CRYOGENIC
3 00030 REM INSULATION SYSTEM WHOSE THERMAL CONDUCTIVITY FOLLOWS THE RELATION
4 00040 REM  $K=C1*T^M0 + C2*T^M1$ 
5 00045 REM MODIFIED IN LATE NOV. 1982.
6 00050 REM
7 00060 REM DEFINITION OF SYMBOLS USED
8 00070 REM
9 00080 REM COLD-SIDE WALL TEMPERATURE TO
10 00090 REM WARM-SIDE WALL TEMPERATURE T9
11 00100 REM SPACING BETWEEN SHIELDS AT I+1 AND I-1 L1(I)
12 00110 REM OVERALL THICKNESS OF INSULATION L
13 00120 REM LOCAL SPACING RATIO, L1(I)/L1(I-1), L2(I)
14 00130 REM OVERALL SPACING RATIO, L/L1(I), L4(I)
15 00140 REM (DISTANCE FROM COLD WALL)/L LS(I)
16 00150 REM I-TH SHIELD TEMPERATURE T(I)
17 00160 REM I-TH SHIELD POSITION RATIO X(I)
18 00170 REM I-TH SHIELD TEMPERATURE RATIO P(I) (ALWAYS >1)
19 00180 REM I-TH COLD-WARM TEMPERATURE RATIO R(I) (ALWAYS <1)
20 00190 REM I-TH DIMENSIONLESS ENTROPY PRODUCTION RATE S(I)
21 00195 REM I-TH DIMENSIONLESS HEAT REMOVAL RATE Q(I)
22 00210 REM TOTAL DIMENSIONLESS ENTROPY PROD. RATE S2(I)
23 00220 REM MINIMUM ENTROPY PRODUCTION RATE S0(I)
24 00230 REM ENTROPY PROD. RATE WITHOUT SHIELDS S9(I)
25 00240 REM ENTROPY PROD. RATE RATIOS S1=S2/S0 AND S4=S9/S0
26 00250 REM NUMBER OF SHIELDS M (= OR 10)
27 00260 REM
28 00265 DIM C(10),X(10)
29 00270 PRINT " "
30 00280 PRINT "INPUT 1 IF MORE WORK IS TO BE DONE, 0 IF FINISHED"
31 00290 INPUT A
32 00300 IF A=0 THEN 01350
33 00310 PRINT "INPUT M0,NO,M,CAMMA & P(I)"
34 00320 INPUT M0,NO,M,CAMMA,P(I)
35 00325 DEF FND(Y)=(M0+1)*Y^M0-M0/(Y^(1-M0))-1/(Y^Y)
36 00330 DEF FNE(Y)=(NO+1)*Y^NO-NO/(Y^(1-NO))-1/(Y^Y)
37 00335 DEF FNG(Y)=Y^(M0+1)-Y^M0+1/Y-1
38 00340 DEF FNC(Y)=Y^(NO+1)-Y^NO+1/Y-1
39 00350 PRINT " EXPONENT M0=",M0," EXPONENT NO=",NO," CAMMA=",CAMMA
40 00355 M1=M0+1
41 00358 N1=NO+1
42 00360 FOR I=1 TO M
43 00370 I1=I-1
44 00380 I2=I-2
45 00390 R(I)=.000001
46 00400 C=1
47 00410 D=1
48 00420 P1=P(I)*R(I)
49 00430 W1=(R(I))^(M0+FNC(P(I))+C0*R(I)^(M0+FNC(P(I))))
50 00435 W2=((R(I))^(M0-1)*FND(P(I))+C0*R(I)^(M0-1)*FNE(P(I)))^2
51 00438 W3=-((FND(P(I))+C0*FNE(P(I)))^2)/(FNC(P(I))+C0*FNG(P(I)))
52 00439 C=W2/W1+W3
53 00440 G1=C*D
54 00450 IF G1>0 THEN 00500
55 00460 IF G1<0 THEN 00570
56 00470 C=-1/C
57 00480 IF ABS(C)>.000001 THEN 00570
58 00490 D=-D
59 00500 R(I)=R(I)+C
60 00510 IF R(I)>0 .999999 THEN 00540
61 00520 IF R(I)<-.000001 THEN 00540
62 00530 GOTO 00420
63 00540 R(I)=R(I)-.9*C
64 00550 C=.1*C
65 00560 GOTO 00420
66 00570 U=-(R(I))^(NO-1)*FND(P(I))+C0*R(I)^(NO-1)*FNE(P(I))
67 00575 X1(I)=U/(FND(P(I))+C0*FNE(P(I)))
68 00580 X(I)=X1(I)/(1+X1(I))
69 00590 V=(FNC(P(I))+C0*FNG(P(I)))/(1-X(I))
70 00595 S(I)=V*(R(I)^M0+FNC(P(I))+C0*R(I)^M0+FNG(P(I)))/X(I)
71 00596 S(I)=S(I)/(1+C0*M1/M1)/M1
72 00600 IF I>1 THEN 00470
73 00610 L3(I)=1
74 00620 R0(I)=R(I)
```

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75 00630 T1(I)=R0(I)*P(I)
76 00640 L4(I)=1
77 00650 LS(I)=E(I)
78 00660 GOTO 01030
79 00670 L2(I)=(1-X(I-1))/X(I)
80 00680 IF I>2 THEN 00720
81 00690 L4(2)=X(1)+(1-X(1))/X(2)
82 00700 R0(2)=R(2)/P(1)
83 00710 GOTO 00930
84 00720 IF I>3 THEN 00740
85 00730 L4(3)=1+(1-X(1))*(1-X(2))/(X(2)*X(3))
86 00740 R0(3)=R(3)/(P(1)*P(2))
87 00750 GOTO 00930
88 00760 B=1
89 00770 L4(I)=0
90 00780 FOR J=2 TO I2
91 00790 B=B*X(I,J)
92 00800 L4(I)=L4(I)+B
93 00810 NEXT J
94 00820 L4(I)=L4(I)*(1-X(I))+1
95 00830 LO=1-X(I)
96 00840 FOR J=2 TO I1
97 00850 EO=LO/X(I,J)
98 00860 NEXT J
99 00870 EO=LO*X(I)
100 00880 L4(I)=L4(I)+EO
101 00890 R0(I)=R(I)
102 00900 FOR J=1 TO I1
103 00910 R0(I)=R0(I)/P(J)
104 00920 NEXT J
105 00930 L3(I)=L4(I)
106 00940 LS(I)=X(I)/L3(I)
107 00950 FOR J=1 TO I
108 00960 L3(J)=L3(I-1)/L2(J)
109 00970 LS(J)=LS(I-1)+X(J)/L3(J)
110 00980 NEXT J
111 00990 T1(I)=R0(I)*P(I)
112 01000 FOR J=1 TO I
113 01010 T1(J)=T1(I-1)*P(J)
114 01020 NEXT J
115 01030 T1(I+1)=1
116 01040 PRINT " "
117 01050 PRINT "I=";I
118 01060 PRINT " "
119 01070 T2(I)=R0(I)
120 01080 FOR J=2 TO I
121 01090 T2(J)=T2(I-1)
122 01100 NEXT J
123 01110 L3(I+1)=L3(I)
124 01120 X(I+1)=1-X(I)
125 01130 FOR J=1 TO I
WIDE LINE
126 01140 Z1=((T1(I+1)*M1-T1(I)*M1)*L3(I+1))/X(I+1)-(T1(I)*M1-T1(I)*M1)*L3(I)/X(I))/M1
WIDE LINE
127 01150 Z2=((T1(I+1)*M1-T1(I)*M1)*L3(I+1))/X(I+1)-(T1(I)*M1-T1(I)*M1)*L3(I)/X(I))/M1
128 01160 G(J)=Z1+C0*Z2/((1+C0*M1/M1))
129 01170 S1(J)=Q(J)/T1(I)
130 01180 PRINT " J=";J;" Q=";Q(J);"; S1=";S1(J);"; LS=";LS(J);"; T/T9=";T1(I)
131 01190 NEXT J
132 01152 Q9=(1-T1(I)*M1+C0*C0*T1(I)*M1)*L3(I)/(X(I+1)*M1)
133 01153 Q9=Q9/(1+C0*M1/M1)
134 01154 Q0=(T1(I)*M1-R0(I))*M1+C0*T1(I)*M1-C0=R0(I)*M1*L3(I)/(X(I)*M1)
135 01155 Q0=Q0/(1+C0*M1/M1)
136 01156 S0=Q0/R0(I)
137 01160 S2(I)=S0-Q9
138 01162 REM CALCULATING DATA TO GET SMIN
139 01163 D=(1-R0(I))/100
140 01164 FOR L=1 TO 101
141 01165 C(L)=R0(I)*D*(L-1)
142 01166 Y(L)=C(L)*M0+C0*M1/M1*C(L)*M0+0 S/C(L)
143 01167 NEXT L
144 01170 FOR J=1 TO I
145 01180 S2(I)=S2(I)+S1(J)
146 01190 NEXT J
147 01201 REM OBTAIN SMIN USING SIMPSON'S RULE
148 01202 H=Y(I)+Y(101)

```

```
149 01203 FOR K=2 TO 100
150 01204 IF K/2=INT(K/2) THEN 01207
151 01205 H=H+2*T(K)
152 01206 GO TO 01208
153 01207 H=H+4*T(K)
154 01208 NEXT K
155 01210 S0(I)=((D/3*H)^2)/(1+G0*N1/M1)
156 01220 S3(I)=S2(I)/S0(I)
157 01230 S9(I)=((1-R0(I)*M1+G0*R0(I)*N1)*(1/R0(I)-1)/M1)/(1+G0*N1/M1)
158 01240 S4(I)=S9(I)/S0(I)
159 01250 IF I=M THEN 01270
160 01260 P(1,I)=1/P1
161 01270 PRINT"
162 01280 PRINT"    P=";P(I);"    R=";R(I);"    X=";X(I);"    X1=";X1(I);"    S=";S(I)
163 01290 PRINT"    L2=";L2(I);"    L4=";L4(I)
164 01291 PRINT"
165 01292 PRINT" COLD WALL/HOT WALL TEMPERATURE RATIO, T0/T9=";R0(I)
166 01293 PRINT" HEAT OUT AT COLD WALL=";R0(I);" HEAT IN AT WARM WALL=";R9(I)
167 01295 PRINT" ENTROPY PRODUCTION RATE AT COLD WALL=";S0(I)
168 01297 PRINT" ENTROPY PRODUCTION RATE AT WARM WALL=";S9(I)
169 01300 PRINT" MINIMUM ENTROPY PRODUCTION RATE, S0=";S0(I)
170 01301 PRINT" ENTROPY PRODUCTION RATE FOR 1, "SHIELDS, S2=";S2(I)
171 01304 PRINT" MAXIMUM ENTROPY PRODUCTION RATE, S9=";S9(I)
172 01310 PRINT" ENTROPY PRODUCTION RATE RATIOS, S3=S2/S0 AND S4=S9/S0"
173 01320 PRINT"      S3=";S3(I);"    S4=";S4(I)
174 01330 NEXT I
175 01340 GOTO 00270
176 01350 END
177 'ECP
```

NEWRAF

This program solves the original, complete, constrained optimization equations developed in Ref. [9] without the simplifying assumption suggested there which eliminated the dimensionless parameter, $h_{fg}/C_p T_H$. Only single-term thermal conductivity functions were considered in this analysis.

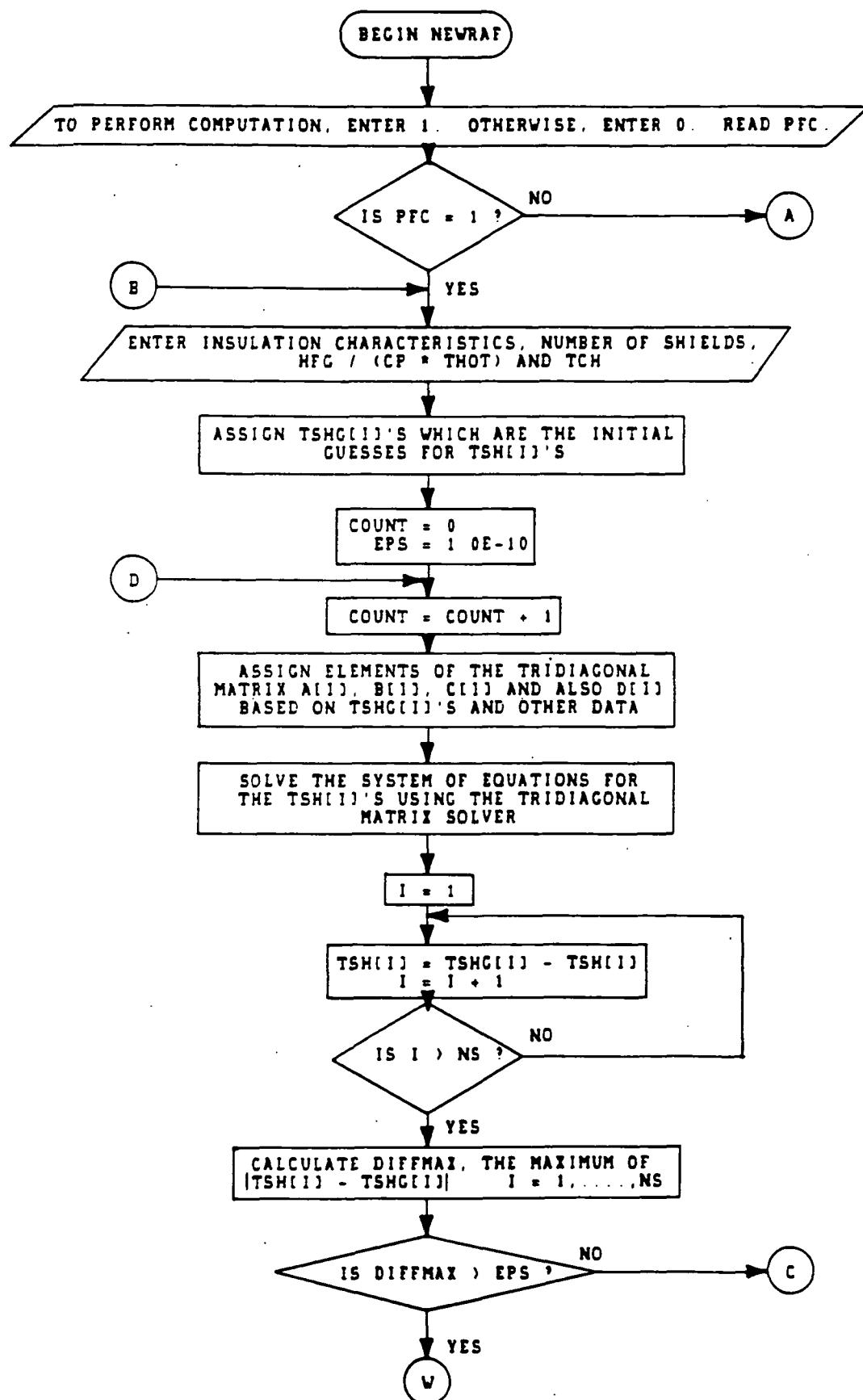
This program also recycles to the starting point. Consequently, the first input is either a 1, if a calculation is to be performed, or a 0, if no more work is to be done.

Next the program requests input of the insulation's characteristics, specifically, the exponent of temperature in the thermal conductivity function, the number of cooled shields, the dimensionless parameter $h_{fg}/C_p T_H$ for the boiloff from the insulated container, and $R = T_C/T_H$.

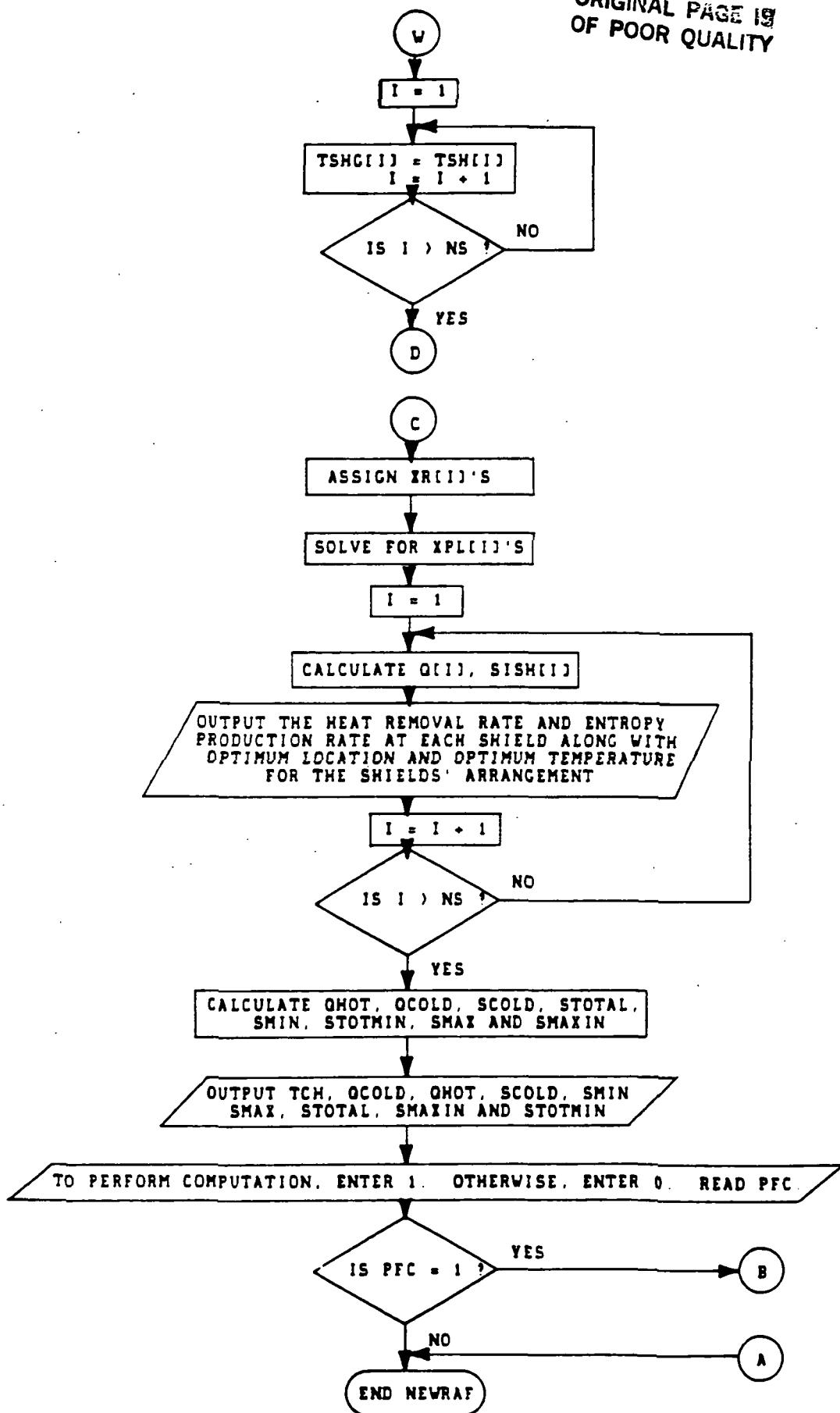
The output specifies the optimal characteristics of the given number of shields with the constraint that the cooling capacity is limited to the boil-off of the liquid due only to the heat leak through the insulation itself.

The flow chart and a program sample follows.

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PROGRAM NEVRAPH(INPUT/,OUTPUT,AKM).

(-----) NEVRAP (-----)
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 JULY 1983

(* THIS PASCAL PROGRAM WAS DEVELOPED TO OPTIMIZE THE
 LOCATION, TEMPERATURE AND HEAT DISSIPATION RATE
 OF EACH COOLED SHIELD INSIDE AN INSULATION LAYER
 THE THERMAL CONDUCTIVITY OF THE INSULATION HAS
 THE GENERAL FORM.
 $K = K_1^*(T^{**}m)$
 THE OBJECTIVE HAS BEEN TO SOLVE THE SET OF 2^*NS+1
 NON-LINEAR EQUATIONS OBTAINED BY BEJAN, A. "DIS-
 CRETE COOLING OF LOW HEAT LEAK SUPPORTS TO 4.2 K,"
 CRYOCENICS, VOL 15, 1975, PP.290-292.
 SOLUTION IS BASED ON THE NEWTON-RAPHSON TECHNIQUE
 DISCUSSED BY STOECKER, W. F., DESIGN OF THERMAL
 SYSTEMS, 2ND EDITION, SECTION 6-11, PP. 117-119,
 McGRAW-HILL BOOK CO., NY, 1980

LABEL 100.

TYPE

ARRAYS=ARRAY[[: 10] OF REAL; (* THE SIZE OF ARRAYS DETERMINES THE MAXIMUM NUMBER OF SHIELDS *)
 ARRAYP=ARRAY[[: 11] OF REAL; (* THE SIZE OF ARRAYP IS NS+1 *)
 ARRATT=ARRAY[[: 20] OF REAL; (* THE SIZE OF ARRATT SHOULD BE TWICE THE NUMBER OF SHIELDS *)

VAR

A	ARRAYS,	(* LOWER-DIAGONAL ELEMENTS OF THE TRIDIAGONAL MATRIX *)
B	ARRAYS,	(* DIAGONAL ELEMENTS OF THE TRIDIAGONAL MATRIX *)
C	ARRAYS,	(* UPPER-DIAGONAL ELEMENTS OF THE TRIDIAGONAL MATRIX *)
D	ARRAYS,	(* RIGHT-HAND SIDE OF THE SET OF EQUATIONS DURING ITERATIONS *)
O	ARRAYS,	(* I-TH DIMENSIONLESS HEAT REMOVAL RATE *)
Q	ARRAYP,	(* DIMENSIONLESS HEAT TRANSFER BETWEEN SHIELDS *)
S	ARRAYS,	(* DIMENSIONLESS ENTROPY PRODUCTION RATE FOR I-TH LAYER *)
SMAI	REAL,	(* MAXIMUM DIMENSIONLESS ENTROPY PRODUCTION RATE *)
SMIN	REAL,	(* MINIMUM DIMENSIONLESS ENTROPY PRODUCTION RATE *)
SMAXIN	REAL,	(* SMAI / SMIN *)
STOTAL	REAL,	(* TOTAL DIMENSIONLESS ENTROPY PRODUCTION RATE *)
STOTMIN	REAL,	(* STOTAL / SMIN *)
SISH	ARRAYS,	(* I-TH DIMENSIONLESS ENTROPY PRODUCTION RATE *)
TSH	ARRAYS,	(* I-TH SHIELD / HOT WALL TEMPERATURE RATIO, ALWAYS (< 1 *)
TSHC	ARRAYS,	(* GUESSED I-TH SHIELD / HOT WALL TEMPERATURE RATIO, ALWAYS (< 1 *)
WORK	ARRATT,	(* DUMMY VARIABLES *)
I	ARRAYP,	(* SPACING BETWEEN NEIGHBORING SHIELDS / INSULATION THICKNESS *)
IPL	ARRAYS,	(* DISTANCE FROM COLD WALL / INSULATION THICKNESS *)
IR	ARRAYS,	(* X[I] / X[I-1] *)
AKM	: TEXT,	(* OUTPUT FILE TO BE USED IF DESIRED *)
BETA	: REAL,	(* PARAMETER DEFINED IN PROCEDURE INPUTH *)

```

80      BOLD      : REAL.          (* DUMMY VARIABLE USED IN SOLVING THE TRIDIAGONAL MATRIX *)
81      COUNT     : INTEGER.       (* NUMBER OF ITERATIONS NEEDED TO DETERMINE TSH(I,I)'S *)
82      DELTAT0,DEN : REAL.          (* DUMMY VARIABLES *)
83      DIFF,DIFFMAX : REAL.         (* DUMMY VARIABLES USED IN CHECKING CONVERGENCE *)
84      DIV,DMAX,DMIN : REAL.        (* DUMMY VARIABLES USED IN SOLVING THE TRIDIAGONAL MATRIX *)
85      EPS       : REAL.          (* A SMALL VALUE USED TO OBSERVE IF CONVERGENCE IS OBTAINED *)
86      GI,GIM1,GIP1 : REAL.        (* DUMMY VARIABLES *)
87      GOLD      : REAL.          (* DUMMY VARIABLE USED IN SOLVING THE TRIDIAGONAL MATRIX *)
88      I,I       : INTEGER.       (* INDICES FOR LOOPS *)
89      ITERIN    : INTEGER.       (* INDEX USED TO TERMINATE ITERATIONS *)
90      M       : REAL.           (* POWER OF THE THERMAL CONDUCTIVITY EQUATION *)
91      MM1      : REAL.           (* EQUALS M-1 *)
92      MP1      : REAL.           (* EQUALS M+1 *)
93      NS       : INTEGER.       (* NUMBER OF SHIELDS *)
94      NSPI     : INTEGER.       (* EQUALS NS+1 *)
95      PFC      : INTEGER.       (* PROGRAM FLOW CONTROLLER *)
96      TCH      : REAL.           (* COLD WALL / HOT WALL TEMPERATURE RATIO, ALWAYS ( 1 ) *)
97      TI,TIMI   : REAL.           (* DUMMY VARIABLES *)
98      QCOLD    : REAL.           (* HEAT OUT AT COLD WALL *)
99      QHOT    : REAL.           (* HEAT IN AT HOT WALL *)
00      SCOLD    : REAL.           (* ENTROPY PRODUCTION RATE AT COLD WALL *)
01      ITOTAL   : REAL.           (* SUM OF TSH(I,I)'S, SHOULD EQUAL 1 AFTER SUCCESSFUL COMPUTATION *)
02
03
04
05
06 PROCEDURE INPUT();
07 BEGIN          (* INPUT OF DATA HEADING *)
08   WRITELN;
09   WRITELN;      ENTER ----) M NS BETA TCH <----);
10   WRITELN;      WHERE M ---- POWER IN THE THERMAL CONDUCTIVITY EQUATION';
11   WRITELN;      NS ---- NUMBER OF SHIELDS';
12   WRITELN;      BETA -- HFG / (CP*THOT');
13   WRITELN;      HFG --- HEAT OF VAPORIZATION [J/KG];
14   WRITELN;      CP --- SPECIFIC HEAT AT CONSTANT PRESSURE [J/KG K];
15   WRITELN;      THOT -- HOT WALL TEMPERATURE [K];
16   WRITELN;      TCH --- COLD WALL / HOT WALL TEMPERATURE RATIO, ALWAYS ( 1 );
17   WRITELN;      (* INPUT OF DATA HEADING *)
18 END;
19
20
21
22 PROCEDURE PFC();
23 BEGIN          (* PFC *)
24   WRITELN;
25   WRITELN;      TO PERFORM COMPUTATION, ENTER 1, OTHERWISE, ENTER 0 );
26   WRITELN;
27 END;          (* PFC *)
28
29
30
31
32 PROCEDURE SINGLESPACE();
33 BEGIN          (* SINGLE SPACE IN OUTPUT *)
34   WRITELN(' ');
35 END;          (* SINGLE SPACE IN OUTPUT *)
36
37
38
39 FUNCTION PWR(X,E REAL) REAL;
40 VAR
41   A      : REAL;
42 BEGIN          (* COMPUTE X**E *)
43   A :=LN(X);
44   PWR :=EXP(A);
45 END;          (* COMPUTE X**E *)
46
47
48
49 FUNCTION MAZOF2(N01,N02 REAL) REAL;
50 BEGIN          (* DETERMINES THE LARGEST OF THE TWO GIVEN NUMBERS *)
51   IF N01>N02 THEN
52     IF N01=N02 THEN
53       MAZOF2 :=N01;
54     ELSE
55       MAZOF2 :=N02;
56     ELSE
57       MAZOF2 :=N01;
58 END;          (* DETERMINES THE LARGEST OF THE TWO GIVEN NUMBERS *)
59

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```
60
61
62 FUNCTION MINOF2(N01,N02:REAL):REAL;
63 BEGIN          (* DETERMINES THE SMALLEST OF THE TWO GIVEN NUMBERS *)
64   IF N01<N02 THEN
65     IF N01>N02 THEN
66       MINOF2:=N02
67     ELSE
68       MINOF2:=N01
69     ELSE
70       MINOF2:=N01
71 END.           (* DETERMINES THE SMALLEST OF THE TWO GIVEN NUMBERS *)
72
73
74
75
76
77
78
79          (* MAIN PROGRAM BODY *)
80
81 BEGIN
82   PEGH,
83   READLN,
84   READ(PEGH),
85   WHILE PEGH=1 DO
86   BEGIN
87
88   (* THIS BLOCK IS USED TO INPUT THE INSULATION THERMAL CONDUCTIVITY, NUMBER *)
89   (* OF SHELDS, HFG/(CP*THT0) AND COLD WALL / HOT WALL TEMPERATURE RATIO *)
90
91   INPUTH
92   READLN
93   READ(M,NS,BETA,TCH);
94   SINGLESPACE,
95   WRITELN('    THERMAL CONDUCTIVITY OF THE INSULATION IS K = K1*T**M, M > 1),
96   WRITELN('      HFG / (CP*THT0) = ',BETA,' SH'),
97   SINGLESPACE,
98   SINGLESPACE.
99
100
101   MFL :=M+1 0,
102   MM1 :=M-1 0,
103
104          (* INITIAL GUESSED VALUES FOR TSHG(I)'S ARE ENTERED *)
105
106   DELTATC :=(1 0-TCH)/(NS+1 0),
107   FOR J :=1 TO NS DO TSHG(J):=J*DELTATC+TCH,
108
109          (* VARIABLE USED TO CHECK CONVERGENCE CRITERION IS SET AND THE ITERATIVE PROCEDURE *)
110          (* OF NEWTON-RAPHSON METHOD IS STARTED *)
111
112   EES :=1 0E-10,
113   COUNT :=0,
114   ITRBIN :=0,
115   REPEAT
116   COUNT :=COUNT+1,
117   FOR I :=1 TO NS DO
118   BEGIN
119     D1 :=TSHG(I),
120     IF NS>1 THEN
121       IF I>1 THEN
122         IF I>NS THEN
123           BEGIN
124             C1M1 :=TSHG(I-1),
125             C1P1 :=TSHG(I+1)
126           END
127         ELSE
128           BEGIN
129             C1M1 :=TSHG(I-1),
130             C1P1 :=I 0
131           END
132       ELSE
133         BEGIN
134           C1M1 :=TCH,
135           C1P1 :=TSHG(I+1)
136         END
137     ELSE
138       BEGIN
139         C1M1 :=TCH,
```

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41 CIP1 = 1.0
42 END.

43 (* ELEMENTS OF THE TRIDIAGONAL MATRIX ARE COMPUTED *)
44
45 A(1) = PWR(CIP1,MP1)-PWR(C1,M)*(-M*C1+MP1*(TCH-BETA));
46 B(1) = MP1*PWR(C1,MH1)*(M*GIM1*(BETA-TCH+C1),C1*(-2 0*(BETA-TCH)));
47 C(1) = B(1)+MP1*PWR(C1,MH1)*C1*(-M*(BETA-TCH)-C1*(M+2 0));
48 C(1) = MP1*PWR(CIP1,M)*((BETA-TCH+C1));
49 D(1) = GIM1*(PWR(CIP1,MP1)-PWR(C1,MP1)+BETA*MP1*PWR(C1,M)-TCH*MP1*PWR(C1,M)+MP1*PWR(C1,MP1));
50 D(1) = D(1)+C1*(PWR(C1,M)*(TCH-BETA)-BETA*MP1*PWR(C1,M)+TCH*MP1*PWR(C1,M)-MP1*PWR(C1,MP1));
51 D(1) = D(1)+CIP1*(BETA*PWR(CIP1,M)-TCH*PWR(CIP1,M));
52 END.
53 A(1) = 0.0.
54 C(NS) = 0.0.
55
56 (* THE TRIDIAGONAL MATRIX SOLVER IS SHOWN IN THIS BLOCK *)
57 (* SEE WESTLAKE, J. R., A HANDBOOK OF NUMERICAL MATRIX *)
58 (* INVERSION AND SOLUTION OF LINEAR EQUATIONS, SECTION *)
59 (* 2.7, PP. 34-35. JOHN WILEY & SONS, INC., NY, 1968 *)
60
61 IF B(1)=0.0 THEN GOTC 100.
62 BOLD = C(1)/B(1).
63 COLD = D(1)/B(1).
64 WORK(1) = COLD.
65 WORKNS(1) = BOLD.
66 DMAI = ABS(B(1)).
67 DMIN = ABS(C(1)).
68 FOR I = 1 TO NS DO
69 BEGIN
70 DIV = B(I)-A(I)*BOLD.
71 IF DIV=0.0 THEN GOTC 100.
72 DMAI = MAINT(DMAI,ABS(DIV)).
73 DMIN = MIN(DMIN,ABS(DIV)).
74 COLD = (C(I)-A(I)*COLD)/DIV.
75 WORK(I) = COLD.
76 BOLD = C(I)/DIV
77 WORKNS(I) = BOLD
78 END.
79 TSH(NS) = COLD
80 J = NS
81 FOR I = 1 TO NS DO
82 BEGIN
83 J = J-1.
84 COLD = WORK(J)-WORK(J+NS)*COLD.
85 TSH(J) = COLD
86 END.

87 (* NEWLY CALCULATED VALUES OF TSH(I)'S ARE COMPUTED *)
88
89 FOR I = 1 TO NS DO TSH(I) = TSHG(I)-TSH(I).

90 (* CONVERGENCE IS CHECKED. IF THE CRITERION IS SATISFIED, THE ITERATION IS *)
91 (* TERMINATED, OTHERWISE THE NEWLY CALCULATED TSH(I)'S ARE USED AS NEW *)
92 (* GUESSES FOR ANOTHER ROUND OF ITERATION *)
93
94 DIFFMAX = 1.0E-15.
95 FOR I = 1 TO NS DO
96 BEGIN
97 DIFF = ABS(TSH(I)-TSHG(I)),
98 DIFFMAX = MAINT(DIFF,DIFFMAX)
99 END.
100 IF DIFFMAX=EPS THEN
101 ITERIN = 1
102 ELSE
103 FOR I = 1 TO NS DO TSHG(I) = TSH(I),
104 UNTIL ITERIN=1.

105 (* IN THIS BLOCK QUANTITIES USED IN DETERMINING THE SHIELDS' SPACINGS ARE COMPUTED *)
106
107 FOR I = 1 TO NS DO
108 BEGIN
109 TI = TSH(I),
110 IF NS<1 THEN
111 IF I<1 THEN
112 IF I<NS THEN
113 TIPI = TSH(I-1)
114 ELSE
115 TIPI = TSH(I-1)
116 ELSE
117 TIPI = TSH(I-1)
118 END.

```

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20      TIM1=TCH
21      ELSE
22          TIM1=TCH;
23          IR111=(MPI*PWR(T1,M)*(T1-TIM1))/(PWR(T1,MP1)-PWR(TIM1,MP1));
24      END.
25      DEN=1.0;
26      FOR I=1 TO NS DO DEN=DEN*IR1NS-I+1)+1.0;
27      NSP1=NS+1;
28
29          (* FINALLY, SPACINGS BETWEEN SHIELDS AND OTHER QUANTITIES OF INTEREST ARE CALCULATED *)
30
31      X[1]=1.0/DEN;
32      XPL[1]=X[1];
33      ITOTAL=X[1];
34      FOR I=2 TO NSP1 DO
35          BEGIN
36              X[1]=X[1]-X[1]*X[1];
37              IF I<NSP1 THEN XPL[1]=XPL[1]*X[1];
38              ITOTAL=ITOTAL*X[1];
39          END;
40          IF (ABS(ITOTAL-1.0) > 1.0E-5) THEN GOTO 100;
41      QL111=(PWR(TSH11,MP1)-PWR(TCH,MP1))/(X[1]*MP1);
42      QLNNSP11=(1.0-PWR(TSHNS,MP1))/(X[NSP1]*MP1);
43      FOR I=2 TO NS DO QL111=(PWR(TSH11,MP1)-PWR(TSH11-1,MP1))/(X[I]*MP1);
44      SINGLESPACE;
45      WRITEIN:   NUMBER OF SHIELDS    = ',NS 2),
46      WRITEIN:   NUMBER OF ITERATIONS = ',COUNT 2);
47      SINGLESPACE;
48      SINGLESPACE;
49      WRITEIN:           HEAT REMOVAL      ENTROPY PRODUCTION      OPTIMUM      OPTIMUM();
50      WRITEIN:           RATE             RATE                LOCATION     TEMPERATURE();
51      WRITEIN:           -----          -----               -----       -----
52      SINGLESPACE;
53      FOR I=1 TO NS DO
54          BEGIN
55              Q111=Q111+1-Q111;
56              SISH11=Q111/TSH11;
57              WRITEIN:   SHIELD ',I,2,'  = $,000.0 5.1' ',SISH11 9.5,' ',9,XPL11 9.5,' ',5,TSH11 9.5)
58          END;
59      SINGLESPACE;
60      SINGLESPACE;
61      QHOT=QL(NSP1);
62      QCOLD=Q111;
63      SCOLD=QCOLD/TCH;
64      STOTAL=SCOLD-QHOT;
65      FOR J=1 TO NS DO STOTAL=STOTAL+SISH(J);
66      IF MDOO 0 THEN
67          SMIN=SQR((1.0-PWR(TCH,(M/2.0)))/(M/2.0))
68      ELSE
69          SMIN=SQR(IN(1.0/TCH));
70      STOTHIN=STOTAL/SMIN;
71      SMAX=(1.0-PWR(TCH,MP1))*(1.0/TCH-1.0)/MP1;
72      SMAIN=SMAX/SMIN;
73      SINGLESPACE;
74      WRITEIN:   COLD WALL / HOT WALL TEMPERATURE RATIO      = ',TCH 14.6),
75      WRITEIN:   HEAT OUT AT COLD WALL                      = ',QCOLD 14.6),
76      WRITEIN:   HEAT IN AT HOT WALL                       = ',QHOT 14.6),
77      WRITEIN:   ENTROPY PRODUCTION RATE AT COLD WALL      = ',SCOLD 14.6),
78      WRITEIN:   ENTROPY PRODUCTION RATE AT HOT WALL        = ',QHOT 14.6),
79      WRITEIN:   MINIMUM ENTROPY PRODUCTION RATE          = ',SHIN 14.6),
80      WRITEIN:   MAXIMUM ENTROPY PRODUCTION RATE          = ',SMAX 14.6),
81      WRITEIN:   TOTAL ENTROPY PROD. RATE WITH ',NS 2,' SHIELDS = ',STOTAL 14.6),
82      WRITEIN:   MAXIMUM / MINIMUM ENTROPY PRODUCTION RATIO = ',SMAIN 14.6),
83      WRITEIN:   TOTAL / MINIMUM ENTROPY PRODUCTION RATIO   = ',STOTHIN 14.6);
84      100 SINGLESPACE;
85      IF (DIV=0 0) OR (B[1]=0 0) THEN
86          BEGIN
87              SINGLESPACE;
88              WRITEIN:   ---) CHECK THE ASSEMBLY OF COEFFICIENTS TO BE USED IN TRIDIAGONAL MATRIX  (---),
89              WRITEIN:   ---) CHECK THE TRIDIAGONAL MATRIX SOLVER (---)
90          END;
91      IF (ABS(ITOTAL-1.0) > 1.0E-5) THEN
92          BEGIN
93              SINGLESPACE;
94              WRITEIN:   ---) ITOTAL IS NOT EQUAL TO 1.0  (---);
95              WRITEIN:   ---) COMPUTATIONS ARE NOT CORRECT (---)
96          END;
97      SINGLESPACE;
98      SINGLESPACE;
99

```

00 PFCH.
01 READLN.
02 READ(PFC)
03 END
04 END
05 /EOP.

CONTINUE FROM PAGE
OF EXISTING PAGE

TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.

? 1

ENTER ----> M NS BETA TCH -----

WHERE: M ----- POWER IN THE THERMAL CONDUCTIVITY EQUATION
 NS ---- NUMBER OF SHIELDS
 BETA -- HFG / (CP*THOT)
 HFG --- HEAT OF VAPORIZATION [J/KG]
 CP --- SPECIFIC HEAT AT CONSTANT PRESSURE [J/KG K]
 THOT -- HOT WALL TEMPERATURE [K]
 TCH --- COLD WALL / HOT WALL TEMPERATURE RATIO, ALWAYS = 1

? 1.0 3 0.0145 0.001

THERMAL CONDUCTIVITY OF THE INSULATION IS K = K1*T**1.0
 HFG / (CP*THOT) = 0.01450

NUMBER OF SHIELDS = 3
 NUMBER OF ITERATIONS = 9

	HEAT REMOVAL RATE	ENTROPY PRODUCTION RATE	OPTIMUM LOCATION	OPTIMUM TEMPERATURE
SHIELD 1	0.10438	1.56143	0.09719	0.06685
SHIELD 2	0.25983	1.12595	0.28870	0.23076
SHIELD 3	0.47781	0.89782	0.58568	0.53219

COLD WALL / HOT WALL TEMPERATURE RATIO	=	0.001000
HEAT OUT AT COLD WALL	=	0.022985
HEAT IN AT HOT WALL	=	0.864998
ENTROPY PRODUCTION RATE AT COLD WALL	=	22.984544
ENTROPY PRODUCTION RATE AT HOT WALL	=	-0.864998
MINIMUM ENTROFY PRODUCTION RATE	=	3.751018
MAXIMUM ENTROPY PRODUCTION RATE	=	499.499501
TOTAL ENTROPY PROD. RATE WITH 3 SHIELDS	=	25.704743
MAXIMUM / MINIMUM ENTROPY PRODUCTION RATIO	=	133.163725
TOTAL / MINIMUM ENTROFY PRODUCTION RATIO	=	6.852738

TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.

? 1

ENTER ----> M NS BETA TCH -----

WHERE: M ----- POWER IN THE THERMAL CONDUCTIVITY EQUATION
 NS ---- NUMBER OF SHIELDS
 BETA -- HFG / (CP*THOT)
 HFG --- HEAT OF VAPORIZATION [J/KG]
 CP --- SPECIFIC HEAT AT CONSTANT PRESSURE [J/KG K]
 THOT -- HOT WALL TEMPERATURE [K]
 TCH --- COLD WALL / HOT WALL TEMPERATURE RATIO, ALWAYS = 1

? 1.0 2 0.0154 0.000806

THERMAL CONDUCTIVITY OF THE INSULATION IS K = K1*T**1.0
HFG / (CP*THOT) = 0.01540

NUMBER OF SHIELDS = 2
NUMBER OF ITERATIONS = 8

	HEAT REMOVAL RATE	ENTROPY PRODUCTION RATE	OPTIMUM LOCATION	OPTIMUM TEMPERATURE
SHIELD 1	0.19732	1.97595	0.16252	0.09986
SHIELD 2	0.59037	1.48999	0.48495	0.39623

COLD WALL / HOT WALL TEMPERATURE RATIO = 0.000806
HEAT OUT AT COLD WALL = 0.030677
HEAT IN AT HOT WALL = 0.818366
ENTROPY PRODUCTION RATE AT COLD WALL = 38.061092
ENTROPY PRODUCTION RATE AT HOT WALL = -0.818366
MINIMUM ENTROPY PRODUCTION RATE = 3.776103
MAXIMUM ENTROPY PRODUCTION RATE = 619.846992
TOTAL ENTROPY PROD. RATE WITH 2 SHIELDS = 40.708665
MAXIMUM / MINIMUM ENTROPY PRODUCTION RATIO = 164.149921
TOTAL / MINIMUM ENTROPY PRODUCTION RATIO = 10.780603

TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.

? 0
0.072 CP SECs, 11471B CM USED.

/BYE:

3KMUFTC COSTS: 255.028 SRUS AT \$.0059 = \$1.50

DESINS

This program optimizes the characteristics of a single cooled shield with different insulations on the two sides. Only one-term thermal conductivity functions are considered.

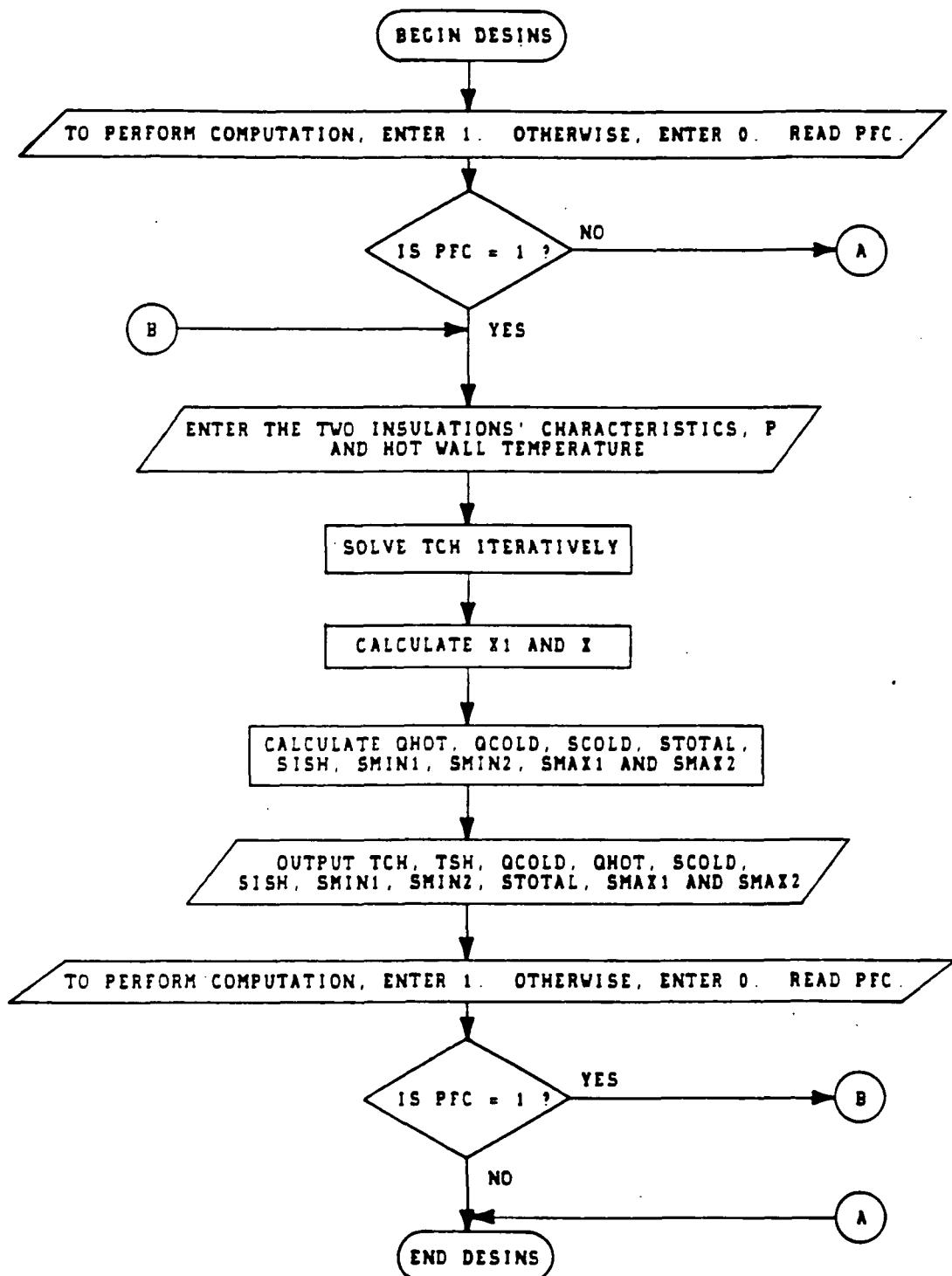
This program also recycles to the starting point; thus the first input is 1, if a calculation is to be performed, or 0 if no more work is to be done.

Next inputs are the characteristics of the two insulations, specifically, the exponents of temperature in the thermal conductivity functions on the hot and cold sides of the shield, a coefficient ratio ALFA (defined in the program), the shield to cold wall temperature ratio, $P = T_S/T_C$, and the hot wall temperature, T_H .

The output specifies the optimal characteristics of the cooled shield as well as other, related information.

The flow diagram and a program sample follows.

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PROGRAM DIFFCOND(INPUT/,OUTPUT,SEN);

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----- DESINS -----

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JULY 1983

THIS PASCAL PROGRAM WAS DEVELOPED TO OPTIMIZE THE
LOCATION, TEMPERATURE AND HEAT DISSIPATION RATE
FOR A COOLED SHIELD IN A CRYOGENIC INSULATION
SYSTEM WHOSE THERMAL CONDUCTIVITY HAS THE FORM.

$K = K_1 \cdot (T^{m_1})$ ON THE HOT SIDE.
 $K = K_2 \cdot (T^{m_2})$ ON THE COLD SIDE

THE METHOD IS BASED ON THE MINIMIZATION OF THE
ENTROPY PRODUCTION RATE WHICH IS PROPORTINAL TO
THE HEAT LEAK ACROSS THE INSULATION.

LABEL 100.
LABEL 200.
LABEL 300.

VAR

P REAL. (* SHIELD / COLD WALL TEMPERATURE RATIO, ALWAYS < 1 *)
SMA1 REAL. (* MAXIMUM ENTROPY PRODUCTION RATE BASED ON $K_1 \cdot T^{m_1}$ *)
SMA12 REAL. (* MAXIMUM ENTROPY PRODUCTION RATE BASED ON $K_2 \cdot T^{m_2}$ *)
SMIN1 REAL. (* MINIMUM ENTROPY PRODUCTION RATE BASED ON $K_1 \cdot T^{m_1}$ *)
SMIN2 REAL. (* MINIMUM ENTROPY PRODUCTION RATE BASED ON $K_2 \cdot T^{m_2}$ *)
STOTAL REAL. (* TOTAL DIMENSIONLESS ENTROPY PRODUCTION RATE *)
S1SH REAL. (* DIMENSIONLESS ENTROPY PRODUCTION RATE AT SHIELD *)
TCH REAL. (* COLD WALL / HOT WALL TEMPERATURE RATIO, ALWAYS < 1 *)
TSH REAL. (* SHIELD / HOT WALL TEMPERATURE RATIO, ALWAYS < 1 *)
I REAL. (* DISTANCE FROM COLD WALL / THICKNESS RATIO *)
II REAL. (* $I / (1.0 - I)$ *)

CC REAL. (* DUMMY VARIABLE *)
COUNT INTEGER. (* NUMBER OF ITERATIONS NEEDED TO DETERMINE TCH *)
DD REAL. (* DUMMY VARIABLE *)
ALFA REAL. (* $[K_2 \cdot (N+1)] / [K_1 \cdot (N+1)]$ *)
C_G1 REAL. (* DUMMY VARIABLES *)
IND INTEGER. (* INDEX TO TERMINATE THE SEARCH FOR TCH *)
M REAL. (* POWER OF THE THERMAL CONDUCTIVITY ON HOT SIDE *)
MP1 REAL. (* EQUALS N+1 *)
N REAL. (* POWER OF THE THERMAL CONDUCTIVITY ON COLD SIDE *)
NP1 REAL. (* EQUALS N+1 *)
PFC INTEGER. (* PROGRAM FLOW CONTROLLER *)
OCOLD REAL. (* HEAT OUT AT COLD WALL *)
QHOT REAL. (* HEAT IN AT HOT WALL *)
SCOLD REAL. (* ENTROPY PRODUCTION RATE AT COLD WALL *)
SEN TEXT. (* OUTPUT FILE TO BE USED IF DESIRED *)
THOT REAL. (* HOT WALL TEMPERATURE [K] *)

```

80
81
82 PROCEDURE INPUTH;
83   BEGIN          (* INPUT OF DATA HEADING *)
84     WRITELN;
85     WRITELN('    ENTER ----) M N ALFA P THOT (----)');
86     WRITELN('    WHERE: M ----- POWER OF THE THERMAL CONDUCTIVITY EQUATION ON THE HOT SIDE');
87     WRITELN('          R ----- POWER OF THE THERMAL CONDUCTIVITY EQUATION ON THE COLD SIDE');
88     WRITELN('          ALFA -- [K2^(M+1)]/[K1^(M+1)]');
89     WRITELN('          P ----- SHIELD / COLD WALL TEMPERATURE RATIO, ALWAYS > 1');
90     WRITELN('          THOT -- HOT WALL TEMPERATURE (K)');
91     WRITELN('    ');
92     WRITELN('END.          (* INPUT OF DATA HEADING *)');
93
94
95
96
97 PROCEDURE PFCN;
98   BEGIN          (* PFCN *)
99     WRITELN;
100    WRITELN('    TO PERFORM COMPUTATION, ENTER 1 OTHERWISE, ENTER 0 ');
101    WRITELN;
102    END.          (* PFCN *)
103
104
105
106 PROCEDURE SINGLESPACE;
107   BEGIN          (* SINGLE SPACE IN OUTPUT *)
108     WRITELN('  ');
109   END.          (* SINGLE SPACE IN OUTPUT *)
110
111
112
113 FUNCTION PWR(X,E REAL): REAL;
114   VAR
115     A           REAL;
116   BEGIN          (* COMPUTE X**E *)
117     A=E*LN(X);
118     PWR=E*PA;
119   END.          (* COMPUTE X**E *)
120
121
122
123 FUNCTION D(E,XI REAL): REAL;
124   BEGIN          (* FUNCTIONAL D *)
125     D=(E+1.0)*PWR(XI,E)-E/(PWR(XI,(1.0-E)))-(1.0/SQR(XI));
126   END.          (* FUNCTIONAL D *)
127
128
129
130 FUNCTION F(E,XI REAL): REAL;
131   BEGIN          (* FUNCTIONAL F *)
132     F=(PWR(XI,(E+1.0))-PWR(XI,E)-1.0*(1.0/XI));
133   END.          (* FUNCTIONAL F *)
134
135
136
137
138
139
140
141   (* MAIN PROGRAM BODY *)
142
143 BEGIN
144   PFCN;
145   READLN;
146   READ(PFC);
147   WHILE PFC=1 DO
148   BEGIN
149
150     (* THIS BLOCK IS USED TO INPUT THE TWO INSULATION THERMAL CONDUCTIVITIES. *)
151     (* SHIELD / COLD WALL TEMPERATURE RATIO AND HOT WALL TEMPERATURE *)
152
153     INPUTH;
154     READLN;
155     READ(M,N,ALFA,P,THOT);
156     SINGLESPACE;
157     WRITELN('    THERMAL CONDUCTIVITY OF THE INSULATION ON THE HOT SIDE IS K = K1^(T0**M+1.0)');
158     WRITELN('    THERMAL CONDUCTIVITY OF THE INSULATION ON THE COLD SIDE IS K = K2^(T0**N+1.0)');
159     WRITELN('          [K2^(M+1)]/[K1^(M+1)] = ',ALFA,9.2);

```

160

```
161  WRITELN(''
162  SINGLESPACE,
163  SINGLESPACE,
```

HOT WALL TEMPERATURE = ',THOT,1,' [K])

82

164

```
165  MP1:=M+1.0;
166  MP1:=M+1.0;
167  TCH :=0.000001;
168  CC :=0.1;
169  DD :=1.0;
170  COUNT :=0;
```

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171

(* THIS BLOCK CALCULATES TCH ITERATIVELY *)

173

```
174  REPEAT
175    TSH :=P*TCH;
176    G :=D(N,P)*D(N,P)/E(N,P)-PWR(TCH,(1.0-N))*D(M,TSH)*D(M,TSH)/E(M,TSH)/ALFA;
177    G1 :=G*DD;
178    IF G1<0.0 THEN GOTO 100;
179    IF G1>0.0 THEN GOTO 200;
180    CC :=(-0.1)*CC;
181    IF ABS(CC)<0.000001 THEN GOTO 200;
182    DD :=-DD;
183    100 TCH :=TCH+CC;
184    IF (TCH>0.99999) OR (TCH<0.00001) THEN
185      BEGIN
186        TCH :=TCH-0.9*CC;
187        CC :=0.1*CC;
188        IF ABS(CC)<0.000001 THEN IND :=1;
189      END;
190    COUNT :=COUNT+1;
191  UNTIL (G1=0.0) OR (ABS(CC)<0.000001) OR (IND=1);
192
```

193

IF IND=1 THEN

195

```
BEGIN
196  SINGLESPACE;
197  SINGLESPACE;
198  SINGLESPACE;
```

199

```
200  WRITELN(''          ---) OPTIMUM CRITERION CANNOT BE SATISFIED      ('' ''),
201  WRITELN(''          ---) USE SINGLE INSULATION WITH THE LOWER CONDUCTIVITY ('' '');
202  GOTO 300
203 END
```

204

(* OTHER QUANTITIES OF INTEREST ARE COMPUTED IN THIS SECTION *)

205

```
206  X :=-ALFA*PWR(TCH,(N-1.0))*D(N,P)/D(M,TSH),
207  I :=X/(1.0+X);
208  QHOT :=(1.0-PWR(TSH,MP1))/((1.0-I)*MP1);
209  QCOLD :=ALFA*PWR(TCH,MP1)*(PWR(P,MP1)-1.0)/(PWR(THOT,(M-N))*I*MP1),
210  SCOLD :=QCOLD/TCH;
211  STOTAL :=(F(M,TSH)*(1.0-I)+ALFA*PWR(TCH,N)*E(N,P)/I)/MP1;
212  SISH :=QHOT-QCOLD/TSH;
213  IF M=0.0 THEN
214    SMIN1 :=SQR(LN(1.0/TCH));
215  ELSE
216    SMIN1 :=SQR((1.0-PWR(TCH,(M/2.0)))/(M/2.0));
217  IF N=0.0 THEN
218    SMIN2 :=SQR(LN(1.0/TCH));
219  ELSE
220    SMIN2 :=SQR((1.0-PWR(TCH,(N/2.0)))/(N/2.0));
221  SMAX1 :=F(M,TCH)/MP1;
222  SMAIZ :=F(N,TCH)/MP1;
```

223

SINGLESPACE,

226

```
227  WRITELN(''          NUMBER OF ITERATIONS           = ',COUNT,0);
228  WRITELN(''          COLD WALL / HOT WALL TEMPERATURE RATIO   = ',TCH,14,6);
229  WRITELN(''          SHIELD / HOT WALL TEMPERATURE RATIO     = ',TSH,14,6);
230  WRITELN(''          SHIELD LOCATION                   = ',I,14,6);
231  WRITELN(''          HEAT OUT AT SHIELD                  = ',QHOT-QCOLD,14,6);
232  WRITELN(''          HEAT OUT AT COLD WALL                = ',QCOLD,14,6);
233  WRITELN(''          HEAT IN AT HOT WALL                 = ',QHOT,14,6);
234  WRITELN(''          ENTROPY PRODUCTION RATE AT COLD WALL = ',SCOLD,14,6);
235  WRITELN(''          ENTROPY PRODUCTION RATE AT HOT WALL  = ',-QHOT,14,6);
236  WRITELN(''          ENTROPY PRODUCTION RATE AT SHIELD   = ',SISH,14,6);
237  WRITELN(''          MINIMUM ENTROPY PRODUCTION RATE BASED ON K1*T**N = ',SMIN1,14,6);
238  WRITELN(''          MINIMUM ENTROPY PRODUCTION RATE BASED ON K2*T**N = ',SMAIZ,14,6);
239  WRITELN(''          TOTAL ENTROPY PRODUCTION RATE             = ',STOTAL,14,6);
240  WRITELN(''          ENTROPY PROD. W/O SHIELD BASED ON K1*T**N = ',SMAIZ,14,6);
```

240 WRITEIN('ENTROPY PROD W/O SHIELD BASED ON X2:T0:N',
241 300 SINGLESPACE,
242 SINGLESPACE,
243 SINGLESPACE,
244 PFCH,
245 READIN,
246 READ(PFC)
247 END
248

83

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TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.

? 1

ENTER ----> M N ALFA P THOT <----

WHERE: M ----- POWER OF THE THERMAL CONDUCTIVITY EQUATION ON THE HOT SIDE
N ----- POWER OF THE THERMAL CONDUCTIVITY EQUATION ON THE COLD SIDE
ALFA -- $[K2^{(M+1)}]/[K1^{(N+1)}]$
P ----- SHIELD / COLD WALL TEMPERATURE RATIO, ALWAYS > 1
THOT -- HOT WALL TEMPERATURE [K]

? 1.0 0.0 20.0 4.5 300.0

THERMAL CONDUCTIVITY OF THE INSULATION ON THE HOT SIDE IS K = $K1^{(T**1.0)}$.
THERMAL CONDUCTIVITY OF THE INSULATION ON THE COLD SIDE IS K = $K2^{(T**0.0)}$.
 $[K2^{(M+1)}]/[K1^{(N+1)}] = 20.00$
HOT WALL TEMPERATURE = 300.00 [K]

NUMBER OF ITERATIONS	=	36
COLD WALL / HOT WALL TEMPERATURE RATIO	=	0.001666
SHIELD / HOT WALL TEMPERATURE RATIO	=	0.007497
SHIELD LOCATION	=	0.390755
HEAT OUT AT SHIELD	=	0.820144
HEAT OUT AT COLD WALL	=	0.000497
HEAT IN AT HOT WALL	=	0.820641
ENTROPY PRODUCTION RATE AT COLD WALL	=	0.298568
ENTROPY PRODUCTION RATE AT HOT WALL	=	-0.820641
ENTROPY PRODUCTION RATE AT SHIELD	=	109.396253
MINIMUM ENTROPY PRODUCTION RATE BASED ON $K1*T**M$	=	3.680131
MINIMUM ENTROPY PRODUCTION RATE BASED ON $K2*T**N$	=	40.925828
TOTAL ENTROFY PRODUCTION RATE	=	178.307751
ENTROPY PROD. W/O SHIELD BASED ON $K1*T**M$	=	299.619216
ENTROPY PROD. W/O SHIELD BASED ON $K2*T**N$	=	598.241762

TO PERFORM COMPUTATION, ENTER 1. OTHERWISE, ENTER 0.

? 0

0.044 CF SECs, 10233B CM USED.

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		6. Performing Organization Code	
7. Author(s) J.C.Chato, J.M.Khadadadi and J.Seyed-Yagoobi		8. Performing Organization Report No. UILU ENG-84-4004	
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9. Performing Organization Name and Address Department of Mechanical and Industrial Enrineering University of Illinois at Urbana-Champaign Urbana, IL 61801		11. Contract or Grant No. NAG2-219	
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15. Supplementary Notes Point of Contact: Technical Monitor, Peter Kittel, MS 244-7 Ames Research Center, Moffett Field, CA 94035 (415) 965-6525 or FTS 448-6525			
16. Abstract <p>A relatively simple method has been developed to optimize the location, temperature, and heat dissipation rate of each cooled shield inside an insulation layer. The method is based on the minimization of the entropy production rate which is proportional to the heat leak across the insulation. The results show that the maximum number of shields to be used in most practical applications is three. However, cooled shields are useful only at low values of the overall, cold wall to hot wall absolute temperature ratio. The performance of the insulation system is relatively insensitive to deviations from the optimum values of the temperature and location of the cooling shields.</p> <p>Design curves are presented for rapid estimates of the locations and temperatures of cooling shields in various types of insulations, and an equation is given for calculating the cooling loads for the shields.</p>			
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